



FT83A-B7129

Service Engineer's Manual



PREFACE

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FCC Declaration



Notice for the USA

Compliance Information Statement (Declaration of Conformity Procedure) DoC FCC Part 15: This device complies with part 15 of the FCC Rules.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following conditions:

- This device may not cause harmful interference.
- This device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

Notice for Canada

This Class A digital apparatus complies with Canadian ICES-003. Cet appareil numérique de la Classe A est conforme à la norme NMB-003 du Canada.

• Notice for Europe (CE Mark)



This product is in conformity with the Council Directive 2014/30/EU and 2014/35/EU.

Warning

This equipment is compliant with Class A of CISPR 32. In a residential environment this equipment may cause radio interference.

This equipment is not suitable for use in locations where children are likely to be present.

CAUTION

Lithium battery included with this board. Do not puncture, mutilate, or dispose of battery in fire. There will be danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type recommended by manufacturer. Dispose of used battery according to manufacturer instructions and in accordance with your local regulations.

The elements of the instructional safeguard shall be as follows:



- element 1a: IEC 60417-6056 (2011-05) for moving fan blades or
IEC 60417-6057 (2011-05) for other moving parts
- element 2: "Moving parts" or "Moving fan blade" as applicable, or equivalent text
- element 3: optional
- element 4: Keep body parts away from moving parts" or "Keep body parts away from fan blades" or "Keep body parts out of the motion path" as applicable, or equivalent text

• VCCI-A

この装置は、クラスA情報技術装置です。この装置を家庭環境で使用すると電波妨害を引き起こすことがあります。この場合には使用者が適切な対策を講ずるよう要求されることがあります。 VCCI-A

• Safety: IEC/EN 62368-1

This equipment is compliant with CB/LVD of Safety: IEC/EN 62368-1:2014.

警告使用者：

此為甲類資訊技術設備，於居住環境中使用時，可能會造成射頻擾動，在此種情況下，使用者會被要求採取某些適當的對策。

警告：為避免電磁干擾，本產品不應安裝或使用於住宅環境。

警告：如果更換錯誤電池會產生爆炸，請以相同或同型電池更換使用。

連絡方式

製造商：神雲科技股份有限公司

地址：桃園市龜山區文化二路 200 號



注意：內部沒有使用可維修的元件
請交由合格的技術人員進行維修



維修前需切斷所有電源

Taiwan BSMI RoHS Declaration

設備名稱：伺服器 / 型號（型式）：FT83A-B7129

Equipment Name: Server / Type: FT83A-B7129

單位 Unit	限用物質及其化學符號 Restricted substances and its chemical symbols					
	鉛 Lead (Pb)	汞 Mercury (Hg)	鎘 Cadmium (Cd)	六價鉻 Hexavalent Chromium (Cr ⁶⁺)	多溴聯苯 Polybrominated biphenyls (PBB)	多溴二苯醚 Polybrominated diphenyl ethers (PBDE)
印刷電路板總成 Printed Circuit Board Assembly	-	○	○	○	○	○
機械組件 Mechanical Assemblies	-	○	○	○	○	○
風扇 Fans	-	○	○	○	○	○
散熱器 Heatsink	○	○	○	○	○	○
電源線 Power Cord	○	○	○	○	○	○
電源供應器 Power Supply	-	○	○	○	○	○

備考1. “○”係指該項限用物質之百分比含量未超出百分比含量基準值。

Note1. “○” indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.

備考2. “-”係指該項限用物質為排除項目。

Note2. “-” indicates that the restricted substance corresponds to the exemption.

About this Manual

This Manual is intended for trained service technician/personnel with hardware knowledge of personal computers. It is aimed to provide you with instructions on installing your TYAN FT83A-B7129.

How this guide is organized

This guide contains the following parts:

Chapter 1: Overview

This chapter give an introduction to the FT83A-B7129 barebones, standard parts list, and accessories. Describes the external components, gives a table of key

Chapter2: Setting Up

This chapter Covers procedures on installing the CPU, memory modules, add on card and hard drives. Give an overview about the FT83A-B7129 barebone from an overall angle.

Chapter 3: Replacing the Pre-installed Components

This chapter covers the removal and replacement procedures for pre-installed components.

Chapter 4: Motherboard Information

This chapter lists the hardware setup procedures that you need to abide by when installing system components. It includes description of the jumpers and connectors on the motherboard.

Chapter5: BIOS Setup

This chapter tells how to change system settings through the BIOS setup menu. Detailed descriptions of the BIOS parameters are also provided.

Chapter 6: Diagnostics

This chapter introduces some BIOS codes and technical terms to provide better service for the customers.

Appendix:

This Chapter Describes the Fan and Temp sensors location; list the cable connection and FRU part tables for reference of system setup and technical support in case a problem arises with your system.

Safety and Compliance Information

Before installing and using TYAN FT83A-B7129, take note of the following precautions:

- Read all instructions carefully.
- Do not place the unit on an unstable surface, cart, or stand.
- Do not block the slots and opening on the unit, which are provided for ventilation.
- Only use the power source indicated on the marking label. If you are not sure, contact the power company.
- The unit uses a three-wire ground cable, which is equipped with a third pin to ground the unit and prevent electric shock. Do not defeat the purpose of this pin. If your outlet does not support this kind of plug, contact your electrician to replace your obsolete outlet.
- Do not place anything on the power cord. Place the power cord where it will not be in the way of foot traffic.
- Follow all warnings and cautions in this manual and on the unit case.
- Do not push objects in the ventilation slots as they may touch high voltage components and result in shock and damage to the components.
- When replacing parts, ensure that you use parts specified by the manufacturer.
- When service or repairs have been done, perform routine safety checks to verify that the system is operating correctly.
- Avoid using the system near water, in direct sunlight, or near a heating device.
- Cover the unit when not in use.

Safety Information

Retain and follow all product safety and operating instructions provided with your equipment. In the event of a conflict between the instructions in this guide and the instructions in equipment documentation, follow the guidelines in the equipment documentation.

Observe all warnings on the product and in the operating instructions. To reduce the risk of bodily injury, electric shock, fire and damage to the equipment, observe all precautions included in this guide.

You must become familiar with the safety information in this guide before you install, operate, or service TYAN products.

Symbols on Equipment

	Caution. This symbol indicates a potential hazard. The potential for injury exists if cautions are not observed. Consult equipment documentation for specific details.
	Caution. Slide-mounted equipment is not to be used as a shelf or a work space.
	Warning. This symbol indicates the presence of hazardous energy circuits or electric shock hazards. Refer all servicing to qualified personnel.
	Warning. This symbol indicates the presence of a hot surface or hot component. If this surface is contacted, the potential for injury exists. To reduce risk of injury from a hot component, allow the surface to cool before touching.
	CAUTION: Risk of Explosion if Battery is replaced by an Incorrect Type. Dispose of Used Batteries According to the Instructions. ATTENTION: Risque d'explosion si la batterie est remplacée par un type incorrect. Mettre au rebut les batteries usagées selon les instructions.
	Multiple power connections. Prior to servicing, disconnect all power cords. Raccordements de puissance multiples. Avant l'entretien, vous devez débranchez tous les cordons d'alimentation.

General Precautions

- Follow all caution and warning instructions marked on the equipment and explained in the accompanying equipment documentation.

Machine Room Environment

- Make sure that the area in which you install the system is properly ventilated and climate-controlled.
- Ensure that the voltage and frequency of your power source match the voltage and frequency inscribed on the electrical rating label of the equipment.
- Do not install the system in or near a plenum, air duct, radiator, or heat register.
- Never use the product in a wet location.

Equipment Chassis

- Do not block or cover the openings to the system.
- Never push objects of any kind through openings in the equipment. Dangerous voltages might be present.
- Conductive foreign objects can produce a short circuit and cause fire, electric shock, or damage to your equipment.
- Lift equipment using both hands and with your knees bent.

Equipment Racks

To avoid injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual materials handling.
- Do not attempt to move a rack by yourself; a minimum of two people are needed to move a rack.
- Do not attempt to move a fully loaded rack. Remove equipment from the rack before moving it.
- Do not attempt to move a rack on an incline that is greater than 10 degrees from the horizontal.

- Make sure the rack is properly secured to the floor or ceiling.
- Make sure the stabilizing feet are attached to the rack if it is a single-rack installation.
- Make sure racks are coupled together if it is a multiple-rack installation.
- Make sure the rack is level and stable before installing an appliance in the rack.
- Make sure the leveling jacks are extended to the floor.
- Make sure the full weight of the rack rests on the leveling jacks.
- Always load the rack from the bottom up. Load the heaviest component in the rack first.
- Make sure the rack is level and stable before pulling a component out of the rack.
- Make sure only one component is extended at a time. A rack might become unstable if more than one component is extended.

To avoid damage to the equipment:

- The rack width and depth must allow for proper serviceability and cable management.
- Ensure that there is adequate airflow in the rack. Improper installation or restricted airflow can damage the equipment.
- The rack cannot have solid or restricted airflow doors. You must use a mesh door on the front and back of the rack or remove the doors to ensure adequate air flow to the system.
- If you install the Model in a rack, do not place equipment on top of the unit. It will cause restricted airflow and might cause damage to the equipment.
- Make sure the product is properly matted with the rails. Products that are improperly matted with the rails might be unstable.
- Verify that the AC power supply branch circuit that provides power to the rack is not overloaded. This will reduce the risk of personal injury, fire, or damage to the equipment. The total rack load should not exceed 80 percent of the branch circuit rating. Consult the electrical authority having jurisdiction over your facility wiring and installation requirements.

Equipment Power Cords

- Use only the power cords and power supply units provided with your system. The system might have one or more power cords.
- Plug the power cord into a grounded (earthed) electrical outlet that is easily accessible at all times.
- In all European electrical environments, you must ground the Green/Yellow tab on the power cord. If you do not ground the Green/Yellow tab, it can cause an electrical shock due to high leakage currents.
- Do not place objects on AC power cords or cables. Arrange them so that no one might accidentally step on or trip over them.
- Do not pull on a cord or cable. When unplugging from the electrical outlet, grasp the cord by the plug.
- To reduce the risk of electrical shock, disconnect all power cords before servicing the appliance.

Equipment Batteries

- The system battery contains lithium manganese dioxide. If the battery pack is not handled properly, there is risk of fire and burns.
- Do not disassemble, crush, puncture, short external contacts, or dispose of the battery in fire or water.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- The system battery is not replaceable. If the battery is replaced by an incorrect type, there is danger of explosion. Replace the battery only with a spare designated for your product.
- Do not attempt to recharge the battery.
- Dispose of used batteries according to the instructions of the manufacturer. Do not dispose of batteries with the general household waste. To forward them to recycling or proper disposal, use the public collection system or return them to TYAN, your authorized TYAN partner, or their agents.

Equipment Modifications

- Do not make mechanical modifications to the system. TYAN is not responsible for the regulatory compliance of TYAN equipment that has been modified.

Equipment Repairs and Servicing

- The installation of internal options and routine maintenance and service of this product should be performed by trained service technicians/personnel who are knowledgeable about the procedures, precautions, and hazards associated with equipment containing hazardous energy levels.
- Do not exceed the level of repair specified in the procedures in the product documentation. Improper repairs can create a safety hazard.
- Allow the product to cool before removing covers and touching internal components.
- Remove all watches, rings, or loose jewelry when working before removing covers and touching internal components.
- Do not use conductive tools that could bridge live parts.
- Use gloves when you remove or replace system components; they can become hot to the touch.
- If the product sustains damage requiring service, disconnect the product from the AC electrical outlet and refer servicing to an authorized service provider. Examples of damage requiring service include:
 - The power cord, extension cord, or plug has been damaged.
 - Liquid has been spilled on the product or an object has fallen into the product.
 - The product has been exposed to rain or water.
 - The product has been dropped or damaged.
 - The product does not operate normally when you follow the operating instructions.

Instructional safeguard requirement

An instructional safeguard shall be provided to reduced the likelihood of unintentional contact with a moving part in accordance with Clause F.5 except that element 3 is optional.

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Chapter 1: Overview

1.1 About the TYAN FT83A-B7129

Congratulations on your purchase of the TYAN® FT83A-B7129, a highly optimized rack-mountable 4U barebone system. FT83A-B7129 is designed to support dual Intel® Xeon® Scalable Processor Families and up to 2,048GB RDIMM, 4,096GB LRDIMM 3DS, providing a rich feature set and incredible performance. Leveraging advanced technology from Intel®, FT83A-B7129 server system is capable of offering scalable 32 and 64-bit computing, high-bandwidth memory design, and lightning-fast PCIE bus implementation. FT83A-B7129 not only empowers your company in today's demanding IT environment but also offers a smooth path for future application usage.

TYAN® also offers the FT83A-B7129 in a version that can support up to twelve (12) 2.5"/3.5" hot-swap SAS/SATA HDDs and (2) hot-swap 2.5" SATA HDD, (8) hot-swap 2.5" NVMe HDD. FT83A-B7129 uses rack-mountable 4U chassis featuring a robust structure and a solid mechanical enclosure. All of this provides FT83A-B7129 the power and flexibility to meet the needs of nearly any server application.



1.2 Product Models

The system board within the Tyan Barebone is defined by the following models:

- **B7129F83AV8E4HR-N:** Intel-based platform
- **B7129F83AV14E8HR-N:** Intel-based platform

1.3 Features

B7129F83AV8E4HR-N Specifications

System	Form Factor	4U Rackmount
	Chassis Model	FT83
	Chassis Dimension (D x W x H)	32.68" x 17.26" x 6.9" (830 x 438.4 x 176mm)
	Motherboard Name	S7129GMRE#
	Motherboard Notification	# The motherboard not sold separately
	Gross Weight	46 kg (101.4 lbs)
Front Panel	Net weight	39.3 kg (86.6 lbs)
	Buttons	(1) UID / (1) PWR w/ LED / (1) RST
	LEDs	(1) HDD / (1) ID / (1) System Event / (2) LAN activity
External Drive Bay	I/O Ports	(2) USB 3.0 ports / (1) COM Port / (1) VGA port
	Q'ty / Type	(12) 3.5"/2.5" Hot-Swap HDD/SSDs w/ (4) NVMe
	HDD Backplane Support	(12) SATA 6Gb/s with (4) NVMe ports
System Cooling Configuration	Supported HDD Interface	SAS 12Gb/s /SATA 6Gb/s /NVMe
	FAN	(8) hot-swappable 8cm fans
Power Supply	Type	CRPS
	Input Range	AC 100-127V/13A / AC 200-240V/9.5A
	Frequency	50-60 Hz
	Output Watts	3,000 Watts (100-127Vac input) / 4,800 Watts (200-240Vac input)
	Efficiency	80 plus Platinum
Processor	Redundancy	3+1
	Q'ty / Socket Type	(2) LGA4189
	Supported CPU Series	3rd Gen Intel Xeon Scalable Processor
	Thermal Design Power Wattage	Max up to 270W (TDP)
	System Bus	Up to 11.2/10.4 GT/s with Intel UltraPath Interconnect (UPI) support
Chipset	PCH	Intel C621A
	Switch IC	(2) PLX PEX88096
CPU-GPU Link Topology	Dual-root	All GPU connected to CPUs evenly

Memory	Supported DIMM Qty	(16)+(16) DIMM slots
	DIMM Type / Speed	DDR4 ECC RDIMM/RDIMM 3DS/LRDIMM/LRDIMM 3DS 3200
	Capacity	Up to 4,096GB RDIMM/ 8,192GB LRDIMM/ 8,192GB RDIMM 3DS/LRDIMM 3DS *Follow latest Intel DDR4 Memory POR
	Memory channel	8 Channels per CPU, 2 DIMM slots per Channel
Expansion Slots	Memory voltage	1.2V
	PCI-E	(3) PCIe Gen.4 x16 slots (FH/HL) / (10) PCIe Gen.4 x16 (FH/10.5" L/DW)
	Pre-installed TYAN Riser Card (PCI-E Gen.4)	(2) M7129F83A-L16 riser card for (2) PCIe Gen.4 x16 slots (left)
	Others	(1) PCIe Gen.4 x16 OCP 3.0 slot for mezz. w/ pull tab
LAN	Physical Dimension Abbreviation	FH/FL (Full-height / Full-length): 4.4" x 12.3" (111.2 x 312mm)
	Q'ty / Port	(1) GbE dedicated for IPMI
Storage SATA	PHY	Realtek RTL8211E
	Connector	(3) SFF-8643 for (12) front SATA ports
	Controller	Intel C621A
	Speed	6Gb/s
Storage NVMe	RAID	RAID 0/1/10/5 (Intel RSTe)
	Connector(U.2)	(2) SFF-8654 for (4) NVMe ports
	Connector (M.2)	(1) 2280 (by PCIe 3.0 x4) M.2 slot on MB / (1) 2280 (by PCIe 4.0 x2) M.2 slot on PCIe I/O board
	Connector type	D-Sub 15-pin
Graphic	Resolution	Up to 1920x1200
	Chipset	Aspeed AST2600
	USB	(2) USB3.0 ports (@ front) / (2) USB3.0 ports (@ rear) (from M7129F83A-RIO)
I/O Ports	COM	(1) DB-9 COM port
	VGA	(1) D-Sub 15-pin port
	RJ-45	(1) GbE port dedicated for IPMI (from M7129F83A-RIO)
TPM (Optional)	TPM Support	Please refer to our TPM supported list.
System Monitoring	Chipset	Aspeed AST2600
	Temperature	Monitors temperature for CPU & memory & system environment

Server Management	Voltage	Monitors voltage for CPU, memory, chipset & power supply
	LED	Over temperature warning indicator, Fan & PSU fail LED indicator
	Others	Watchdog timer support
	Onboard Chipset	Onboard Aspeed AST2600
	AST2600 iKVM Feature	24-bit high quality video compression / Supports storage over IP and remote platform-flash / USB 2.0 virtual hub
BIOS	AST2600 IPMI Feature	IPMI 2.0 compliant baseboard management controller (BMC) / 10/100/1000 Mb/s MAC interface
	Brand / ROM size	AMI, 32MB
BIOS	Feature	Hardware Monitor / Boot from USB device/PXE via LAN/Storage / Console Redirection / User Configurable FAN PWM Duty Cycle / SMBIOS 3.0/PnP/Wake on LAN / ACPI 6.1 / ACPI sleeping states S4,S5
	Operating System	Please refer to our AVL support lists.
Regulation	FCC (SDoC)	Class A
	CE (DoC)	Class A
	CB/LVD	Yes
	VCCI	Class A
	C-Tick	Class A
Operating Environment	Operating Temp.	10° C ~ 35° C (50° F ~ 95° F)
	Non-operating Temp.	- 40° C ~ 70° C (-40° F ~ 158° F)
	In/Non-operating Humidity	90%, non-condensing at 35° C
	Note	Please refer to the TYAN NVIDIA Compatibility List for the operating temperature while GPGPU deployed
	RoHS	Yes
Package Contains	Barebone	(1) FT83A-B7129 Barebone
	Manual	(1) Quick Installation Guide

B7129F83AV14E8HR-N Specifications

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	Q'ty / Type	(2) 2.5" Hot-Swap HDD/SSDs / (8) NVMe / (12) 3.5" Hot-Swap HDD/SSDs
	Front Drive Bay Interface	(2) SATA 6Gb/s / (8) NVMe / (12) SATA 6Gb/s / SAS 12Gb/s
System Cooling Configuration	Front HDD Backplane Support	NVMe / SATA 6Gb/s
	FAN	(8) hot-swappable 8cm fans
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	Input Range	AC 100-127V/13A / AC 200-240V/9.5A
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Expansion Slots	DIMM Type / Speed	DDR4 ECC RDIMM/RDIMM 3DS/LRDIMM/LRDIMM 3DS 3200
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	Memory channel	8 Channels per CPU, 2 DIMM slots per Channel
	Memory voltage	1.2V
	PCI-E	(1) PCIe Gen.4 x16 slot (FH/HL) / (10) PCIe Gen.4 x16 (FH/10.5" L/DW)
	Pre-installed TYAN Riser Card (PCI-E Gen.3)	(2) M7129F83A-L16 riser card for (2) PCI-E Gen4 x16 slot (left)
	Pre-installed TYAN Mezz. Card (PCI-E Gen.3)	F7129F83A-RIO
	Others	(1) PCIe Gen.4 x16 OCP 3.0 slot for mezz. w/ pull tab
	Physical Dimension Abbreviation	FH/FL (Full-height, Full-length): 4.4" x 12.3" (111.2 x 312mm)
	Q'ty / Port	(1) GbE dedicated for IPMI
LAN	PHY	Realtek RTL8211E
	Connector	(3) SFF-8643 for (12) front SATA drives
	Controller	Intel C621A
	Speed	6Gb/s
Storage SATA	RAID	RAID 0/1/10/5 (Intel RSTe)
	RAID	RAID 0/1 (Intel RSTe)
Storage sSATA	Connector (M.2)	(1) 2280 (by PCIe 3.0 x4) M.2 slot on MB / (1) 2280 (by PCIe 4.0 x2) M.2 slot on PCIe I/O board
	Connector (U.2)	(2) SFF-8654 for (4) NVMe ports
Graphic	Connector type	D-Sub 15-pin
	Resolution	Up to 1920x1200
	Chipset	Aspeed AST2600
	USB	(2) USB3.0 ports (@ front) / (2) USB3.0 ports (@ rear)
I/O Ports	COM	(1) DB-9 COM port
	VGA	(1) D-Sub 15-pin port
	RJ-45	(1) GbE port dedicated for IPMI
TPM (Optional)	TPM Support	Please refer to our TPM supported list.
System Monitoring	Chipset	Aspeed AST2600
	Temperature	Monitors temperature for CPU & memory & system environment
	Voltage	Monitors voltage for CPU, memory, chipset &

Server Management	power supply
	LED Over temperature warning indicator, Fan & PSU fail LED indicator
	Others Watchdog timer support
	Onboard Chipset Onboard Aspeed AST2600
BIOS	AST2600 iKVM Feature 24-bit high quality video compression / Supports storage over IP and remote platform-flash / USB 2.0 virtual hub
	AST2600 IPMI Feature IPMI 2.0 compliant baseboard management controller (BMC) / 10/100/1000 Mb/s MAC interface
Operating System	Brand / ROM size AMI, 32MB
	Feature Hardware Monitor / Boot from USB device/PXE via LAN/Storage / Console Redirection / User Configurable FAN PWM Duty Cycle / SMBIOS 3.0/PnP/Wake on LAN / ACPI 6.1 / ACPI sleeping states S4,S5
Regulation	OS supported list Please refer to our AVL support lists.
Regulation	FCC (SDoC) Class A
	CE (DoC) Class A
	CB/LVD Yes
	VCCI Class A
	C-Tick Class A
Operating Environment	Operating Temp. 10° C ~ 35° C (50° F~ 95° F)
	Non-operating Temp. - 40° C ~ 70° C (-40° F ~ 158° F)
	In/Non-operating Humidity 90 90%, non-condensing at 35° C
RoHS	RoHS 6/6 Compliant Yes
Package Contains	Barebone (1) FT83A-B7129 Barebone
	Manual (1) Quick Installation Guide

NOTE:

1. The specifications are subject to change without prior notice.
2. Please visit our website for the latest specifications.

1.4 Standard Parts List

This section describes FT83A-B7129 package contents and accessories. Open the box carefully and ensure that all components are present and undamaged. The product should arrive packaged as illustrated below.

1.4.1 Box Contents

FT83A-B7129 Chassis Kit

- 4U chassis*1
- (3+1) 4,800W (80+ Platinum) power Supply
- (8) hot-swap 8038 Fans
- (1) TYAN® S7129GMRE Mother Board
- (1) M1718T65-FPB Front Panel Board
- (1) M1717T65-USB Front USB Board
- (2) M7129F83A-L16
- (1) M7129F83A-FB Fan Board
- (1) M7129F83A-IO PCIE board
- (1) M7129F83A-RIO Rear IO board
- (1) M1297T65-BP12E-12 (B7129F83AV8E4HR-2T-N sku)
- (1) M1315F83A-BP12E-10 (B7129F83AV14E8HR-2T-N sku)

1.4.2 Accessories

If any items are missing or appear damaged, contact your retailer or browse to TYAN®'s website for service: <http://www.tyan.com>.

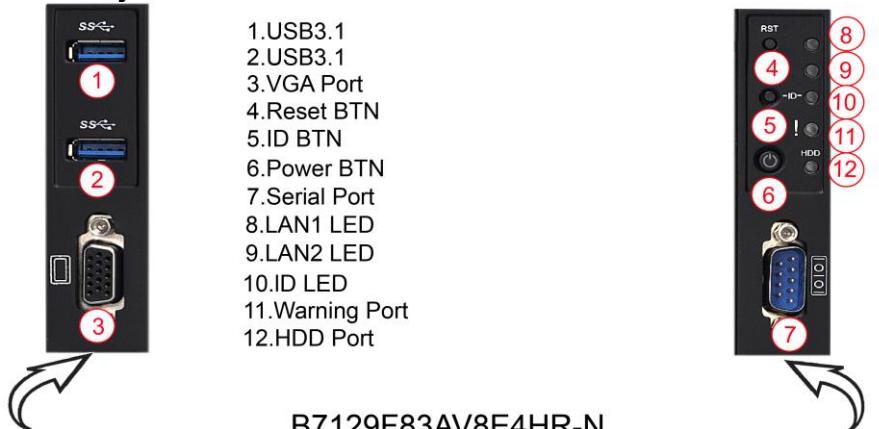
FT83A-B7129 Accessory Kit

- (2) CPU Heatsink
- (1) Rail Kit
- (2) Screw pack (PCI_E BKT)
- (2) Screw pack (M.2)
- (1) Quick Installation Guide
- (4) AC Power code (US)
- (4) AC Power code (EU)
- (1) Air duct
- (10) 200 mm,2*4P(M),P4.2/ 2*4P(M) Power Cable
- (10) 250mm,2*4P(M), P4.2/2*3P+2*1P(M)*2pcs, GPU Power Cable

1.5 About the Product

The following views show you the product.

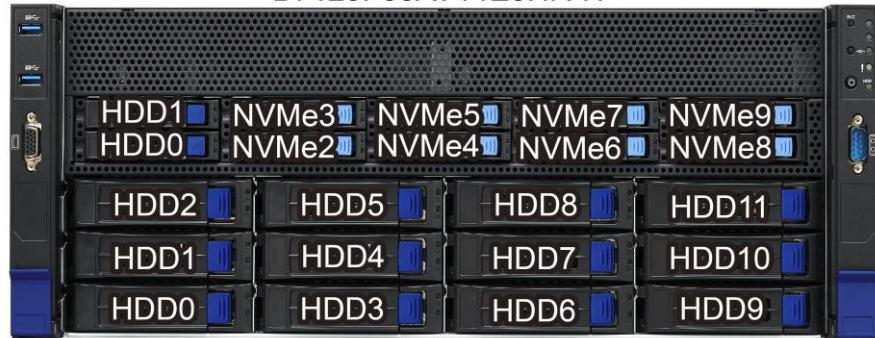
1.5.1 System Front View



B7129F83AV8E4HR-N



B7129F83AV14E8HR-N



M1718T65-FPB Front Panel LED Control Board

Switch and LED Indication

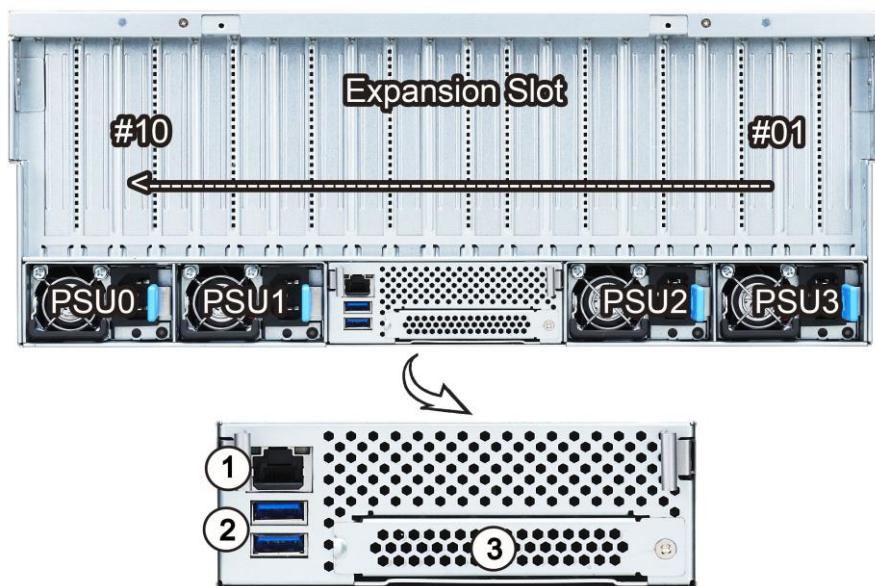
Field	QTY	Color	Behavior
Power	1	Green	System Power off / off System Power On / solid on
Onboard LAN	2		NO Function
ID	1	Blue	Normal / Off Located / Solid on
Warning	1	Red/Green/Blue	System normal /All off Memory warning / Green blinking PSU warning / Blue solid on FAN warning / Blue blinking System fault / Red solid on
Onboard HDD LED	1	Green/Red	HDD present / Green solid on HDD activity / Green blinking HDD fail / Red solid on



Status LED(Red)
Active LED(Green)

DRIVE STATE	Active LED (Green)	Status LED (Red)
Drive Present, No Active	Solid on	Off
Drive Present with Active	Blinking	Off
Drive Failure	Don't care	Solid on
RAID Rebuild	Don't care	Blinking @4 Hz
Drive Locate Identifier	Don't care	Blinking @1 Hz

1.5.2 System Rear View



1. LAN1: from Realtek RTL8211E PHY for IPMI
2. USB 3.1 x 2
3. OCP Card Area (OCP 3.0 LAN mezzanine slot)

NOTE:

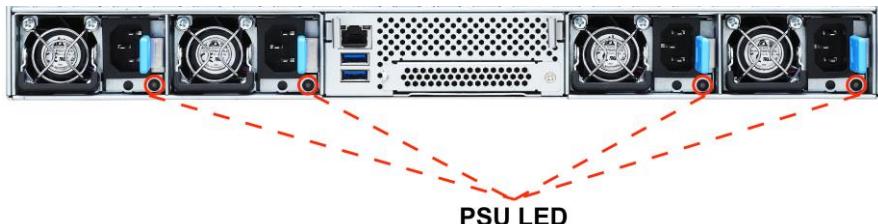
1. M7129F83A-RIO Rear IO board is pre-installed.

1.5.3 LED Definitions

1Gbps LAN Port LAN Indication

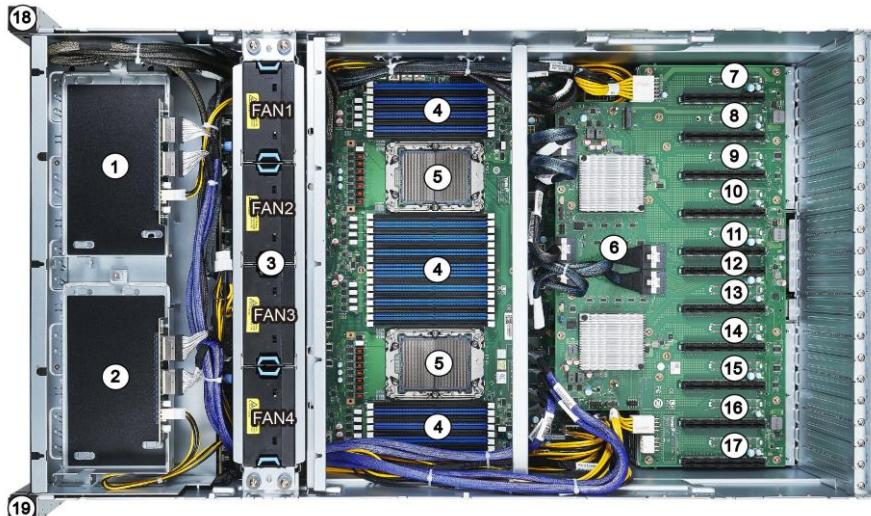
1Gbps LAN Link/Activity LED Scheme			
		Left LED (Link/Activity) LED Color: Green	Right LED (Speed) LED Color: Amber
No Link		OFF	OFF
10 Mbps	Link	Green Solid On	OFF
	Active	Green Blinking	OFF
100 Mbps	Link	Green Solid On	Green Solid On
	Active	Green Blinking	Green Solid On
1000 Mbps (1Gbps)	Link	Green Solid On	Amber Solid On
	Active	Green Blinking	Amber Solid On

NOTE: "Left" and "Right" are viewed from the rear panel.



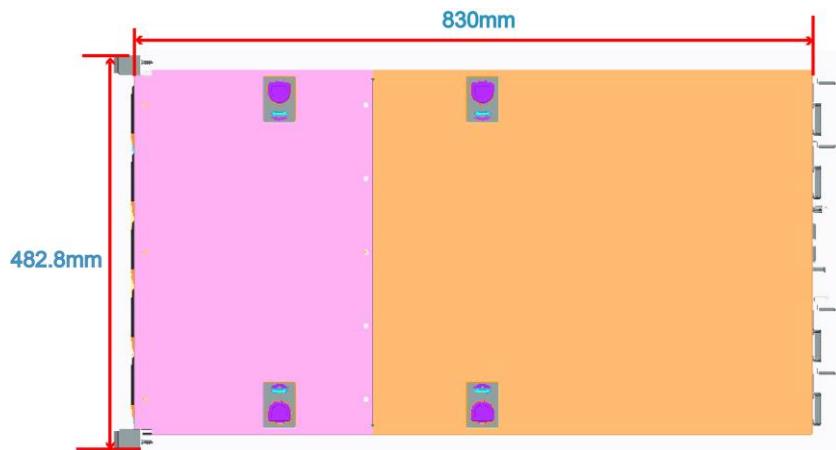
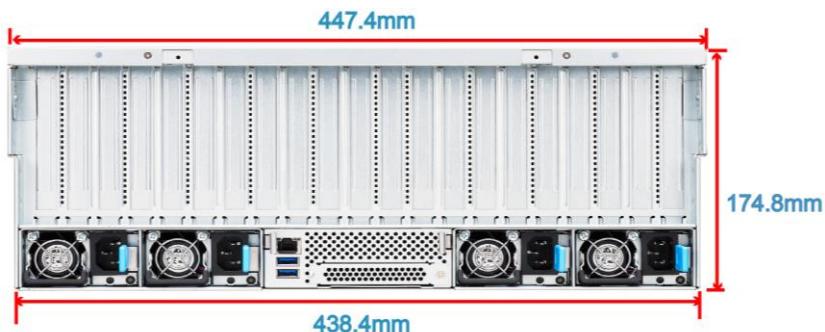
PSU LED Definitions	Dual-color	
Power Supply Condition	Green LED	Amber LED
No AC power to all power supplies	OFF	OFF
Power supply critical event causing a shutdown failure, OCP, OVP, Fan Fail, OTP, UVP	OFF	AMBER
Power supply warning events where the power supply continues to operate; high temp(inlet temperature>54 deg (PMBus reading), or hot spot temperature>105deg (PMBus reading), high power, high current, slow fan(<1200rpm).	OFF	0.5Hz Blink AMBER
AC present Only 12VSB on(PS off) or PS in Smart Redundant state	1Hz Blink GREEN	OFF
Output ON and OK	ON	OFF
AC cord unplugged or AC power lost, with a second power supply in parallel still with AC input power.	OFF	AMBER
FW update mode	2Hz Blink GREEN	OFF

1.5.4 Internal View



NO.	Explanation
1.	Riser Bracket1 with M7129F83A-L16 (10) U.2 NVMe or (2) SATA (MAX.) + (8) U.2 NVMe w/M1315F83A-BP12E-10 HDD BP Board (pre-installed) (12) 3.5" HDDs/SSDs (HDD0 ~ HDD11) w/M1297T65-BP12E-12 HDD BP Board (pre-installed) or M1313F83A-BP12E-12 HDD BP Board (pre-installed)
2	Riser Bracket2 with M7129F83A-L16 (10) U.2 NVMe or (2) SATA (MAX.) + (8) U.2 NVMe w/M1315F83A-BP12E-10 HDD BP Board (pre-installed) (12) 3.5" HDDs/SSDs (HDD0 ~ HDD11) w/M1297T65-BP12E-12 HDD BP Board (pre-installed) or M1313F83A-BP12E-12 HDD BP Board (pre-installed)
3	System Fan with M7129F83A-Fan Board(pre-installed)
4	Memory Slot
5	CPU Socket
6	M7129FT83A-IO PCIE Board
7~11	PCIE Gen4 x16 Slots (FH/FL, GPU#1 ~ GPU#5)
12	PCIE Gen4 x16 Slots (FH/FL)
13~17	PCIE Gen4 x16 Slots (FH/FL, GPU#6 ~ GPU#10)

1.5.5 Chassis Dimensions



Chapter 2: Setting Up

2.0.1 Before you Begin

This chapter explains how to install the CPUs, CPU heatsinks, memory modules, and hard drives. Instructions on inserting add on cards are also given.

2.0.2 Work Area

Make sure you have a stable, clean working environment. Dust and dirt can get into components and cause malfunctions. Use containers to keep small components separated. Putting all small components in separate containers prevents them from becoming lost. Adequate lighting and proper tools can prevent you from accidentally damaging the internal components.

2.0.3 Tools

The following procedures require only a few tools, including the following:

- A cross head (Phillips) screwdriver
- A grounding strap or an anti-static pad

Most of the electrical and mechanical connections can be disconnected using your fingers. It is recommended that you do not use needle nosed pliers to remove connectors as these can damage the soft metal or plastic parts of the connectors.

Caution!



1. To avoid damaging the motherboard and associated components, do not use torque force greater than **7kgf/cm (6.09 lb/in)** on each mounting screw for motherboard installation.
2. Do not apply power to the board if it has been damaged.

2.0.4 Precautions

Components and electronic circuit boards can be damaged by discharges of static electricity. Working on a system that is connected to a power supply can be extremely dangerous. Follow the guidelines below to avoid damage to FT83A-B7129 or injury to yourself.

- Ground yourself properly before removing the top cover of the system. Unplug the power from the power supply and then touch a safely grounded object to release static charge (i.e. power supply case). If available, wear a grounded wrist strap. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
-
- Avoid touching motherboard components, IC chips, connectors, memory modules, and leads.
- The motherboard is pre-installed in the system. When removing the motherboard, always place it on a grounded anti-static surface until you are ready to reinstall it.
- Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Do not flex or stress circuit boards.
- Leave all components inside the static-proof packaging that they ship with until they are ready for installation.
- After replacing optional devices, make sure all screws, springs, or other small parts are in place and are not left loose inside the case. Metallic parts or metal flakes can cause electrical shorts.

2.1 Installing Motherboard Components

This section describes how to install components on to the motherboard, including CPUs, memory modules and Add-on cards.

2.1.1 Removing the Chassis Cover

Follow these instructions to remove FT83A-B7129 chassis cover.

1. Remove the screw from the back side of the cover.



2. Press the two latch to pull the back cover in the direction of the arrow to remove the top cover.



3. Remove the screw from the front top cover.



4. Press the button to remove the back top cover from the chassis.



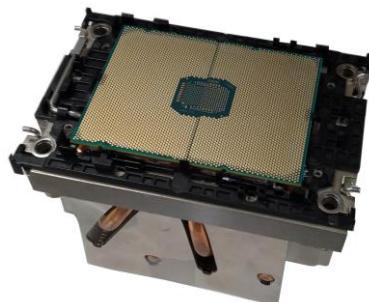
2.1.2 Installing the CPU, Heat sink and Air Duct

Follow the steps below on installing the processor, heatsink and air duct.

1. Align the triangle edge of the carrier with the notch on the edge of the heatsink. Then install the carrier on the bottom of the heatsink and make sure the latches are snapped under the edge of the heatsink.



2. Align and install the processor on the carrier. Make sure the gold arrow is located in the correct direction.



3. Remove the CPU cover.

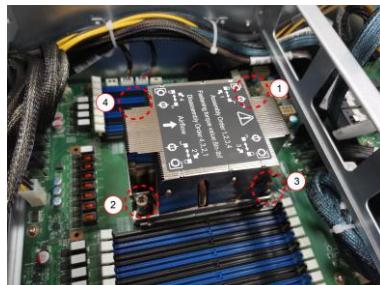


4. Carefully flip the heatsink assembly. Align the heatsink with the CPU socket by the guide pins. Make sure also that the triangle edge of the carrier is aligned correctly with the triangle mark on the CPU socket. Then place the heatsink assembly onto the top of the CPU socket.



5. Press down on the retention clips to fix the heatsink assembly to the CPU socket.
6. To secure the heatsink assembly, use a T30 Security Torx to tighten the screws in a sequential order (1→2→3→4).

NOTE: When disassembling the heatsink, loosen the screws in reverse order (4→3→2→1).



7. Repeat the procedures described earlier to install the second processor and heatsink.
8. Place the air duct on top of the heatsink and screw it to the chassis.



2.1.3 Installing the Memory

Follow these instructions to install the memory modules onto the motherboard.

1. Press the memory slot locking levers in the direction of the arrows as shown in the following illustration.



2. Align the memory module with the slot. When inserted properly, the memory slot locking levers lock automatically onto the indentations at the ends of the module.

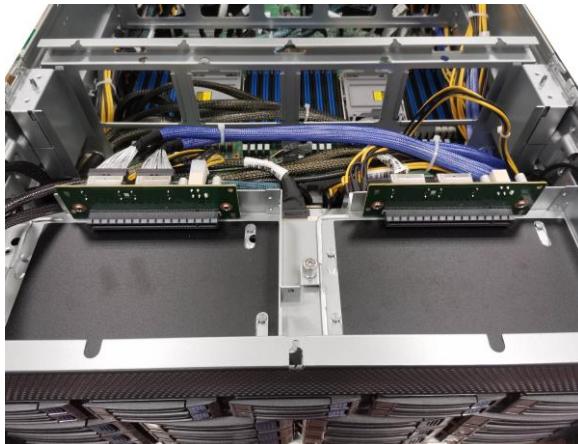


2.1.4 Installing the Expansion Card (PCIE Board)

Follow these instructions to install the PCIE cards.

Installing Expansion Cards

1. Locate the PCIE Bracket.



2. Insert the riser card to the PCIE x16 slot. Secure the card to the bracket with a screw.



Installing GPU Card

Follow the instructions to install the expansion cards with card brackets or card guides.

1. Unscrew to remove the Linkbar.

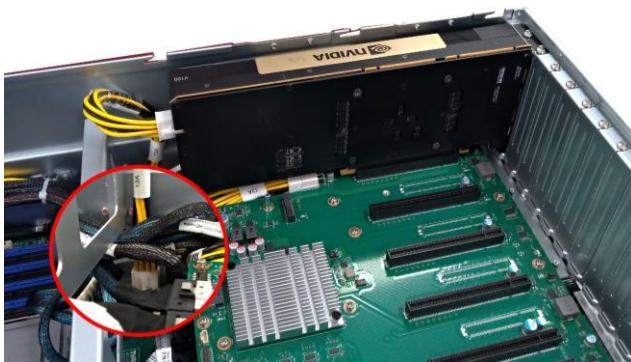


2. Locate the PCIE Gen.4 x16 slot on the motherboard. Unscrew to take out the dummy brackets.

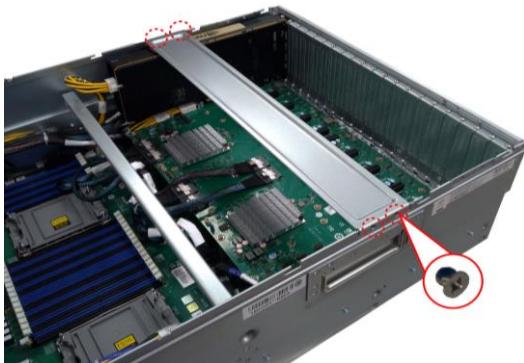




3. Insert the GPU card into the PCIE Gen. 4 slot and screw the GPU card to the chassis. Connect the GPU PWR cable to the GPU card and motherboard.



4. Secure the GPU Bracket to the chassis with 4 screws.



2.1.5 Installing Hard Drives

The FT83A-B7129 supports ten 2.5" Hard Drives and twelve 3.5"/2.5" Hard Drives. Follow these instructions to install a hard drive.

Installing 3.5"/2.5" HDD

1. Press Locking lever to release the 3.5" HDD tray.



2. Pull the 3.5" HDD tray out of the chassis.



3. Pull open the locking lever to install the 3.5" hard disk drive into the HDD tray and lock the tray lever to secure HDD.





4. Reinsert the HDD tray into the chassis.



Installing 2.5" HDD

Follow these instructions to install a 2.5" HDD/SSD.

Warning!!! Always install the hard disk drive to the chassis after the chassis has been secured on the rack.

1. Press the locking lever latch and pull the locking lever open.



2. Slide the HDD tray out.

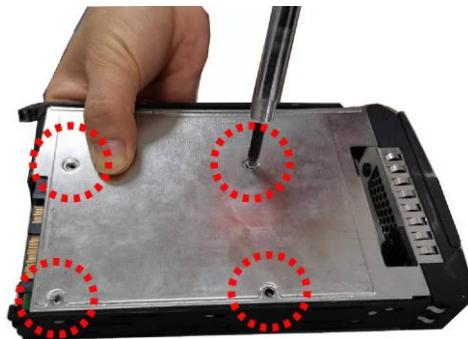


3. Place the 2.5" HDD/SSD into the HDD tray and align the 2.5" HDD/SSD with its hole.





4. Turn over the HDD tray and secure the HDD/SSD to the tray using 4 screws.



5. Reinsert the HDD tray into the chassis. Push to secure the locking lever until it clicks into place.



Follow these instructions to install a 2.5" HDD/SSD.

1. Press the locking lever latch and pull the locking lever open.



2. Slide the HDD tray out.



3. Open the lock to place the 2.5" hard disk drive into the HDD tray. Push the HDD to the left.



4. Lock the tray lever to secure HDD.



5. Reinsert the HDD tray into the chassis. Push to secure the locking lever until it clicks into place.



2.2 Rack Mounting

After installing the necessary components, the TYAN TS83A-B7129 chassis can be mounted in a rack using the supplied rack mounting kit.

Sliding Rail Kit

- Sliding Rails x 2
- Rail screw Pack x 2

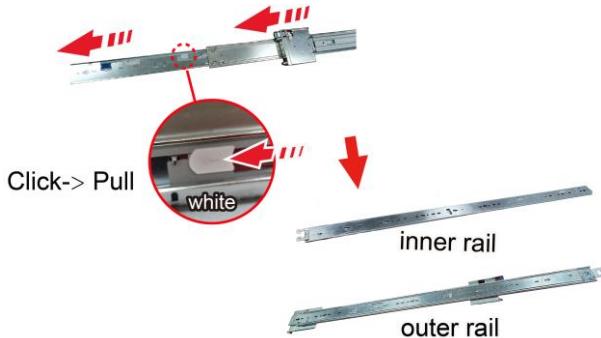
2.2.1 Installing the Server in a Rack

Follow these instructions to mount the TYAN TS83A-B7129 into an industry standard 19" rack.

NOTE: Before mounting the TYAN TS83A-B7129 chassis in a rack, ensure that all internal components have been installed and that the unit has been fully tested. However, to make the installation easier, we suggest that you remove all HDD trays before you insert the chassis into the rack.

Remove the Inner Rail

1. Pull tab forward and take out inner rail.



2. Push (a) and slide middle rail back.



Install the Inner rail onto the chassis

1. Align the inner sliding rail on the side of the server, and push towards the arrow to secure the hooks.



2. To install one screw onto chassis base each side.

NOTE: Chassis base with or without screw hole design and the screw position for inner rail may be different for each chassis.



Detach inner rail from standoff

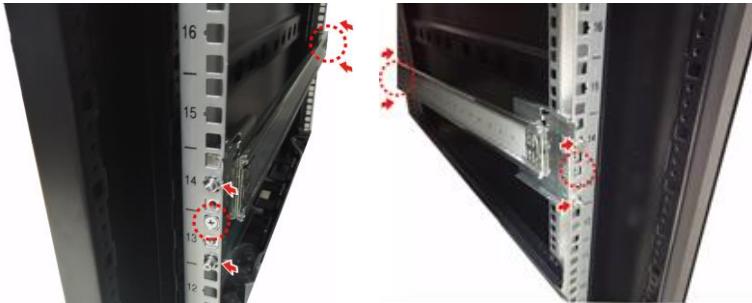
1. Loosen screw both sides of the server.
2. Pull the latch upward and remove the keyhole from standoff and slide inner rail forward to remove inner rail.



Fix the Outer rail/bracket assembly to the frame

Please according to the bracket type, and refer to the install/detach instruction.

1. Secure the outer rails to the rack on each side.



2. Please repeat installation steps for the other side.

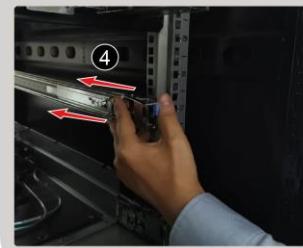
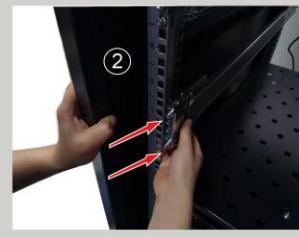
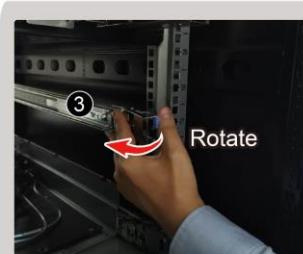
Detach bracket from rack post to

1. Release the outer rails from the rack on each side.

Front bracket



Rear bracket



2. Please repeat the detach steps for the other side.

Rack Mounting the Server

1. Pull the middle rail fully extended in lock position, ensure ball bearing retainer is located at the front of the middle rail.



2. Horizontally insert the chassis into middle-outer rails. When hit a stop, please pull/push the blue release tab on the inner rails.

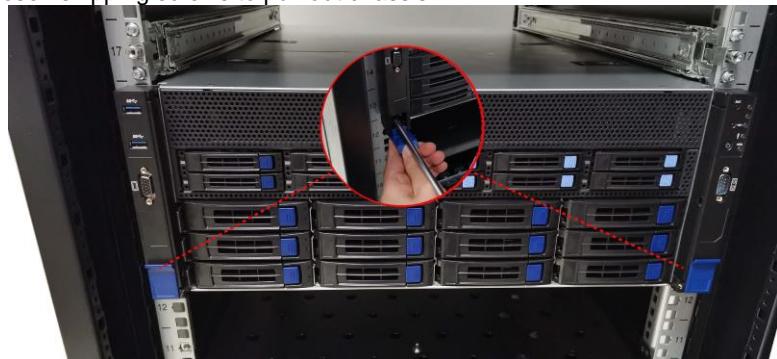


3. Tighten chassis with shipping screws.



2.2.2 Removing the Server from Rack

1. Loosen shipping screws to pull out chassis.



2. Pull the disconnect tab forward to remove chassis at the full extension position.



3. Push tab to slide the middle rail back.



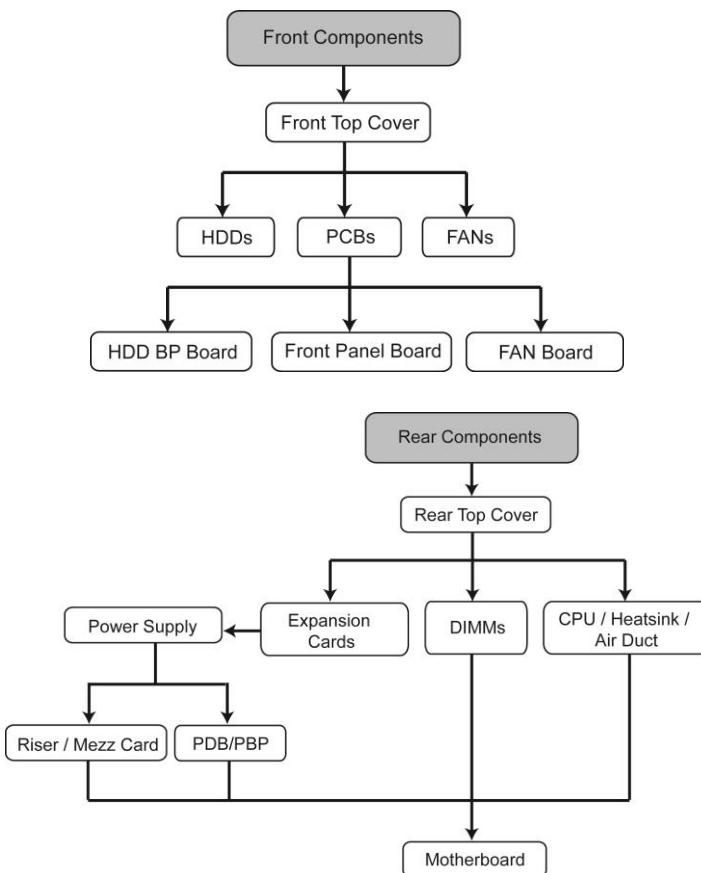
Chapter 3: Replacing Pre-Installed Components

3.1 Introduction

This chapter explains how to replace the pre-installed components, including the S7129GMRE Motherboard, M7129F83A-L16 Riser Card, M1297T65-BP12E-12/M1315F83A-BP12E-10 HDD Backplane Board, M7129F83A-IO IO board, M7129F83A-RIO Rear IO card, M7129F83A-FB Fan Board, System Fan and Power Supply, etc.

3.2 Disassembly Flowchart

The following flowchart outlines the disassembly procedure.



3.3 Removing the Cover

Before replacing any parts you must remove the chassis cover. Follow Chapter 2.1.1 to remove the cover of FT83A-B7129.

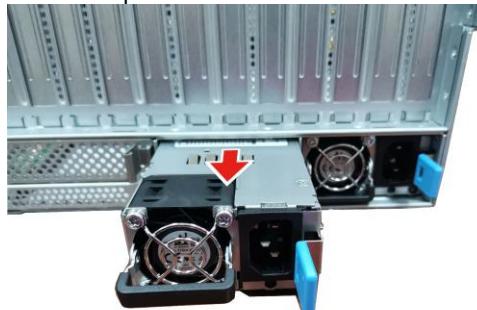
3.4 Replacing the Power Supply

To replace the power supply follow these instructions.

1. Press the tab as in the diagram from down to up.



2. Free the power from the power socket.



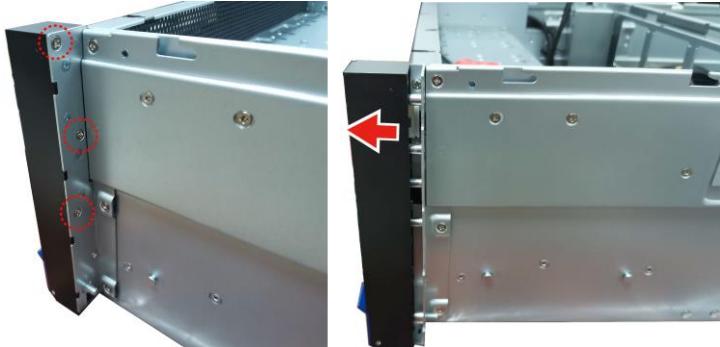
3. Replace a new single power and reinsert it into the power socket following the above steps in reverse.



3.5 Replacing the Front Panel Board

Follow these instructions to replace the [M1718T65-FPB](#) Front Panel Board.

1. Unscrew to remove the front panel board module.

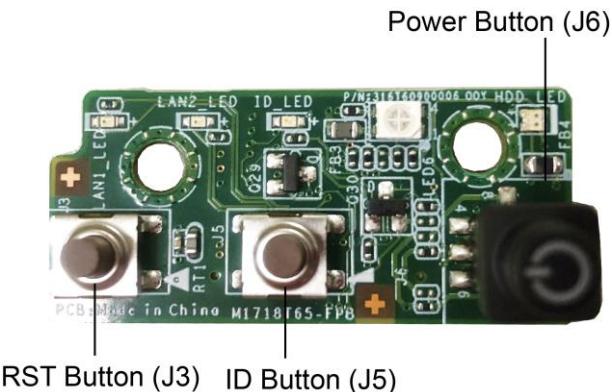


2. Loosen three screws to take out the front panel board. Loosen two screws to take out the front panel board.



3. Follow the steps described earlier in reverse order to reinstall the front panel board module.

3.5.1 Front Panel Board Features



M1718T65-FPB Front Panel Board	
Form Factor	<ul style="list-style-type: none">● PCB Dimensions: 40.00*18.00*1.6mm● Thickness: 1.6mm● Layer: 4 layers
Specifications	<ul style="list-style-type: none">● power button with LED● reset button● ID button● LED: ID LED (blue), Onboard HDD LED (green/Red), FAULT LED (Red/green/Blue), Power LED

3.6 Replacing the USB Board

Follow these instructions to replace the [M1717T65-USB](#) USB Board.

1. Unscrew to remove the front panel board module.

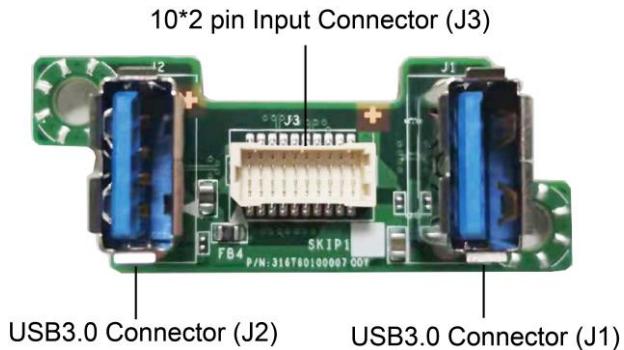


2. Loosen three screws to take out the front panel board. Loosen two screws to take out the front panel board.



3. Follow the steps described earlier in reverse order to reinstall the front panel board module.

3.6.1 Front Panel Board Features



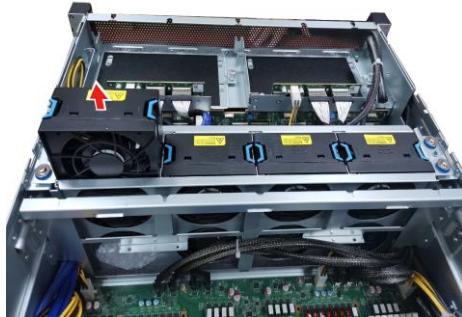
M1717T65-USB USB Board

Form Factor	<ul style="list-style-type: none">● PCB Dimensions: 48.00*19.00*1.6mm● Thickness: 1.6mm● Layer: 4 layers
Specifications	<ul style="list-style-type: none">● USB 3.0 Connectors● 10*2PIN input Connector

3.7 Replacing the System Fan

Follow these instructions to replace the system Fan.

1. Take out the system fan.



2. Press both sides of the fan cage as in the image.



3. Open the fan cage.



4. Take out the small fans.



5. Replace a new fan.



3.8 Replacing the Fan Board

Follow these instructions to replace the [M7129F83A-FB](#) Fan Board.

6. Remove all Fan modules.



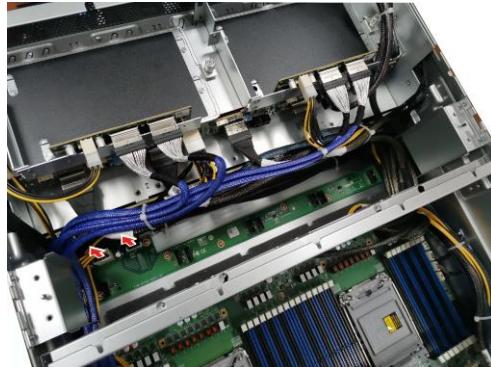
7. Unscrew the fan cage.



8. Lift up the fan cage.



9. Disconnect all cables from the Fan Board.



10. Unscrew to replace with a new Fan Board. Follow the steps in reverse order to reinstall the Fan Board.



3.8.1 Fan Board Features



M7129F83A-FB Fan Board

Specifications	(1) ATX 2*4P Power connector for power input(Power) (8) 7P FAN connector support(FAN1-FAN8) (1) 2*10P System FAN connector for main board(J10)
----------------	--

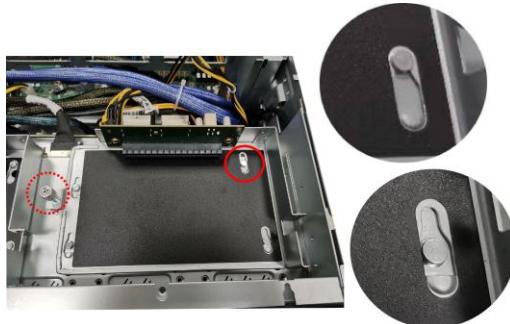
3.9 Replacing the Riser Board

Follow these instructions to replace the **M7129F83A-L16** riser card.

1. Disconnect the from the M7129F83A-PCIE Board.



2. Unscrew the release the buckle in the direction of the image to release the riser tray.



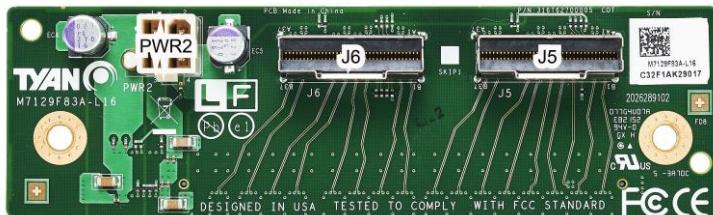
3. Unscrew to release the M7129F83A-L16 riser card.



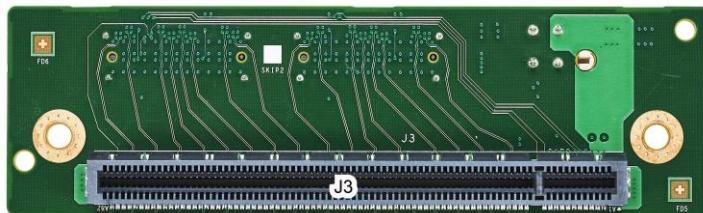
4. Follow the steps described earlier in reverse order to reinstall the IO Bridge Bracket.

3.9.1 Riser Board Features

Front View



Rear View



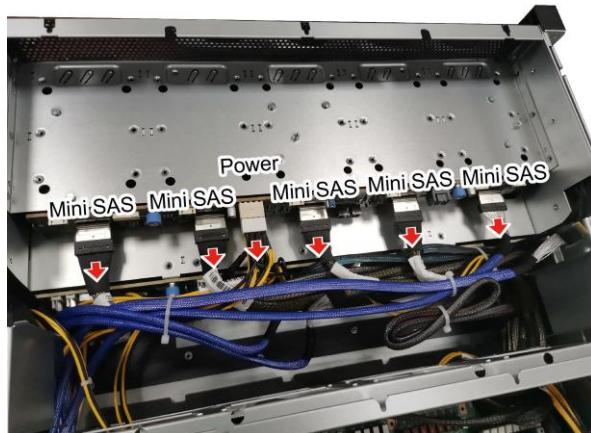
M7129F83A-L16 IO Bridge Board

Specifications	(2) Slim SAS Connector(J5/J6) (1) 2*2 Power Connector(PWR2) (1) PCIE Slot x16 (J3)
-----------------------	--

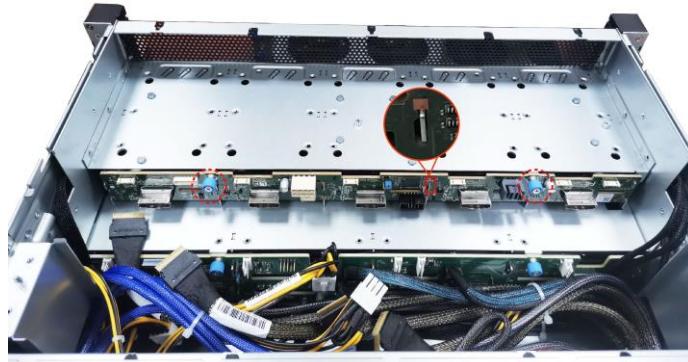
3.10 Replacing the HDD Backplane Board

Follow these instructions to replace the [M1315F83A-BP12E-10](#) HDD Backplane Board.

1. Disconnect all cables connected to the HDD BP Board.



2. Unscrew the HDD BP Board and release it from the hook.



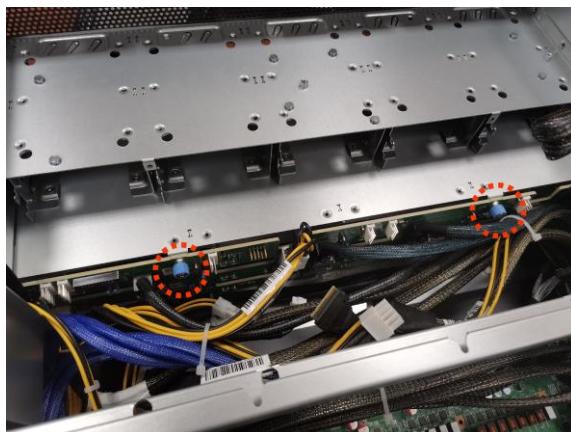
3. Take out the HDD BP Board to replace with a new one. Follow the procedures described earlier in reverse order to reinstall the HDD BP Board and HDD cage.

Follow these instructions to replace the [M1297T65-BP12E-12](#) HDD Backplane Board.

4. Disconnect all cables connected to the HDD BP Board.



5. Unscrew the HDD BP Board from the chassis.



6. Take out the HDD BP Board to replace with a new one. Follow the procedures described earlier in reverse order to reinstall the HDD BP Board and HDD cage.

3.10.1 HDD Backplane Board Features

M1315F83A-BP12E-10

Front View

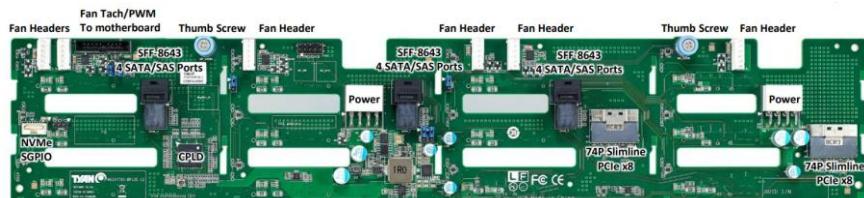


Rear View



M1297T65-BP12E-12

Front View



Rear View



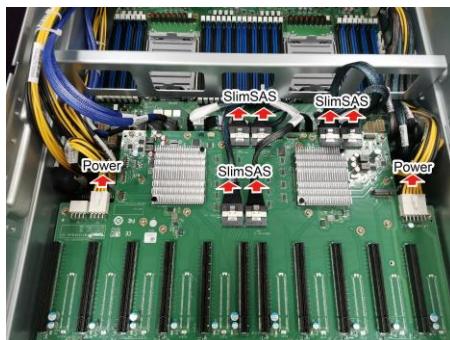
3.11 Replacing PCIE Board

Follow these instructions to replace the [M7129F83A-IO](#) PCIE Board.

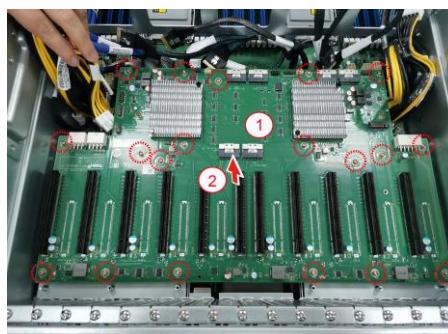
1. Unscrew to remove the GPU Bracket.



2. Disconnect all cables connected to the PCIE Board.



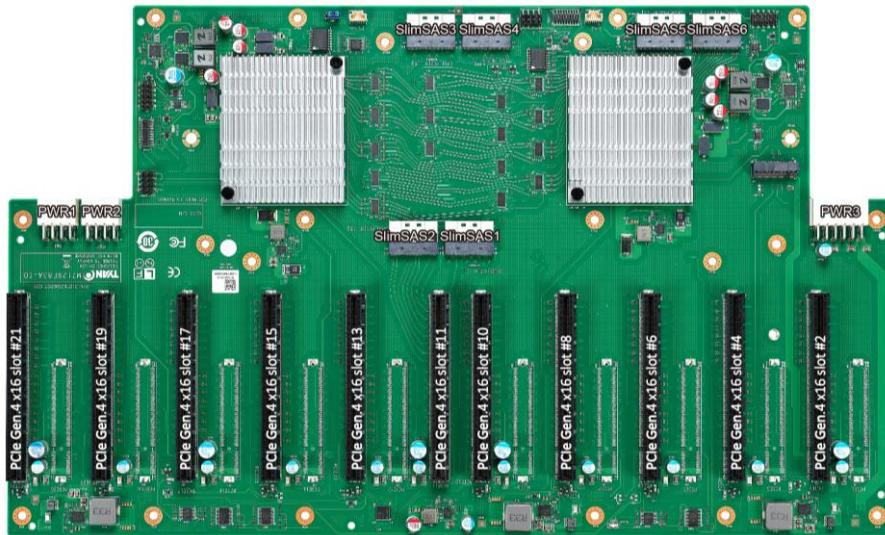
3. Unscrew to lift up the PCIE Board Bracket (totally 19 screws).



4. Replace the PCIE Board with a new one. Follow the steps described earlier in reverse order to reinstall the PCIE Board Bracket.

3.11.1 PCIE Board Features

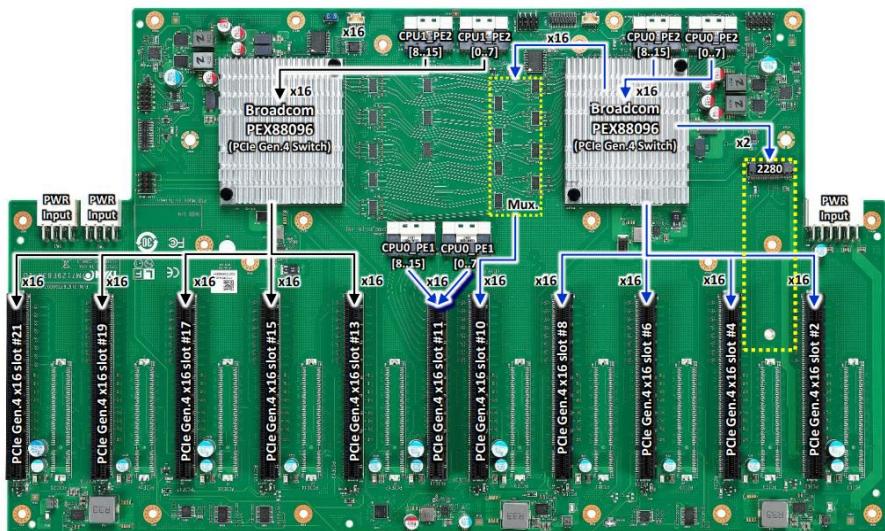
Front View



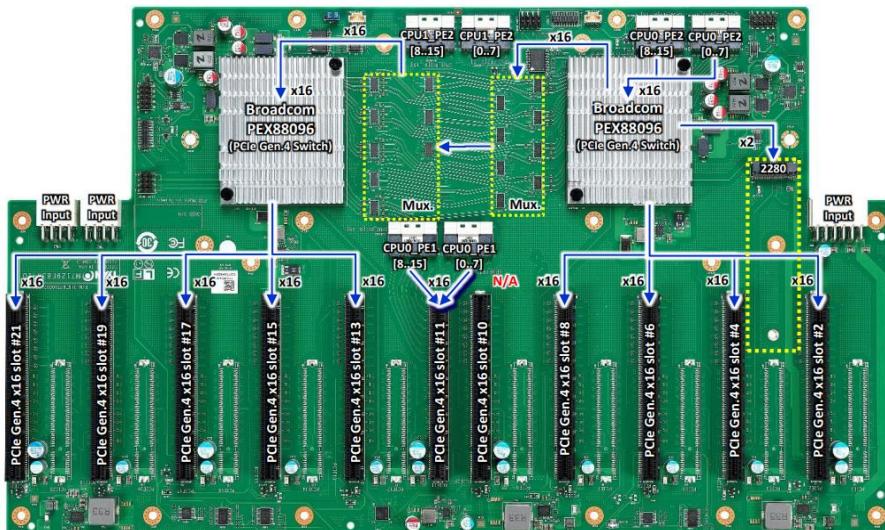
M7129F83A-IO PCIE Board

Specifications	Dual PCIE x24 lanes input and expansion to (1)PCIE x16 +(10) DW PCI-E x16 slots or (1)PCIE x16+ (20) PCIE x8 slots
-----------------------	--

M7129F83A-IO Default PCIe Routing Topology (Dual Root)



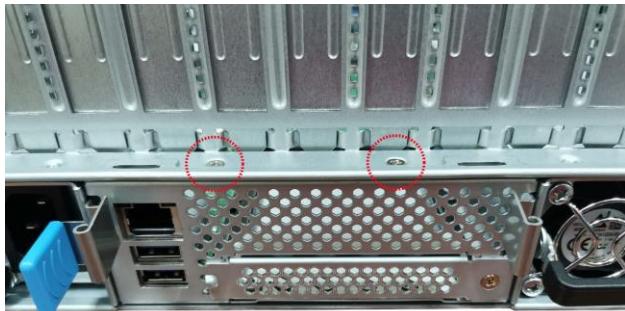
M7129F83A-IO Optional PCIe Routing Topology (Single Root)



3.12 Replacing the Rear IO Board

Follow these instructions to replace the [M7129F83A-RIO](#) Rear IO Board.

1. Unscrew the Rear IO Bracket.



2. Push both latches to pull the Rear IO Bracket out.



3. Unscrew to remove the iron bracket.



4. Follow the steps described earlier in reverse order to reinstall the Rear IO Bracket.

3.12.1 Rear IO Board Features

Front View

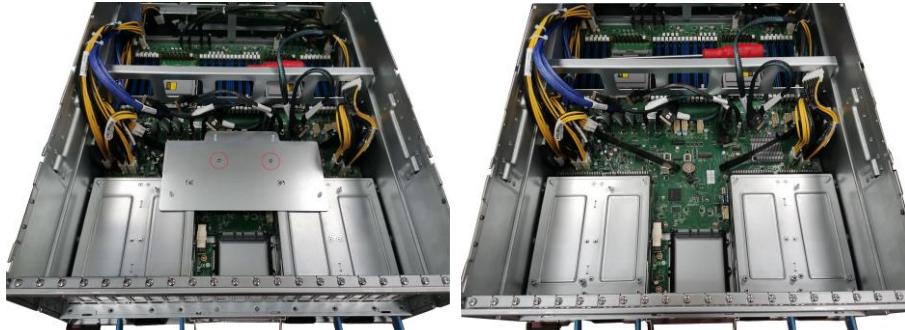


M7119FA77-RIO Rear IO Board	
Specifications	(1)1G RJ-45 port for IPMI + (2)USB3.0 ports (1) FCI Board to board connector to Main board (1) OCP type A + (1)OCP type B connector for NIC OCP card

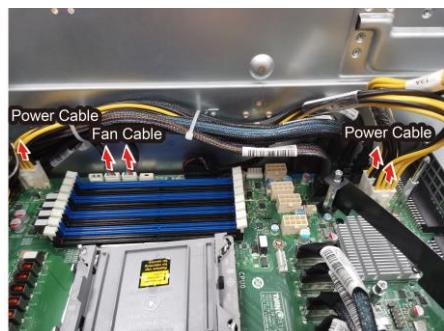
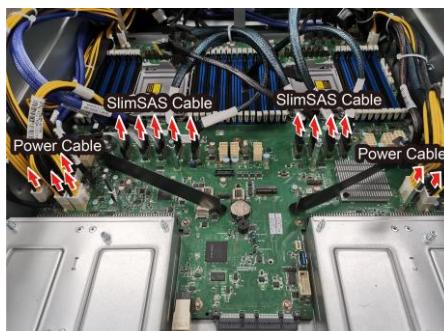
3.13 Replacing the Motherboard

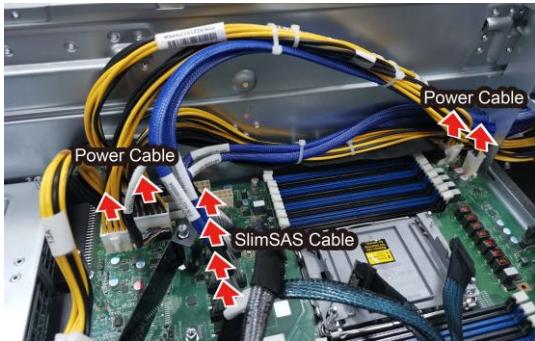
After removing all of the aforementioned cables and components, follow these instructions to remove the motherboard from the chassis.

1. Unscrew to remove the board.

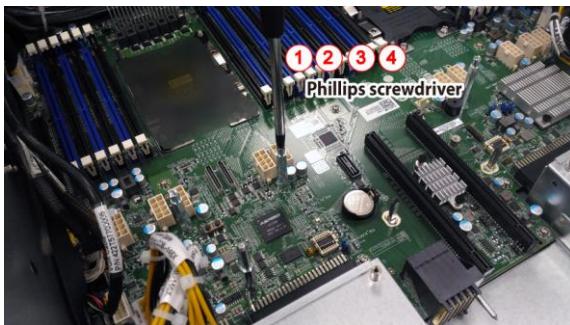
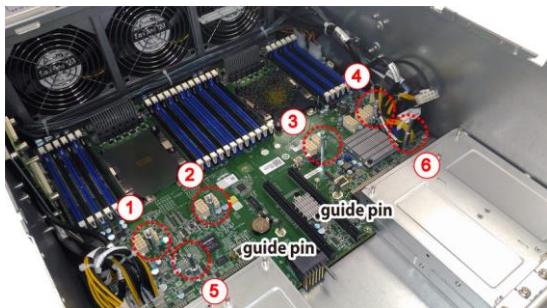


2. Disconnect all cables on the motherboard.



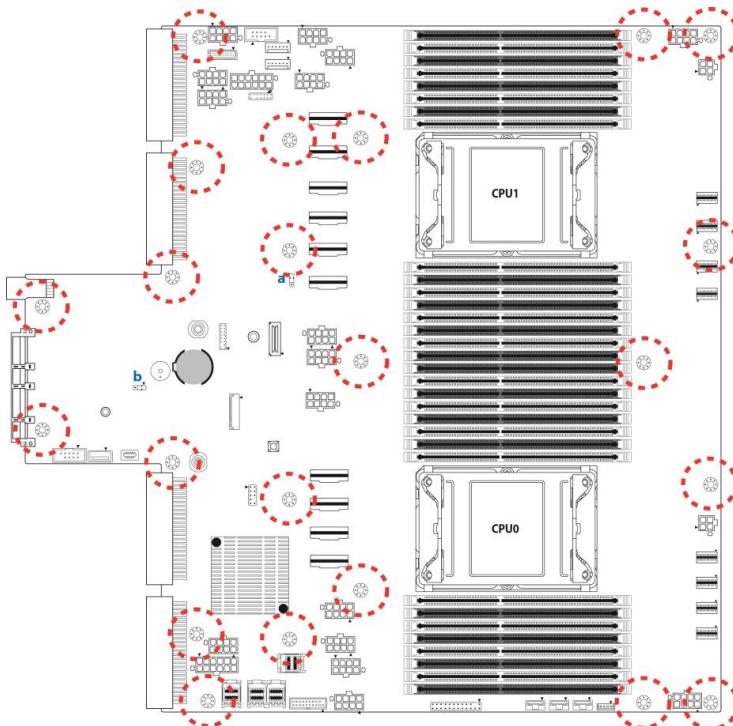


3. Refer to [**3.9 Replacing the IO Board**](#) to unscrew to lift up the Linkbar.
4. Use a hex screwdriver and Phillips screwdriver to loosen screws.





5. Unscrew the motherboard to lift it up for replacement.



Chapter 4: Motherboard Information

You are now ready to install your motherboard.

How to install our products right... the first time

The first thing you should do is read this user's manual. It contains important information that will make configuration and setup much easier. Here are some precautions you should take when installing your motherboard:

- (1) Ground yourself properly before removing your motherboard from the antistatic bag. Unplug the power from your computer power supply and then touch a safely grounded object to release static charge (i.e. power supply case). For the safest conditions, MiTAC recommends wearing a static safety wrist strap.
- (2) Hold the motherboard by its edges and do not touch the bottom of the board, or flex the board in any way.
- (3) Avoid touching the motherboard components, IC chips, connectors, memory modules, and leads.
- (4) Place the motherboard on a grounded antistatic surface or on the antistatic bag that the board was shipped in.
- (5) Inspect the board for damage.

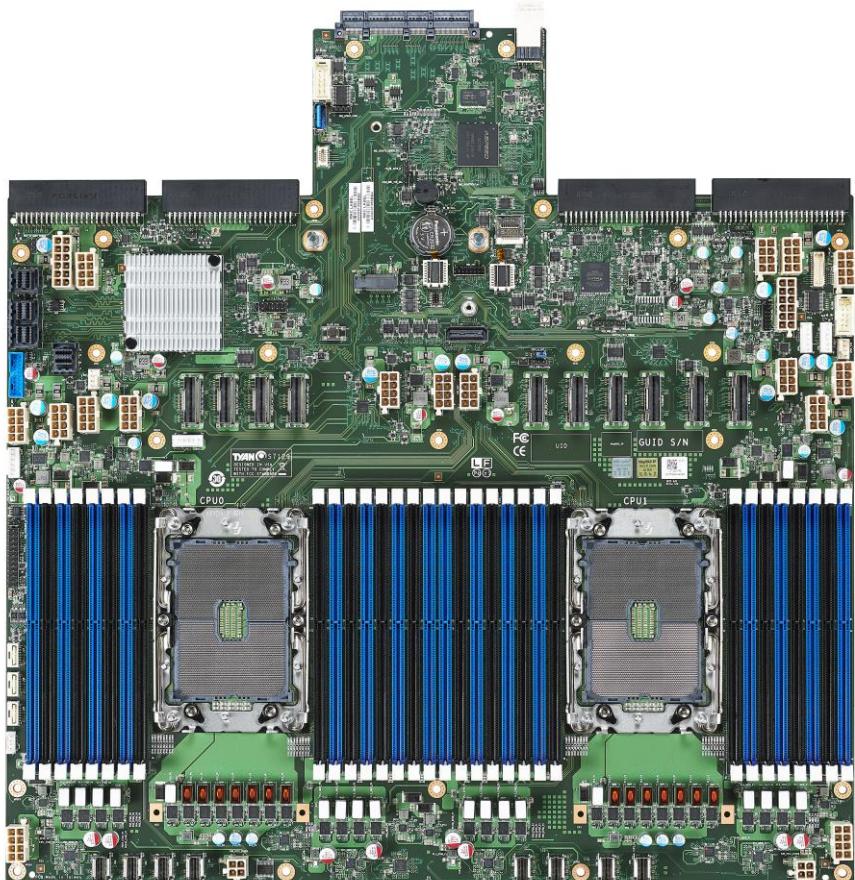
The following pages include details on how to install your motherboard into your chassis, as well as installing the processor, memory, disk drives and cables.

Caution!



3. To avoid damaging the motherboard and associated components, do not use torque force greater than **7kgf/cm (6.09 lb/in)** on each mounting screw for motherboard installation.
4. Do not apply power to the board if it has been damaged.

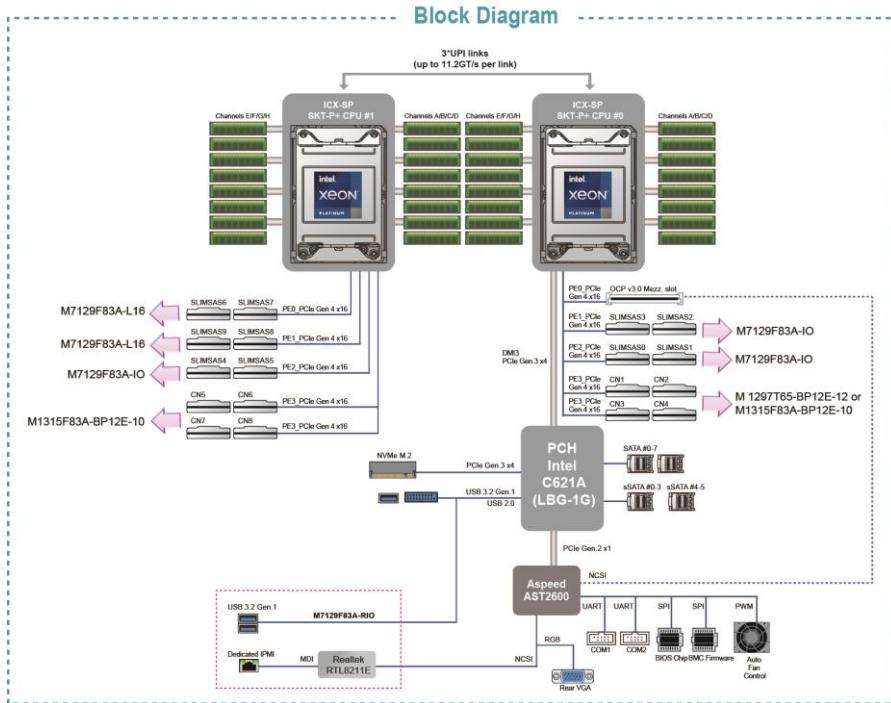
4.1 Board Image



S7129

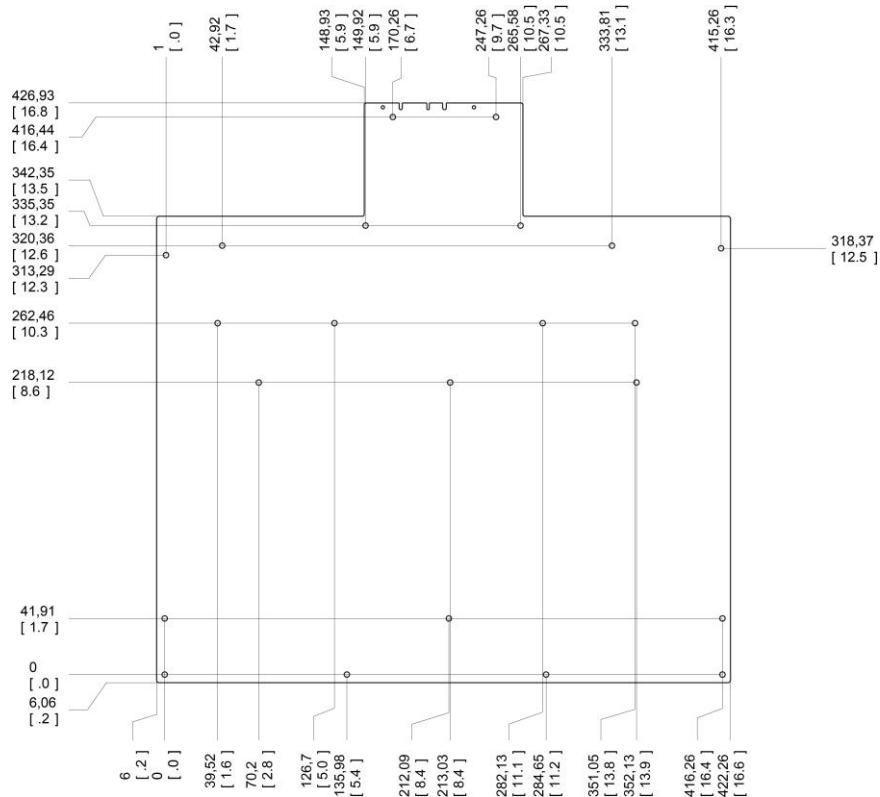
This picture is representative of the latest board revision available at the time of publishing. The board you receive may not look exactly like the above picture.

4.2 Block Diagram

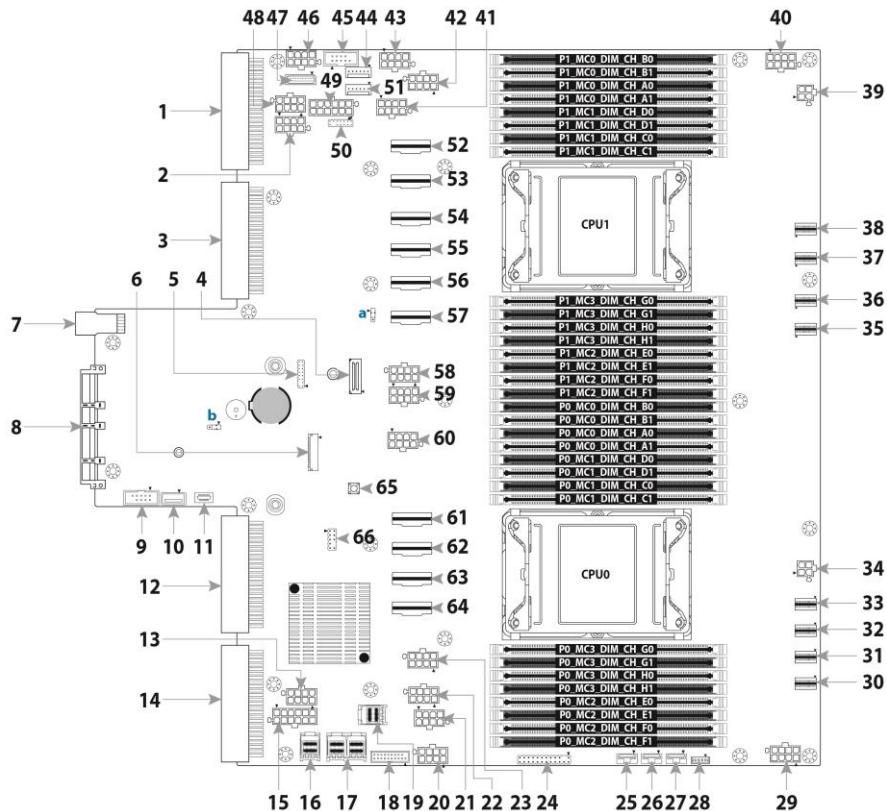


S7129 Block Diagram

4.3 Motherboard Mechanical Drawing



4.4 Board Parts, Jumpers and Connectors



This diagram is representative of the latest board revision available at the time of publishing. The board you receive may not look exactly like the above diagram. The DIMM slot numbers shown above can be used as a reference when reviewing the DIMM population guidelines shown later in the manual. For the latest board revision, please visit our web site at <http://www.tyan.com>.

Jumpers & Connectors

Connectors	
1.PSU Connector(J1)	34. Power Connector for Front Riser (J52)
2.Power Connector for Fan (J46)	35. SlimSAS Connector for HDD BP (CN8)
3.PSU Connector (J2)	36. SlimSAS Connector for HDD BP (CN7)
4.XDP Connector (J7)	37. SlimSAS Connector for HDD BP (CN6)
5.TYAN Module Header (DBG_HD1)	38. SlimSAS Connector for HDD BP (CN5)
6.M.2 Connector (NGFF1)	39. Power Connector for Front Riser (J36)
7.RGMII/Rear USB B2B Connector (CN9)	40. Power Connector for MB (J49)
8.OCP3.0 Connector (J39)	41. Power Connector for GPU(J32)
9. COM2 Port (HD_COM2)	42. Power Connector for GPU(J16)
10. USB 3.1 TYPEA Connector (J24)	43. Power Connector for GPU (J6)
11.Reserved for SPI TPM(J34)	44. Rear Fan Connector(J41)
12.PSU Connector (J3)	45. COM1 Port (HD_COM1)
13.Power Connector for MB (J45)	46. Power Connector for MB(J50)
14.PSU Connector (J4)	47. Fan Header(FAN_HD1)
15.Power Connector for PCIe IO Board (J47)	48. Power Connector for PCIe IO Board (J15)
16.SSATA Connector (J20)	49. Power Connector for HDD BP (J55)
17.SATA Connector (SATA0_7)	50. VGA Port (FPIO_VGA)
18.FPB USB Connector (J5)	51. Rear Fan Connector (J42)
19.SSATA Connector (J23)	52. SlimSAS Connector for PCIe Riser (SlimSAS6)
20.Power Connector for GPU(J21)	53. SlimSAS Connector for PCIe Riser (SlimSAS7)
21.Power Connector for GPU(J37)	54. SlimSAS Connector for PCIe Riser (SlimSAS9)
22.Power Connector for GPU(J33)	55. SlimSAS Connector for PCIe Riser (SlimSAS8)
23.Power Connector for GPU(J14)	56. SlimSAS Connector for PCIe IO (SlimSAS4)
24.Front Panel Header (ID_LED/FPIO)	57. SlimSAS Connector for PCIe IO (SlimSAS5)
25.Signal For NVMe Hotplug (J17)	58. Power Connector for GPU (J12)
26.Signal For NVMe Hotplug (J18)	59. Power Connector for GPU (J13)
27.Signal For NVMe Hotplug (J19)	60. Power Connector for GPU (J11)
28. SATA Raid Key (J51)	61. SlimSAS Connector for PCIe IO (SlimSAS3)
29. Power Connector for MB (J54)	62. SlimSAS Connector for PCIe IO (SlimSAS2)
30.SlimSAS Connector for HDD BP (CN4)	63. SlimSAS Connector for PCIe IO (SlimSAS0)
31.SlimSAS Connector for HDD BP (CN3)	64. SlimSAS Connector for PCIe IO (SlimSAS1)
32.SlimSAS Connector for HDD BP (CN2)	65. Clear CMOS Button (CLEAR_BTN1)
33.SlimSAS Connector for HDD BP (CN1)	66.JTAG Connector for CPLD (J28)
Jumpers	
a LPC Mode(default) (J59_12) ESPI Mode (J59_23)	b ME Recovery Mode Jumper (default) (J113-12) ME Firmware Update Jumper(J113_23)

FAN_HD1: 30-Pin FAN Connector

Signal	Pin	Pin	Signal
FAN_T1	1	2	FAN_T6
FAN_T2	3	4	FAN_T7
FAN_T3	5	6	FAN_T8
FAN_T4	7	8	FAN_T9
FAN_T5	9	10	FAN_T10
GND	11	12	GND
PWM2	13	14	PWM1
FAN_T11	15	16	SDA
FAN_T12	17	18	SCL
P5V	19	20	PWM3
P5V	21	22	GND
FAN_T13	23	24	FAN_T15
FAN_T14	25	26	FAN_T16
PWM4	27	28	PWM5
PWM0	29	30	GND

HD_COM1: COM Port Header

Signal	Pin	Pin	Signal
BMC_COM1_DCD	1	2	BMC_COM1_DRS
BMC_COM1_RXD	3	4	BMC_COM1_RTS
BMC_COM1_TXD	5	6	BMC_COM1_CTS
BMC_COM1_DTR	7	8	BMC_COM1_NRI
GND	9	10	KEY

HD_COM2: COM Port Header

Signal	Pin	Pin	Signal
COM2_DCD	1	2	COM2_DSR
COM2_RXD	3	4	COM2_RTS
COM2_TXD	5	6	COM2_CTS
COM2_DTR	7	8	COM2_NRI
GND	9	10	KEY

TYPEA_USB3: Vertical Type-A USB3.1 Connector

Signal	Pin	Pin	Signal
+5V	1	2	USB DATA2-
USB DATA2+	3	4	GND
SSRX-	5	6	SSRX+
GND	7	8	SSTX-
SSTX+	9		

J5: FPB USB3.0 Header

Signal	Pin	Pin	Signal
+5V	1	20	KEY
N2_RX	2	19	+5V
P2_RX	3	18	N1_RX
GND	4	17	P1_RX
N2_TX	5	16	GND
P2_TX	6	15	N1_TX
GND	7	14	P1_TX
N12	8	13	GND
P12	9	12	N10
OC_N	10	11	P10

FPIO_1: Front Panel Header

Signal	Pin	Pin	Signal
PW_LED+	1	2	FP_PWR(3.3V)
KEY	3	4	FP_ID_LED_PWR
PW_LED-	5	6	FP_ID_LED_N
HD_LED+	7	8	HWM_FAULT_LED-
HD_LED-	9	10	SYS_FAULT_LED-
PW_SW#	11	12	LAN1_ACTLED+
GND	13	14	LAN1_ACTLED-
RST_SW#	15	16	SDA
GND	17	18	SCL
FP_ID_LED_BTN_N	19	20	INTRUDER#
FPIO_TEMP_IN	21	22	LAN2_ACTLED+
NMI_SW#	23	24	LAN2_ACTLED-

FPIO_VGA: Front Panel VGA Header

Signal	Pin	Pin	Signal
GND	1	2	P5V
GND	3	4	CON_VGA_R
GND	5	6	CON_VGA_G
GND	7	8	CON_VGA_B
GND	9	10	CLK_33M
CON_VGA_HS	11	12	KEY
CON_VGA_CLK	13	14	CON_VGA_VS

J51: SATA_RAID_KEY (HW Key for Intel VROC – NVMe only)

Signal	Pin	Pin	Signal
GND	1	2	2.21K to VCC3_AUX
GND	3	4	2.21K to VCC3_AUX

J20/J23: SSATA SGPIO Connector (SSATA0~3)

Signal	Pin	Pin	Signal
RSVD	PIN A1	PIN A2	INTL
GND	PIN A3	PIN A4	RX1_P
RX1_N	PIN A5	PIN A6	GND
RX3_P	PIN A7	PIN A8	RX3_N
GND	PIN A9	PIN B1	VACT
RSL	PIN B2	PIN B3	GND
RX0_P	PIN B4	PIN B5	RX0_N
GND	PIN B6	PIN B7	RX2_P
RX2_N	PIN B8	PIN B9	GND
SCL	PIN C1	PIN C2	SDA
GND	PIN C3	PIN C4	TX1_P
TX1_N	PIN C5	PIN C6	GND
TX3_P	PIN C7	PIN C8	TX3_N
GND	PIN C9	PIN D1	VACT
VMAN	PIN D2	PIN D3	GND
TX0_P	PIN D4	PIN D5	TX0_N
GND	PIN D6	PIN D7	TX2_P
TX2_N	PIN D8	PIN D9	GND

SATA Connector (SATA0~7)

Signal	Pin	Pin	Signal
RSVD	PIN A1	PIN A2	INTL
GND	PIN A3	PIN A4	RX1_P
RX1_N	PIN A5	PIN A6	GND
RX3_P	PIN A7	PIN A8	RX3_N
GND	PIN A9	PIN B1	VACT
RSL	PIN B2	PIN B3	GND
RX0_P	PIN B4	PIN B5	RX0_N
GND	PIN B6	PIN B7	RX2_P
RX2_N	PIN B8	PIN B9	GND
SCL	PIN C1	PIN C2	SDA
GND	PIN C3	PIN C4	TX1_P
TX1_N	PIN C5	PIN C6	GND
TX3_P	PIN C7	PIN C8	TX3_N
GND	PIN C9	PIN D1	VACT
VMAN	PIN D2	PIN D3	GND
TX0_P	PIN D4	PIN D5	TX0_N
GND	PIN D6	PIN D7	TX2_P
TX2_N	PIN D8	PIN D9	GND

DBG_HD1: TYAN Module Header

Signal	Pin	Pin	Signal
P3V3	1	2	FRAME_N
LAD0	3	4	KEY
LAD1	5	6	PLT_RST_N
LAD2	7	8	GND
LAD3	9	10	CLK_33M
DBG_SERIRQ	11	12	GND
DBG_PRES_N	13	14	VCC3_AUX
TPM_ADDR_MB	15	16	PCH TPM_PP_EN

J55: 8-pin Power Connector to HDD BP

Signal	Pin	Pin	Signal
GND	1	5	P12V_IN
GND	2	6	P12V_IN
GND	3	7	P12V_IN
GND	4	8	P12V_IN

J47/J15: 8-pin Power Connector to PCIE Board

Signal	Pin	Pin	Signal
GND	1	7	P12V_IN
GND	2	8	P12V_IN
GND	3	9	P12V_IN
GND	4	10	P12V_IN
GND	5	11	P12V_IN
GND	6	12	P12V_IN

J45/J50: 8-pin Power Connector to MB

Signal	Pin	Pin	Signal
GND	1	5	P12V_IN
GND	2	6	P12V_IN
GND	3	7	P12V_IN
GND	4	8	P12V_IN

Clear_BTN1: RTC reset Button for clear CMOS

Normal (Default)	Pin	1	2	3	4
Signal	GND	GND		RST_N	RST_N

J6/J11/J12/J13/J16/J21/J32/J33/J37: 8-pin Power Connector to GPU Card

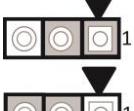
	Signal	Pin	Pin	Signal
	GND	1	5	P12V_IN
	GND	2	6	P12V_IN
	GND	3	7	P12V_IN
	GND	4	8	P12V_IN

NOTE: The 8-pin GPU power connector can support up to 30A.

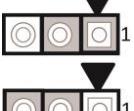
J36 / J52: 8-pin Power Connector to Front Riser Card

	Signal	Pin	Pin	Signal
	GND	1	3	P12V_IN
	GND	2	4	P12V_IN

J113: ME Recovery Mode Jumper/ME Firmware Update Jumper

	Pin1	Pin2	Pin3
	NC	FM_ME_RCVR_N	GND
1-2 Closed: Normal 2-3 Closed: ME Recovery Mode			

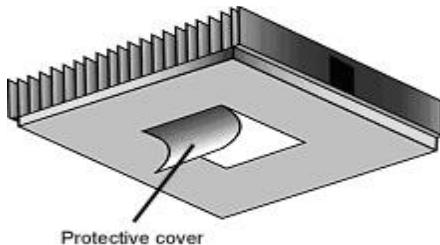
J59: ESPI_LPC Jumper

	Pin1	Pin2	Pin3
	PD_ESPI_EN	ESPI_H_LPC_L	VCC3_AUX
1-2 Closed: LPC Mode 2-3 Closed: ESPI Mode			

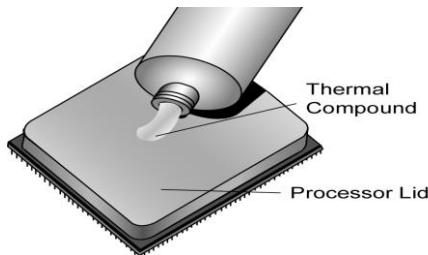
Jumper Legend

	OPEN - Jumper OFF	Without jumper cover
	CLOSED - Jumper ON	With jumper cover

4.5 Thermal Interface Material



There are two types of thermal interface materials designed for use with the processors.



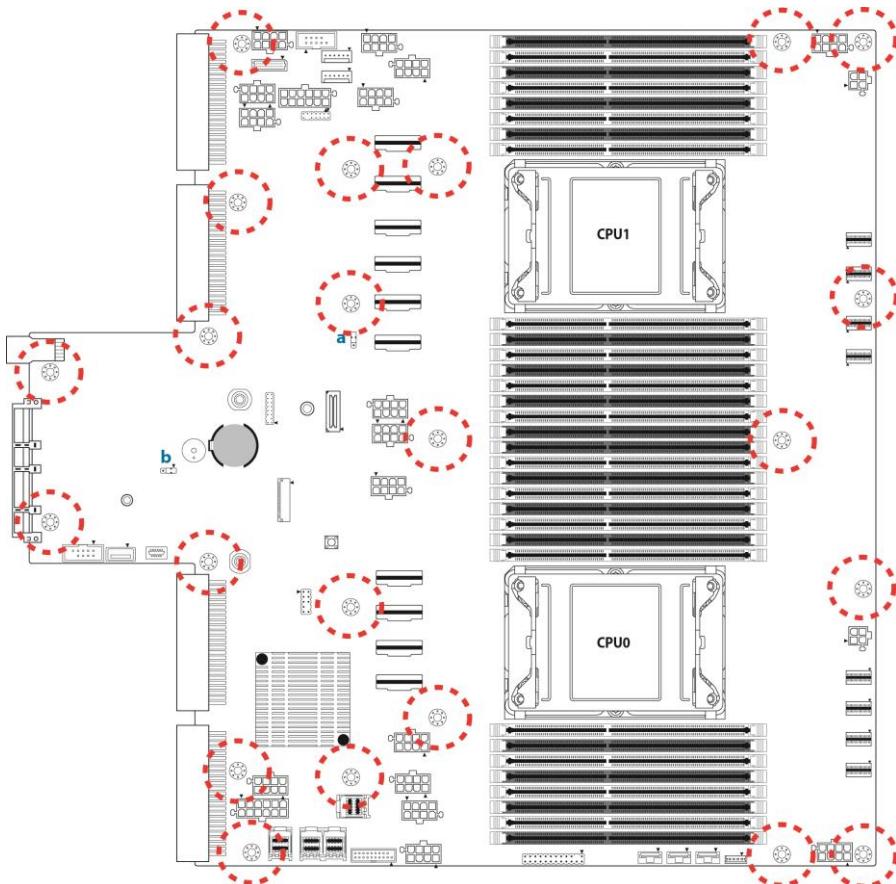
The most common material comes as a small pad attached to the heat sink at the time of purchase. There should be a protective cover over the material. Take care not to touch this material. Simply remove the protective cover and place the heat sink on the processor.

The second type of interface material is usually packaged separately. It is commonly referred to as 'thermal compound'. Simply apply a thin layer on to the CPU lid (applying too much will actually reduce the cooling).

NOTE: Always check with the manufacturer of the heat sink & processor to ensure that the thermal interface material is compatible with the processor and meets the manufacturer's warranty requirements.

4.6 Tips on Installing Motherboard in Chassis

Before installing your motherboard, make sure your chassis has the necessary motherboard support studs installed. These studs are usually metal and are gold in color. Usually, the chassis manufacturer will pre-install the support studs. If you are unsure of stud placement, simply lay the motherboard inside the chassis and align the screw holes of the motherboard to the studs inside the case. If there are any studs missing, you will know right away since the motherboard will not be able to be securely installed.



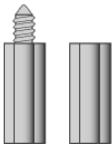
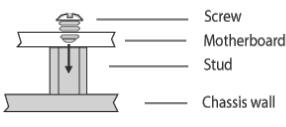
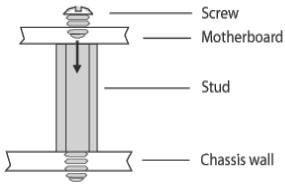
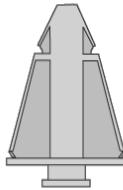
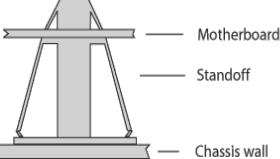
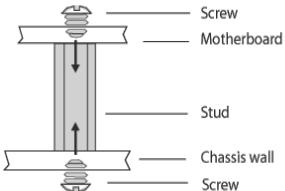
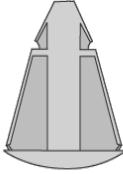
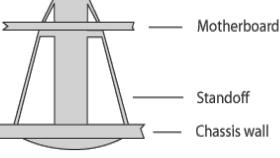
NOTE: Be especially careful to look for extra stand-offs. If there are any stand-offs present that are not aligned with a mounting hole on the motherboard, it will likely

short components on the back of the motherboard when installed. This will cause malfunction and/or damage to your motherboard.

Some chassis include plastic studs instead of metal. Although the plastic studs are usable, MITAC recommends using metal studs with screws that will fasten the motherboard more securely in place.

Below is a chart detailing what the most common motherboard studs look like and how they should be installed.

Mounting the Motherboard

Type	Solutions for installing	
	 Screw Motherboard Stud Chassis wall	 Screw Motherboard Stud Chassis wall
	 Motherboard Standoff Chassis wall	 Screw Motherboard Stud Chassis wall
	 Motherboard Standoff Chassis wall	 Stud Chassis wall Screw

Before installing memory, ensure that the memory you have is compatible with the motherboard and processor. Check the TYAN Web site at <http://www.tyan.com> for details of the type of memory recommended for your motherboard.

- This platform supports (16)+(16) DDR4 RDIMM/RDIMM 3DS/LRDIMM/ LRDIMM 3DS 3200/2933/2666/2400
- 1.2V DDR4 DIMMs are supported
- All installed memory will be automatically detected. No jumpers or settings need to be changed for memory detection.
- All memory must be of the same type and density. **Different memory types can NOT be mixed and matched on the same motherboard.**

- **General Population Requirements**

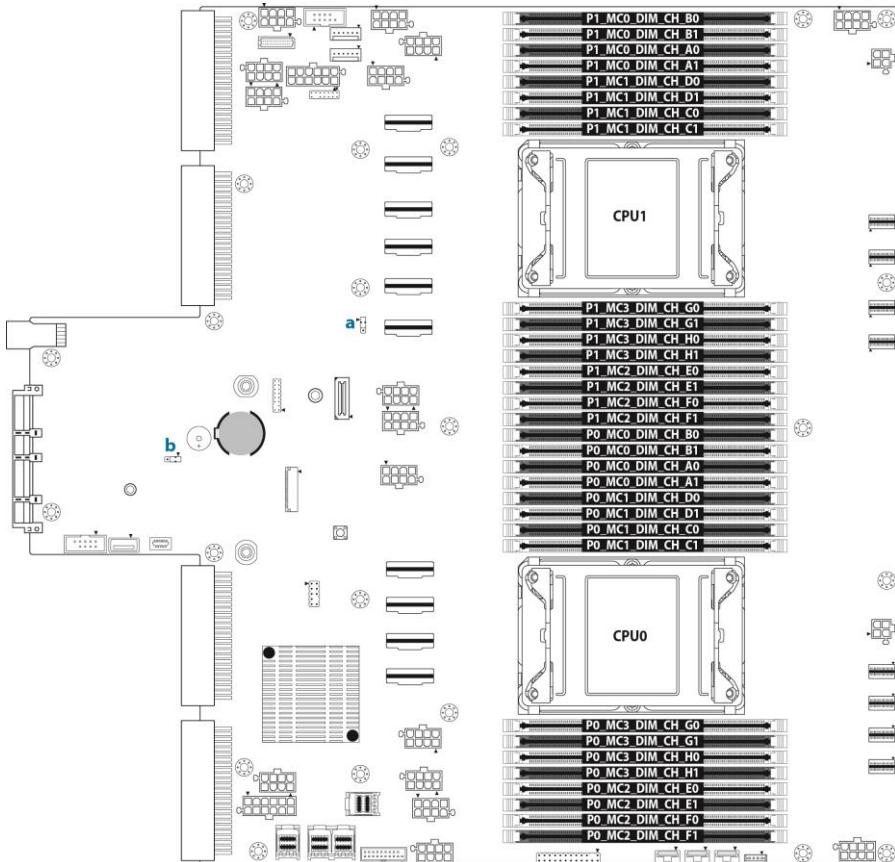
DIMM Mixing Rules:

- All DIMMs must be either all DDR4 DIMMs and/or DDR4 and Barlow Pass DIMMs.
- Mixing of RDIMMs and LRDIMMs is not allowed in the same channel, across different channels, and across different sockets.
- Mixing of Barlow Pass DIMMs with RDIMMs is supported in Whitley platform.
- Mixing of Barlow Pass DIMMs with LRDIMMs is supported in Whitley platform.
- Mixing of DDR4 or Barlow Pass operating frequencies is not recommended.
- NVDIMM is not validated and can not be mixed with Barlow Pass DIMMs.

- **Key Parameters for DIMM Configuration**

Parameter	Possible Values
# of Channels	1, 2, 3, 4, 5, 6, 7, 8
# of DIMMs Populated per channel	1DPC or 2DPC
DIMM Type	RDIMM (w/ECC), 3DS-RDIMM, LRDIMM, 3DS-LRDIMM, Barlow Pass DIMM
DIMM construction	<ul style="list-style-type: none">● non-3DS RDIMM Raw Cards: A/B (2Rx4), C (1Rx4), D (1Rx8), E (2Rx8)● 3DS RDIMM Raw Cards: A/B (4Rx4,8Rx4)● non-3DS LRDIMM Raw Cards: D/E (4Rx4)● 3DS LRDIMM Raw Cards: A/B (4Rx4,8Rx4)● Barlow Pass DIMM

DIMM Location



NOTE:

- ✓ indicates a populated DIMM slot.
- Use paired memory installation for max performance.
- Populate the same DIMM type in each channel, specifically
 - Use the same DIMM size
 - Use the same # of ranks per DIMM
- Always install with CPU0 Socket first.

Memory Population Table

Single CPU Installed		Quantity of memory installed															
(CPU0 only)		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
CPU0_DIMM_A0	√	√			√		√		√			√					√
CPU0_DIMM_A1												√					√
CPU0_DIMM_B0							√		√			√					√
CPU0_DIMM_B1					√		√		√			√					√
CPU0_DIMM_C0												√					√
CPU0_DIMM_C1												√					√
CPU0_DIMM_D0												√					√
CPU0_DIMM_D1												√					√
CPU0_DIMM_E1												√					√
CPU0_DIMM_F0												√					√
CPU0_DIMM_F1												√					√
CPU0_DIMM_G0					√		√		√			√					√
CPU0_DIMM_G1												√					√
CPU0_DIMM_H0												√					√
CPU0_DIMM_H1												√					√
Dual CPU Installed		Quantity of memory installed															
(CPU0 and CPU1)		2	4	6	8	10	12	14	16	18	20	22	24	26	28	30	32
CPU0_DIMM_A0	√	√			√		√		√			√					√
CPU0_DIMM_A1												√					√
CPU0_DIMM_B0							√		√			√					√
CPU0_DIMM_B1					√		√		√			√					√
CPU0_DIMM_C0												√					√
CPU0_DIMM_C1												√					√
CPU0_DIMM_D0												√					√
CPU0_DIMM_D1												√					√
CPU0_DIMM_E0		√					√		√			√					√
CPU0_DIMM_E1												√					√
CPU0_DIMM_F0												√					√
CPU0_DIMM_F1												√					√
CPU0_DIMM_G0					√		√		√			√					√
CPU0_DIMM_H0												√					√
CPU0_DIMM_H1												√					√
CPU1_DIMM_A0	√	√					√		√								√
CPU1_DIMM_A1												√					√
CPU1_DIMM_B0							√		√			√					√
CPU1_DIMM_B1												√					√
CPU1_DIMM_C0												√					√
CPU1_DIMM_C1												√					√
CPU1_DIMM_D0												√					√
CPU1_DIMM_D1												√					√
CPU1_DIMM_E0		√					√		√			√					√
CPU1_DIMM_E1												√					√
CPU1_DIMM_F0												√					√
CPU1_DIMM_F1												√					√
CPU1_DIMM_G0												√					√
CPU1_DIMM_G1												√					√
CPU1_DIMM_H0												√					√
CPU1_DIMM_H1												√					√

DCPMM Support Location

Symmetric Population within the Socket													
	iMC1				iMC0				Channel A				
Modes	Slot 1	Slot 0	Slot 1	Slot 0	Slot 1	Slot 0							
AD	DCPMM	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	2-2-2
MM	DCPMM	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	2-2-2
AD + MM	DCPMM	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	2-2-2
AD	-	DRAM1	-	DRAM1	DCPMM	DRAM1	-	DRAM1	-	DRAM1	-	DRAM1	2-1-1
MM	-	DRAM3	-	DRAM3	DCPMM	DRAM3	-	DRAM3	-	DRAM3	DCPMM	DRAM3	2-1-1
AD + MM	-	DRAM4	-	DRAM4	DCPMM	DRAM4	-	DRAM4	-	DRAM4	DCPMM	DRAM4	2-1-1
AD	-	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	-	DRAM1	DCPMM	DRAM1	DCPMM	DRAM1	2-2-2
MM	-	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	-	DRAM2	DCPMM	DRAM2	DCPMM	DRAM2	2-2-2
AD + MM	-	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	-	DRAM4	DCPMM	DRAM4	DCPMM	DRAM4	2-2-2
AD	-	DCPMM	-	DRAM1	-	DRAM1	-	DCPMM	-	DRAM1	-	DRAM1	1-1-1
MM	-	DCPMM	-	DRAM2	-	DRAM2	-	DCPMM	-	DRAM2	-	DRAM2	1-1-1
AD + MM	-	DCPMM	-	DRAM4	-	DRAM4	-	DCPMM	-	DRAM4	-	DRAM4	1-1-1
AD	-	DCPMM	DRAM1	DRAM1	DRAM1	DRAM1	-	DCPMM	DRAM1	DRAM1	DRAM1	DRAM1	2-2-1

Asymmetric Population within the Socket													
	iMC1				iMC0				Channel A				
Modes	Slot 1	Slot 0	Slot 1	Slot 0	Slot 1	Slot 0							
AD	-	DRAM1	-	DRAM1	-	DRAM1	-	DRAM1	-	DRAM1	DCPMM	DRAM1	2-1-1
AD*	-	DRAM1	-	DRAM1	-	DRAM1	-	DRAM1	-	DRAM1	DCPMM	DRAM1	2-1-1

- * 2nd socket has no DCPMM DIMM
- Mode definitions: AD=App Direct Mode, MM=Memory Mode, AD+MM=Mixed Mode
- For MM, general DDR4+DCPMM ratio is between 1:4 and 1:16. Excessive capacity for DCPMM can be used for AD.
- For each individual population, rearrangements between channels are allowed as long as the resulting population is consistent to Purley PDG rules
- For each individual population, the same DDR4 DIMM has to be used in all slots, as specified by the Purley PDG rules
- For each individual population, sockets are normally symmetric with exceptions for 1 DCPMM per socket and 1 DCPMM per node case.

DDR4 Type					Capacity
DRAM1	RDIMM	3DS RDIMM	LRDIMM	3DS LRDIMM	Any Capacity
DRAM2	RDIMM	3DS RDIMM	LRDIMM	3DS LRDIMM	Any Capacity and Preferably, >=32GB
DRAM3	RDIMM	-	-	-	16GB or 32GB
DRAM4	RDIMM	3DS RDIMM	LRDIMM		Any Capacity

4.7 Finishing Up

Congratulations on making it this far! You have finished setting up the hardware aspect of your computer. Before closing up your chassis, make sure that all cables and wires are connected properly, especially SATA cables and most importantly, jumpers. You may have difficulty powering on your system if the motherboard jumpers are not set correctly.

In the rare circumstance that you have experienced difficulty, you can find help by asking your vendor for assistance. If they are not available for assistance, please find setup information and documentation online at our website or by calling your vendor's support line.

Chapter 5: BIOS Setup

5.1 About the BIOS

The BIOS is the basic input/output system, the firmware on the motherboard that enables your hardware to interface with your software. The BIOS determines what a computer can do without accessing programs from a disk. The BIOS contains all the code required to control the keyboard, display screen, disk drives, serial communications, and a number of miscellaneous functions. This chapter describes the various BIOS settings that can be used to configure your system.

The BIOS section of this manual is subject to change without notice and is provided for reference purposes only. The settings and configurations of the BIOS are current at the time of print and are subject to change, and therefore may not match exactly what is displayed on screen.

This section describes the BIOS setup program. The setup program lets you modify basic configuration settings. The settings are then stored in a dedicated, battery-backed memory (called NVRAM) that retains the information even when the power is turned off.

To start the BIOS setup utility:

1. Turn on or reboot your system.
2. Press **** or **<F2>** during POST (**Del** on remote console) to start the BIOS setup utility.

5.1.1 Setup Basics

The table below shows how to navigate in the setup program using the keyboard.

Key	Function
Left/Right Arrow Keys	Change from one menu to the next
Up/Down Arrow Keys	Move between selections
Enter	Open highlighted section
PgUp/PgDn Keys	Change pages
+-	Change options
ESC	Exit

5.1.2 Getting Help

Pressing [F1] will display a small help window that describes the appropriate keys to use and the possible selections for the highlighted item. To exit the Help Window, press [ESC] or the [Enter] key again.

5.1.3 In Case of Problems

If you have trouble booting your computer after making and saving the changes with the BIOS setup program, you can restart the computer by holding the power button down until the computer shuts off (usually within 4 seconds); resetting by pressing CTRL-ALT-DEL; or clearing the CMOS.

The best advice is to only alter settings that you thoroughly understand. In particular, do not change settings in the Chipset section unless you are absolutely sure of what you are doing. The Chipset defaults have been carefully chosen either by MITAC or your system manufacturer for best performance and reliability. Even a seemingly small change to the Chipset setup options may cause the system to become unstable or unusable.

5.1.4 Setup Variations

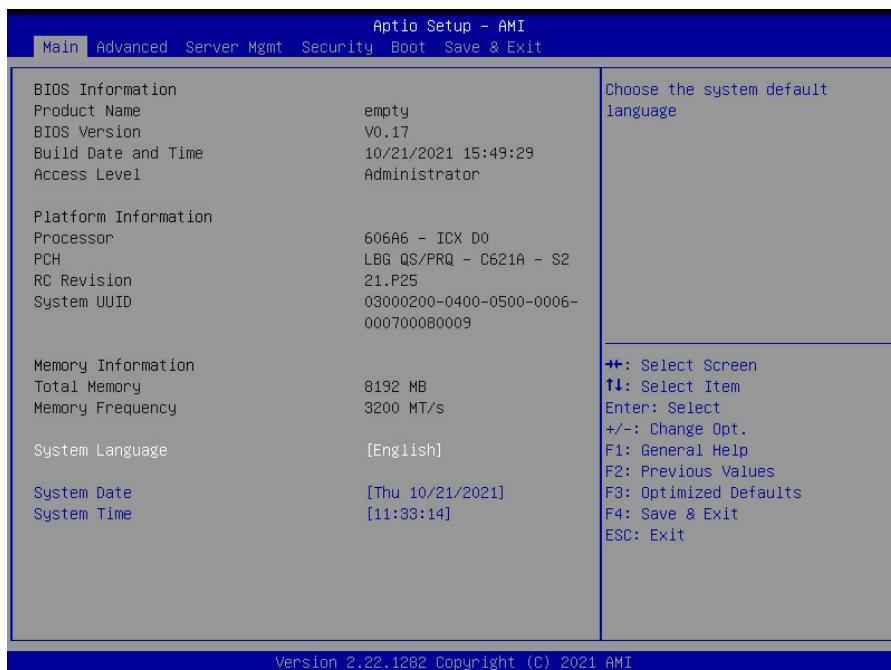
Not all systems have the same BIOS setup layout or options. While the basic look and function of the BIOS setup remains more or less the same for most systems, the appearance of your Setup screen may differ from the charts shown in this section. Each system design and chipset combination requires a custom configuration. In addition, the final appearance of the Setup program depends on the system designer. Your system designer may decide that certain items should not be available for user configuration, and remove them from the BIOS setup program.

NOTE: The following pages provide the details of BIOS menu. Please be noticed that the BIOS menu are continually changing due to the BIOS updating. The BIOS menu provided are the most updated ones when this manual is written. Please visit TYAN's website at <http://www.tyan.com> for the information of BIOS updating.

5.2 Main Menu

In this section, you can alter general features such as the date and time.

Note that the options listed below are for options that can directly be changed within the Main Setup screen.



System Language

Choose the system default language.

English / Simplified Chinese / Japanese

System Date

Set the Date. Use Tab to switch between Date elements. Default Ranges:

Year: 1998-9999

Months: 1-12

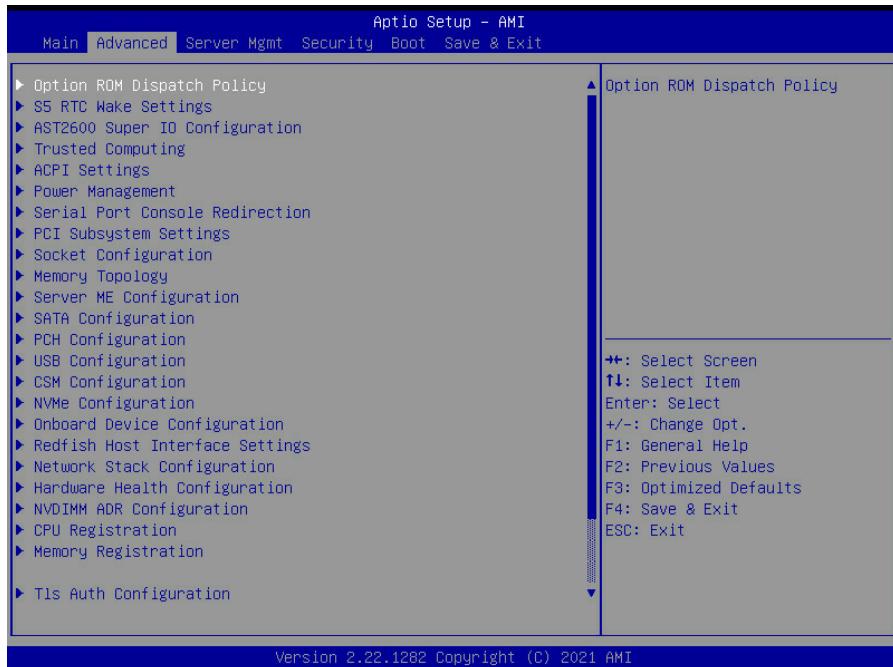
Days: dependent on month

System Time

Set the Time. Use Tab to switch between Time elements.

5.3 Advanced Menu

This section facilitates configuring advanced BIOS options for your system.



NOTE: This is a sample screenshot of the Advanced Menu. The HII network drivers displayed here depend on the card(s) you installed and the functions you enabled.

Option ROM Dispatch Policy

Option ROM Dispatch Policy.

S5 RTC Wake Settings

Enable system to wake from S5 using RTC alarm.

AST2600 Super IO Configuration

System Super IO Chip Parameters

Trusted Computing

Trusted Computing Settings.

ACPI Settings

System ACPI Parameters.

Power Management

Power Management.

Serial Port Console Redirection

Serial Port Console Redirection.

PCI Subsystem Settings

PCI, PCI-X and PCI Express Settings.

Socket Configuration

Socket Configuration.

Memory Topology

Memory Topology.

Server ME Configuration

Configure Server ME Technology Parameters.

SATA Configuration

SATA devices and settings.

PCH Configuration

SATA Device Information.

USB Configuration

USB Configuration Parameters.

CSM Configuration

CSM configuration: Enable/Disable, Option ROM execution settings, etc.

NVMe Configuration

NVMe Device Options Settings.

Onboard Device Configuration

Onboard Device and Function Configuration.

Redfish Host Interface Settings

Redfish Host Interface Parameters.

Network Stack Configuration

Network Stack Settings

Hardware Health Configuration

Hardware health Configuration Parameters.

NVDIMM ADR Configuration

NVDIMM ADR Configuration.

CPU Registration

This item support INTEL CPU, sign the CPU will record current CPU. Once BIOS checked different with registered CPU, show WRNING message on POST screen.

Memory Registration

Sign the Memory will record current Memory. Once BIOS checked different with registered Memory, show WARNING message on POST screen.

T1s Auth Configuration

Press <Enter> to select T1s Auth Configuration.

iSCSI Configuration

Configure the iSCSI parameters.

VLAN Configuration (MAC: XXXXXXXXXXXX)

VLAN Configuration (MAC: XXXXXXXXXXXX)

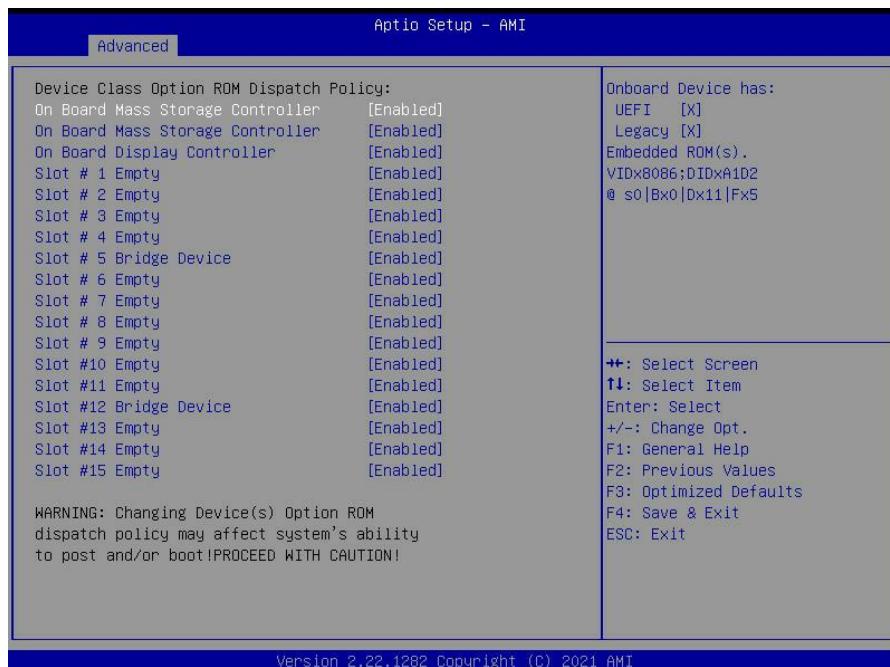
MAC: XXXXXXXXXXXX --- IPV4 Network Configuration

Configure network parameters. (MAC: XXXXXXXXXXXX)

MAC: XXXXXXXXXXXX --- IPV6 Network Configuration

Configure IPV6 network parameters. (MAC: XXXXXXXXXXXX)

5.3.1 Option ROM Dispatch Policy



Version 2.22.1282 Copyright (C) 2021 AMI

On Board Mass Storage Controller

Onboard Device has:

UEFI [X].

Legacy [X]

Embedded ROM(s).

VIDx8086; DIDxA252

@ s0|Bx0|Dx11|Fx5

Enabled / Disabled

On Board Mass Storage Controller

Onboard Device has:

UEFI [X].

Legacy [X]

Embedded ROM(s).

VIDx8086; DIDxA202

@ s0|Bx0|Dx17|Fx0

Enabled / Disabled

On Board Display Controller

Onboard Device has:

UEFI [X].

Legacy [X]

Embedded ROM(s).

VIDx1A03; DIDx2000

@ s0|Bx4|Dx0|Fx0

Enabled / Disabled

Slot #1~4 Empty

Enable or Disable Option ROM execution for selected Slot.

Enabled / Disabled

Slot #5 Bridge Device

Device on Slot does not have an option ROM.

Slot #6~11 Empty

Enable or Disable Option ROM execution for selected Slot.

Enabled / Disabled

Slot #12 Bridge Device

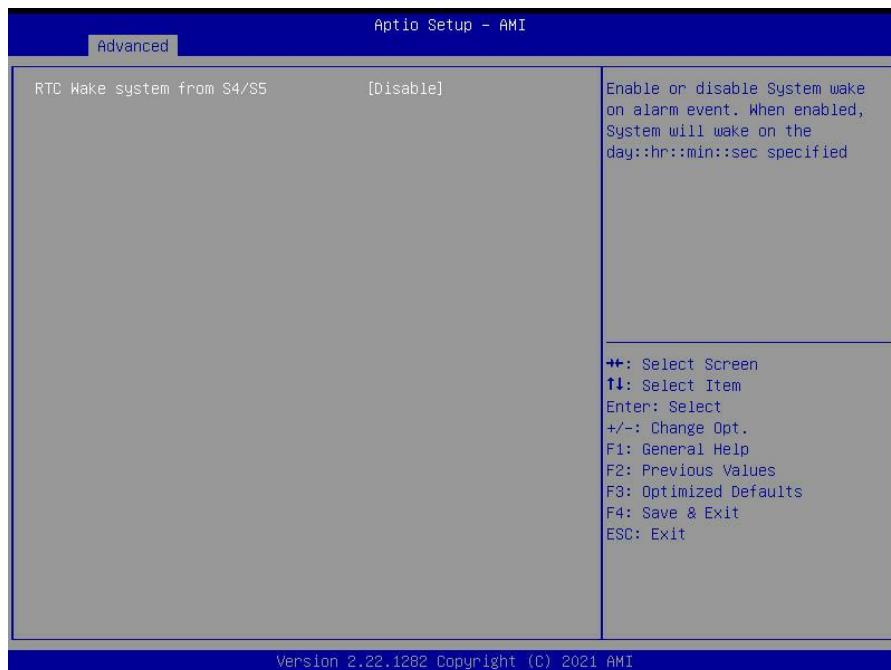
Device on Slot does not have an option ROM.

Slot #13~15 Empty

Enable or Disable Option ROM execution for selected Slot.

Enabled / Disabled

5.3.2 S5 RTC Wake Settings



Wake system from S4/S5

Enable or disable System wake on alarm event. When enabled, System will wake on the day::hr::min::sec specified.

Disable / Fixed Time / Dynamic Time

When Wake system from S5 is set to **[Fixed Time]**

Wake up hour

Select 0-23. For example enter 3 for 3am and 15 for 3pm.

Wake up minute

Select 0-59 for Minute.

Wake up second

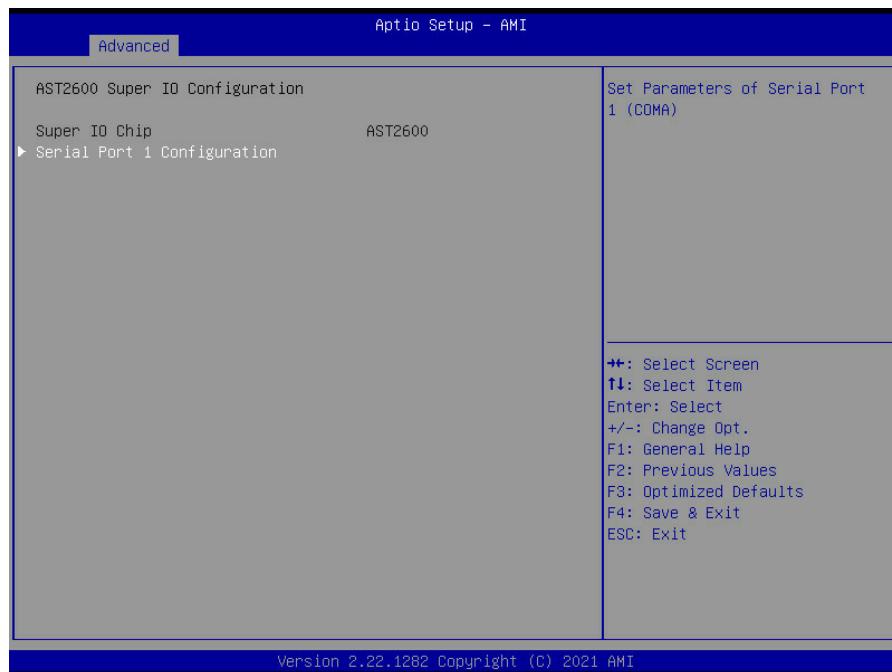
Select 0-59 for Second.

When Wake system from S5 is set to **[Dynamic Time]**

Wake up Minute increase

1

5.3.3 AST2600 Super IO Configuration



Super IO Chip

Read only.

Serial Port 1 Configuration

Set Parameters of Serial Port 1 (COMA).

5.3.3.1 Serial Port 1 Configuration



Serial Port

Enable or disable Serial Port (COM).

Enabled / Disabled

Change Settings

Select an optimal setting for Super IO Device.

Auto / IO=3F8h; IRQ=4;

/ IO=3F8h; IRQ=3, 4, 5, 6, 7, 9, 10, 11, 12;
/ IO=2F8h; IRQ=3, 4, 5, 6, 7, 9, 10, 11, 12;
/ IO=3E8h, IRQ=3, 4, 5, 6, 7, 9, 10, 11, 12;
/ IO=2E8h, IRQ=3, 4, 5, 6, 7, 9, 10, 11, 12;

5.3.4 Trusted Computing

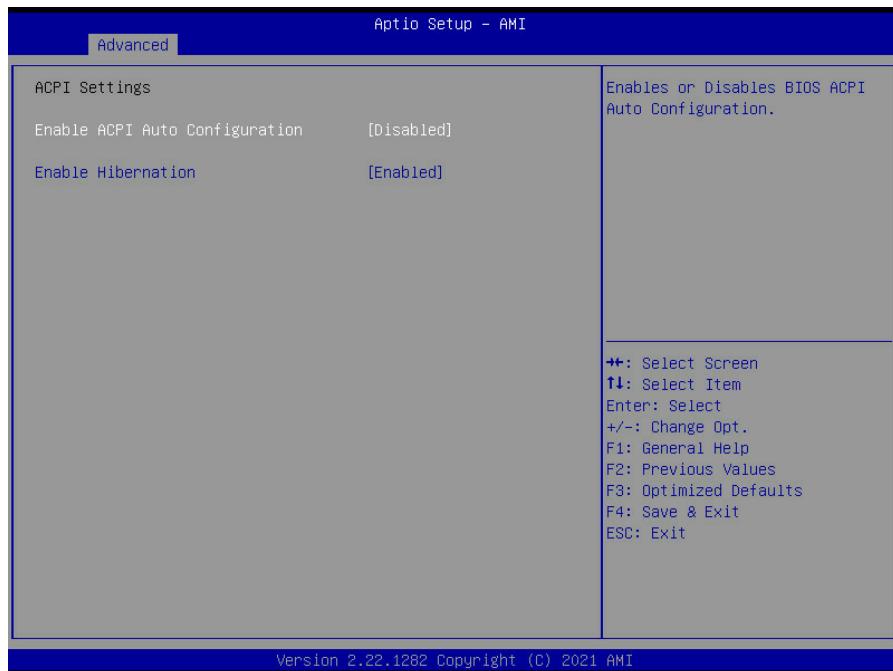


Security Device Support

Enables or Disables BIOS support for security device. O.S. will not show Security Device. TCG EFI protocol and INT1A interface will not be available.

Enable / **Disable**

5.3.5 ACPI Settings



Enable ACPI Auto Configuration

Enable or Disable BIOS ACPI Auto Configuration.

Disabled / Enabled

Enable Hibernation

Enable or Disable System ability to Hibernate (OS/S4 Sleep State). This option may not be effective with some operating system.

Disabled / **Enabled**

5.3.6 Power Management

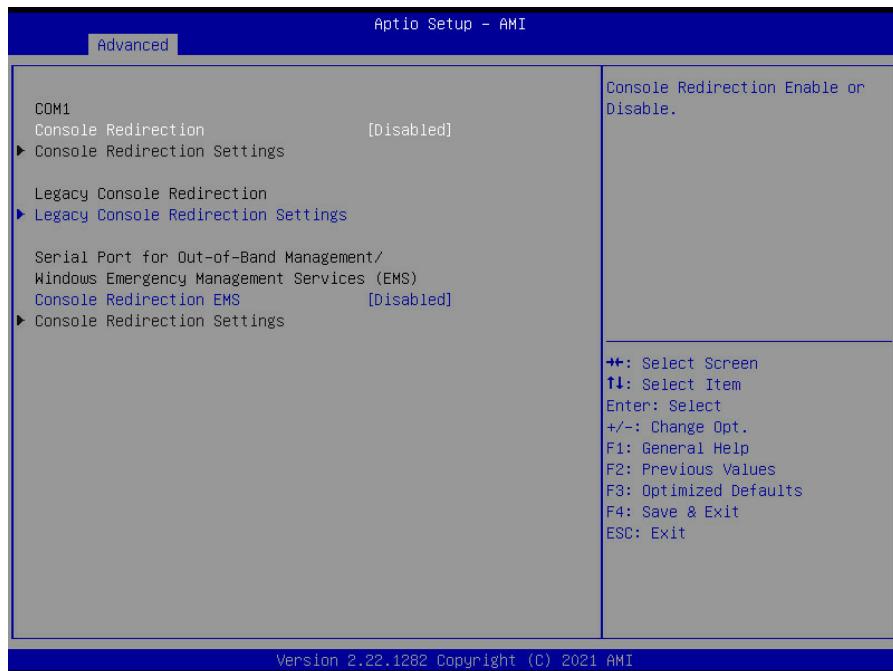


CPU Power and Performance Policy

CPU Power and Performance Policy.

Performance / Balanced Power / Power

5.3.7 Serial Port Console Redirection



Console Redirection

Console redirection enable or disable.

Disabled / Enabled

Legacy Console Redirection Settings

Legacy Console redirection settings.

Console Redirection Settings

The settings specify how the host computer (which the user is using) will exchange data. Both computers should have the same or compatible settings.

5.3.9.1 COM1 Console Redirection Settings



Terminal Type

Emulation: ANSI: Extended ASCII char set. VT100: ASCII char set.

VT100+: Extends VT100 to support color, function keys, etc.

VT-UTF8: Uses UTF8 encoding to map Unicode chars onto 1 or more bytes.

VT100+ / VT100 / VT-UTF8 / ANSI

Bits per Second

Select serial port transmission speed. The speed must be matched on the other side.

Long or noisy lines may require lower speeds.

38400 / 9600 / 19200 / 57600 / **115200**

Data Bits

8 / 7

Parity

A parity bit can be sent with the data bits to detect some transmission errors. Even: parity bit is 0 if the num of 1's in the data bits is even. Odd: parity bit is 0 if the num of 1's in the data bits is odd. Mark: parity bit is always 1. Space: parity bit is always 0. Mark and Space parity do not allow for error detection.

None / Even / Odd / Mark / Space

Stop Bits

Stop bits indicate the end of a serial data packet. (A start bit indicates the beginning). The standard setting is 1 stop bit. Communication with slow devices may require more than 1 stop bit.

1/2

Flow Control

Flow Control can prevent data loss from buffer overflow. When sending data, if the receiving buffers are full, a 'stop' signal can be sent to stop the data flow. Once the buffers are empty, a 'start' signal can be sent to restart the flow. Hardware flow control uses two wires to send start/stop signal.

None / Hardware RTS/CTS

VT-UTF8 Combo Key Support

Enable VT-UTF8 Combination Key Support for ANSI/VT100 terminals.

Enabled / Disabled

Recorder Mode

On this mode enabled only text will be sent. This is to capture Terminal data.

Disabled / Enabled

Resolution 100x31

Enable or disable extended terminal resolution.

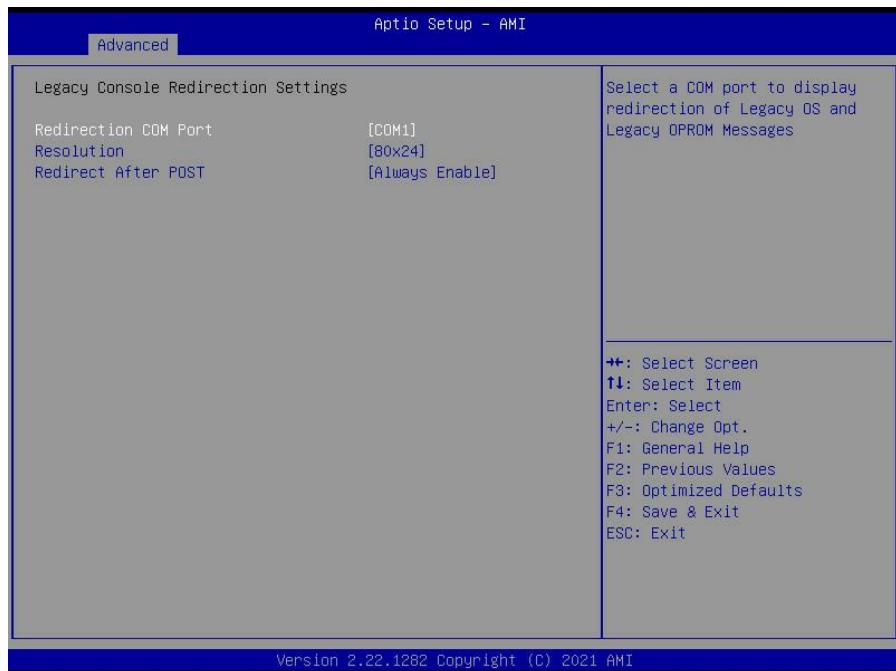
Disabled / Enabled

Putty KeyPad

Select FunctionKey and KeyPad on Putty.

VT100 / LINUX / XTERMR6 / SCO / ESCN / VT400

5.3.9.2 Legacy Console Redirection Settings



Legacy Serial Redirection Port

Select a COM port to display redirection of Legacy OS and Legacy OPROM Messages.

COM1

Resolution

On Legacy OS, the Number of Rows and Columns supported redirection.

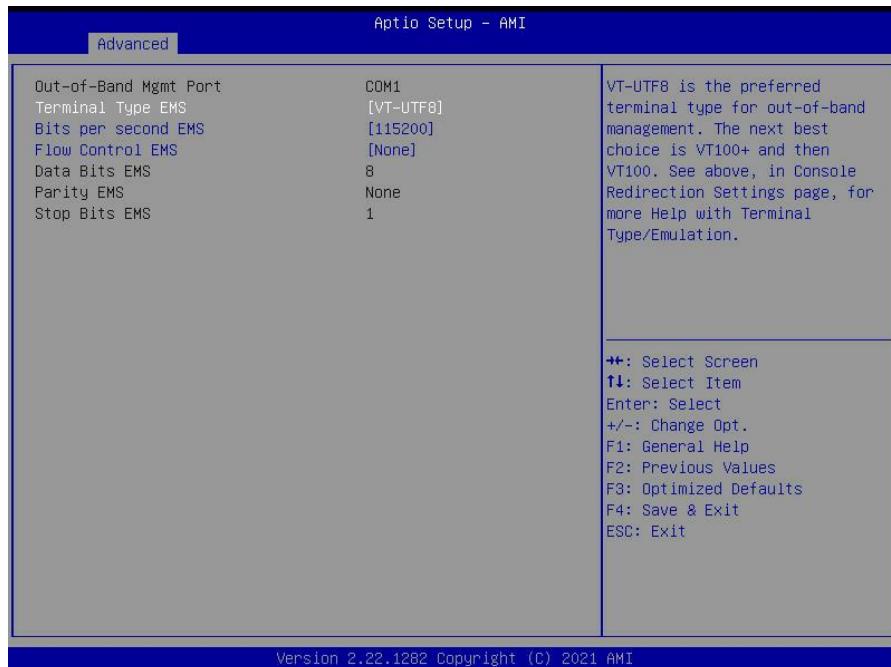
80x24 / 80x25

Redirect After POST

When BootLoader is selected, then Legacy Console Redirection is disabled before booting to legacy OS. When Always Enable is selected, then Legacy Console Redirection is enabled for legacy OS. Default setting for this option is set to Always Enable.

Always Enable / BootLoader

5.3.9.3 Serial Port for Out-Of-Band Management/Windows Emergency Services (EMS) Console Redirection Settings



Out-of-Band Mgmt Port

Microsoft Windows Emergency Management Services (EMS) allows for remote management of a Windows Server OS through a serial port.

COM1

Terminal Type

VT-UTF8 is the preferred terminal type for out-of-band management. The next best choice is VT100+ and then VT100. See above, in Console Redirection Settings page, for more Help with Terminal Type/Emulation.

VT-UTF8 / VT100 / VT100+ / ANSI

Bits per Second

Select serial port transmission speed. The speed must be matched on the other side. Long or noisy lines may require lower speeds.

115200 / 9600 / 19200 / 57600

Flow Control

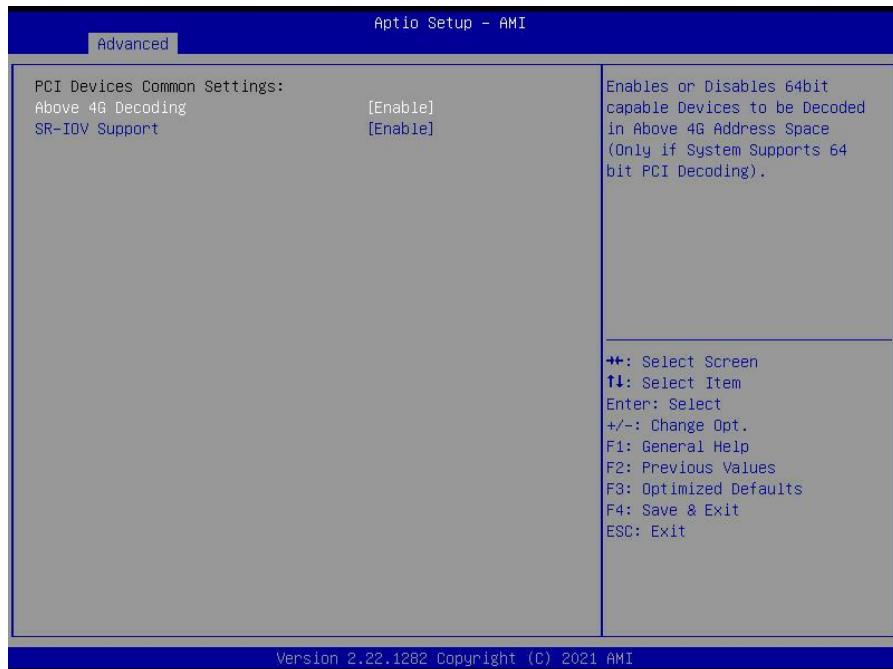
Flow Control can prevent data loss from buffer overflow. When sending data, if the receiving buffers are full, a 'stop' signal can be sent to stop the data flow. Once the buffers are empty, a 'start' signal can be sent to restart the flow. Hardware flow control uses two wires to send start/stop signal.

None / Hardware RTS/CTS / Software Xon/Xoff

Data Bits / Parity / Stop Bits

Read only.

5.3.10 PCI Subsystem Settings



Above 4G Decoding

Enables or Disables 64bit capable Devices to be Decoded in Above 4G Address Space (Only if System Supports 64 bit PCI Decoding).

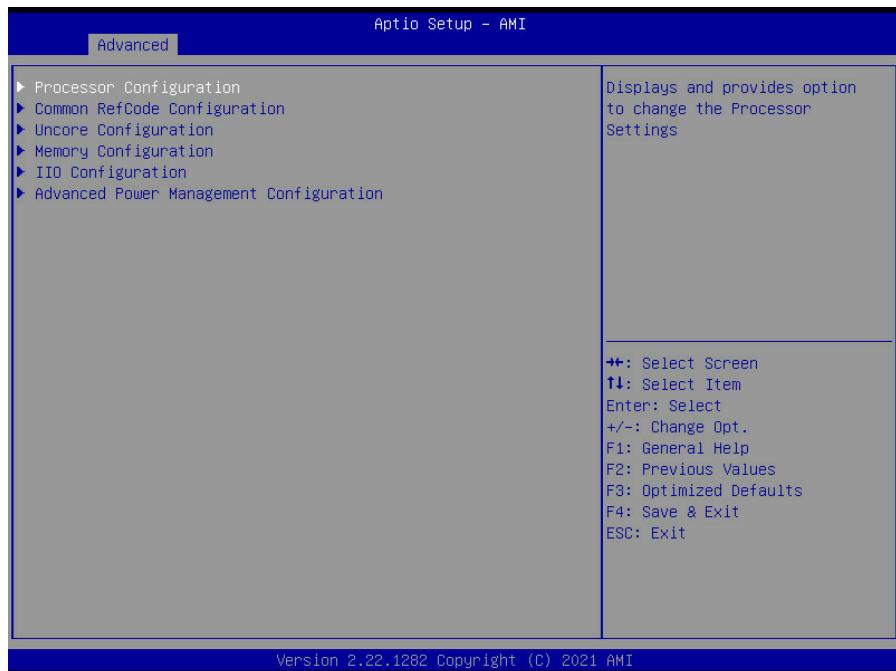
Enable / Disable

SR-IOV Support

If system has SR-IOV capable PCIe Devices, this option Enables or Disables Single Root IO Virtualization Support.

Enable / Disable

5.3.11 Socket Configuration



Processor Configuration

Displays and provides option to change the Processor Settings.

Common RefCode Configuration

Displays and provides option to change the Common RefCode Settings.

Uncore Configuration

Displays and provides option to change the Uncore settings

Memory Configuration

Displays and provides option to change the Memory Settings.

IIO Configuration

Displays and provides option to change the IIO Settings.

Advanced Power Management Configuration

Displays and provides option to change the Power Management Settings.

5.3.11.1 Processor Configuration



Hyper-Threading [All]

Enables Hyper Threading (Software Method to Enable/Disabled Logical Processor threads).

Disable / **Enable**

Enable Intel® TXT

Enable Intel® TXT.

Disable / Enable

Intel® Virtualization Technology

Intel® Virtualization Technology allows a platform to run multiple operating systems and applications in independent partitions. Note: A change to this option requires the system to be powered off and then back on before the setting takes effect.

Disable / **Enable**

Enable SMX

Enables Safer Mode Extensions.

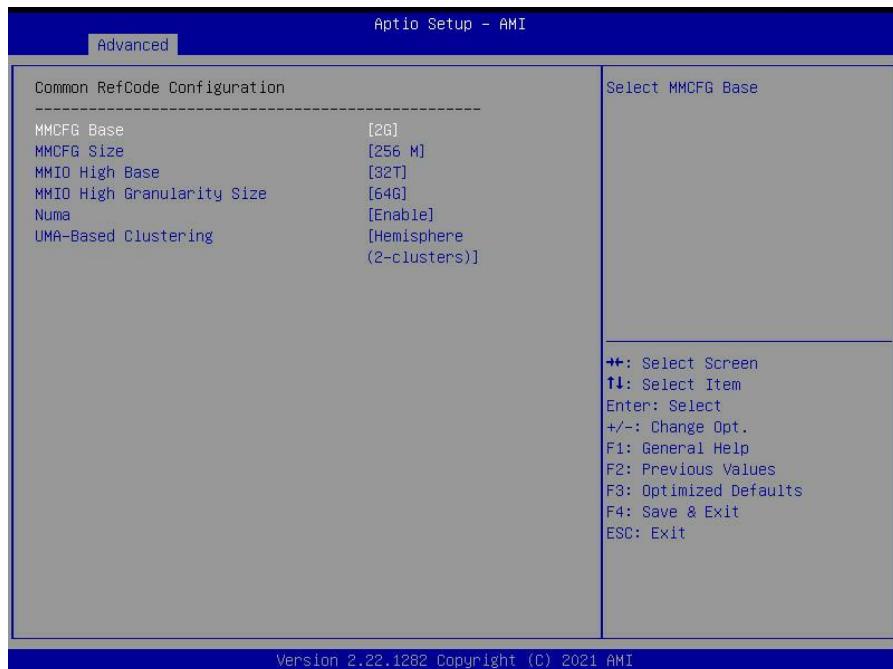
Disable / **Enable**

Total Memory Encryption (TME)

Enable/Disable Total Memory Encryption (TME)

Disable / **Enable**

5.3.11.2 Common RefCode Configuration



MMCFG Base

Select MMCFG Base.

1G / 1.5G / 1.75G / **2G** / 2.25G / 3G / Auto

MMCFG Size

Select MMCFG Size.

64M / 128M / **256M** / 512M / 1G / 2G / Auto

MMIO High Base

Select MMIO High Base.

56T / 40T / **32T** / 24T / 16T / 4T / 2T / 1T / 512G / 3584T

MMIO High Granularity Size

Selects the allocation size used to assign mmioh resources. Total mmioh space can be up to 32xgranularity.

Per stack mmioh resource assignments are multiples of the granularity where 1 unit per stack is the default allocation.

1G / 4G / 16G / **64G** / 256G / 1024G

Numa

Enable or Disable Non uniform Memory Access (NUMA).

Disable / **Enable**

UMA-Based Clustering

UMA Based Clustering options include Disable (ALL2ALL), Hemisphere (2 cluster), and Quadrant (4 cluster, not supported on ICX). These option are only valid when SNC is disabled. If SNC is enabled, UMA-Based Clustering is automatically disabled by BIOS.

Disable (All2 All) / **Hemisphere (2- clusters)**

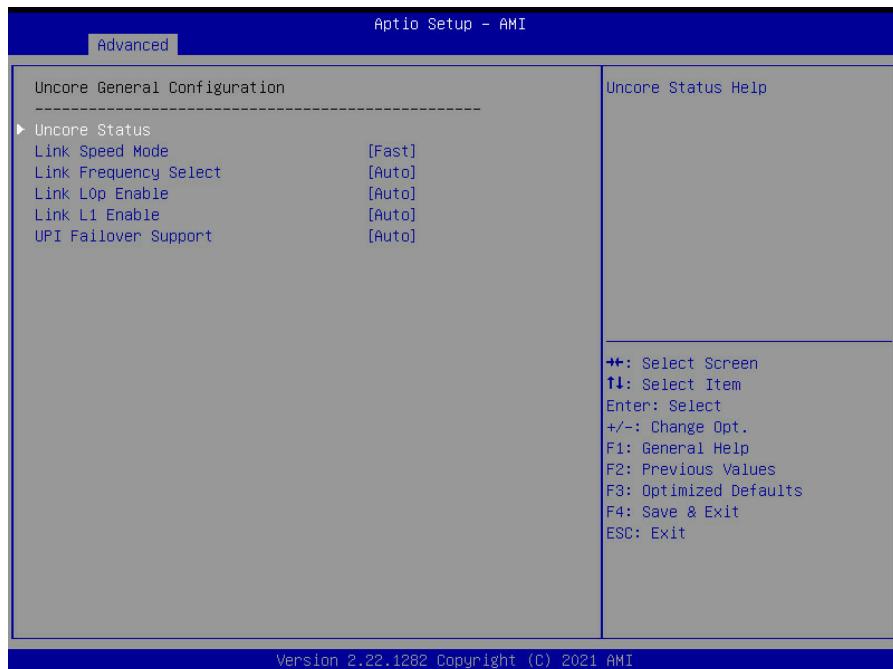
5.3.11.3 UPI Configuration



Uncore General Configuration

Displays and provides option to change the Uncore General Settings.

5.3.11.3.1 UPI General Configuration



Uncore Status

Uncore Status Help

Link Speed Mode

Select the UPI link speed as either the POR speed (Fast) or default speed (Slow).
Slow / **Fast**

Link Frequency Select

Allows for selecting the UPI Link Frequency.

9.6GT/s / 10.4GT/s / 11.2GT/s / **Auto** / Use Per Link Setting

Link L0p Enable

Enable --- Set the c_l0p_en,

Disable --- Reset it,

Auto --- Auto decides based on Si Compatibility.

Disable / Enable / **Auto**

Link L1 Enable

Enable --- Set the c_l1_en,

Disable --- Reset it,

Auto --- Auto decides based on Si Compatibility.

Disabled / Enable / **Auto**

UPI Failover Support

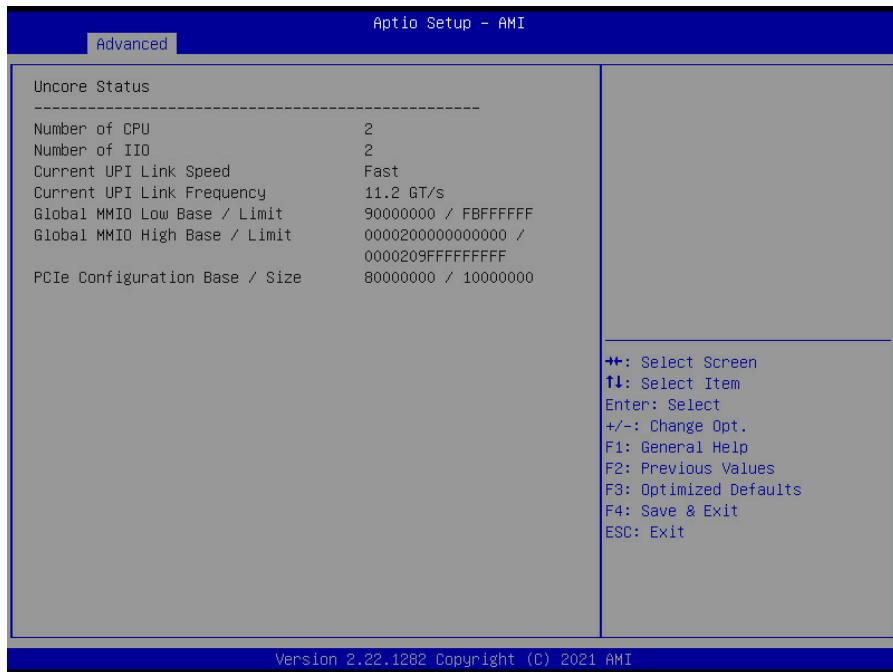
Enable - Set the c_failover_en,

Disable - Reset it,

Auto - Auto decides based on Si Compatibility

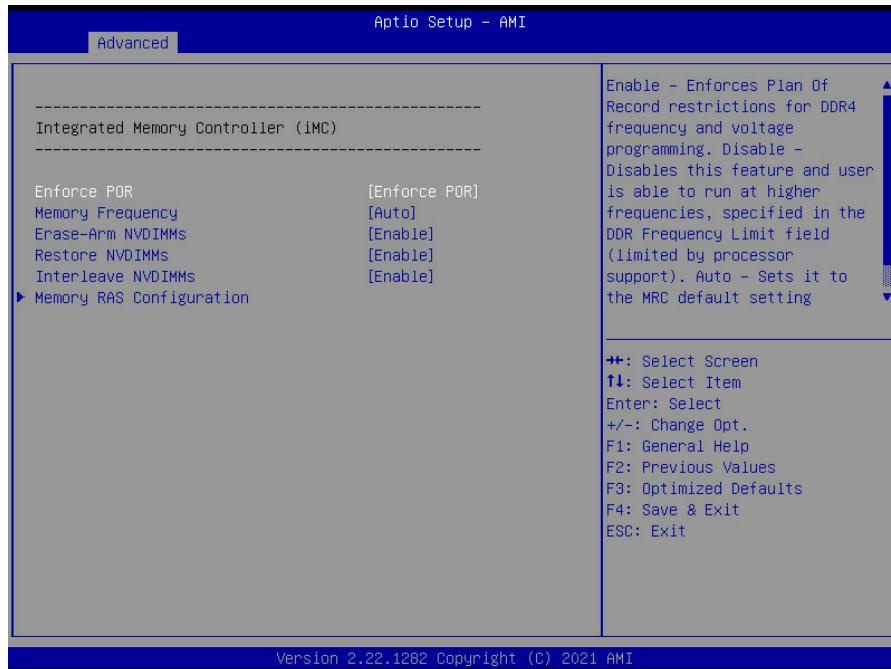
Disabled / Enable / Auto

5.3.11.3.1.1 Uncore Status



Read only

5.3.11.4 Memory Configuration



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Enforce POR

Enable --- Enforces Plan Of Record restrictions for DDR4 frequency and voltage programming. Disable --- disables this feature and user is able to run at higher frequencies, specified in the DDR Frequency Limit field (limited by processor support). Auto --- Sets it to the MRC default setting; current default is Enable.

Enforce POR / Disabled

Memory Frequency

Maximum Memory Frequency Selections in Mhz. If Enforce POR is disabled, user will be able to run at higher frequencies than the memory support (limited by processor support). Do not select Reserved.

Auto / 2400 / 2666 / 2933 / 3200

Erase-Arm NVDIMMs

Enables/Disables Erasing and Arming NVDIMMs.

Enabled / Disabled

Restore NVDIMMs

Enables/Disables automatic restoring of NVDIMMs.

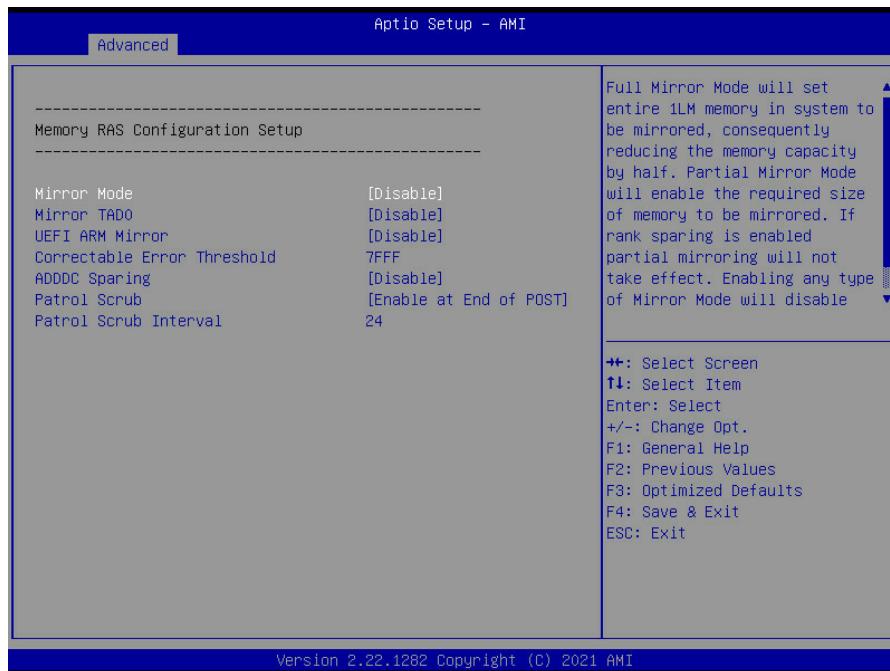
Enabled / Disabled

Interleave NVDIMMs

Controls if NVDIMMs are interleaved together or not.

Enabled / Disabled

5.3.11.4.1 Memory RAS Configuration



Mirror Mode

Full Mirror Mode will set entire 1LM memory in system to be mirrored, consequently reducing the memory capacity by half. Partial Mirror Mode will enable the required size of memory to be mirrored. If rank sparing is enabled partial mirroring will not take effect. Enabling any type of Mirror Mode will disable XPT Prefetch.

Disable / Full Mirror Mode / Partial Mirror Mode

Mirror TADO

Enable Mirror on entire memory for TADO.

Enable / **Disable**

UEFI ARM Mirror

Imitate behavior of UEFI based Address Range Mirror with setup option

Enable / **Disable**

Correctable Error Threshold

Correctable Error Threshold (0x01 – 0x7fff) used for sparing, tagging, and leaky bucket.

10

ADDDC Sparing

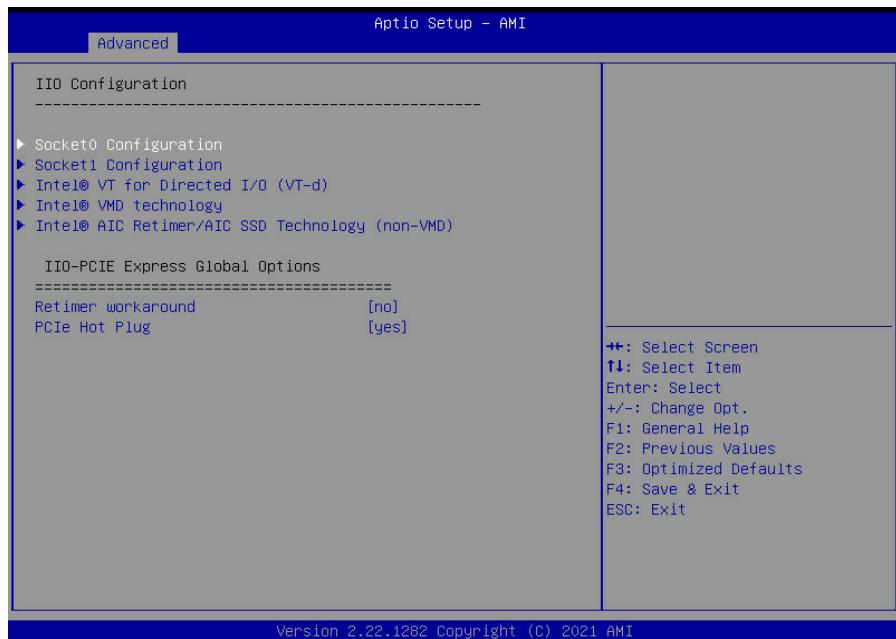
Enable/Disable ADDDC Sparing

Enable / **Disable****Patrol Scrub**

Enable/Disable Patrol Scrub.

Disabled / Enabled / **Enable at End of POST****Patrol Scrub Interval****24**

5.3.11.5 IIO Configuration



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Socket0 Configuration

Socket0 Parameters

Socket1 Configuration

Socket1 Parameters

Intel® VT for Directed I/O (VT-d)

Press <Enter> to bring up the Intel® VT for Directed I/O (VT-d) Configuration menu.

Intel® VMD Technology

Press <Enter> to bring up the Intel® VMD for Volume Management Device Configuration menu.

Intel® AIC Retimer/AIC SSD Technology (non-VMD)

Press <Enter> to bring up the Intel® AIC Retimer/AIC SSD Configuration menu.

Retimer workaround

Enable or disable the retime workaround

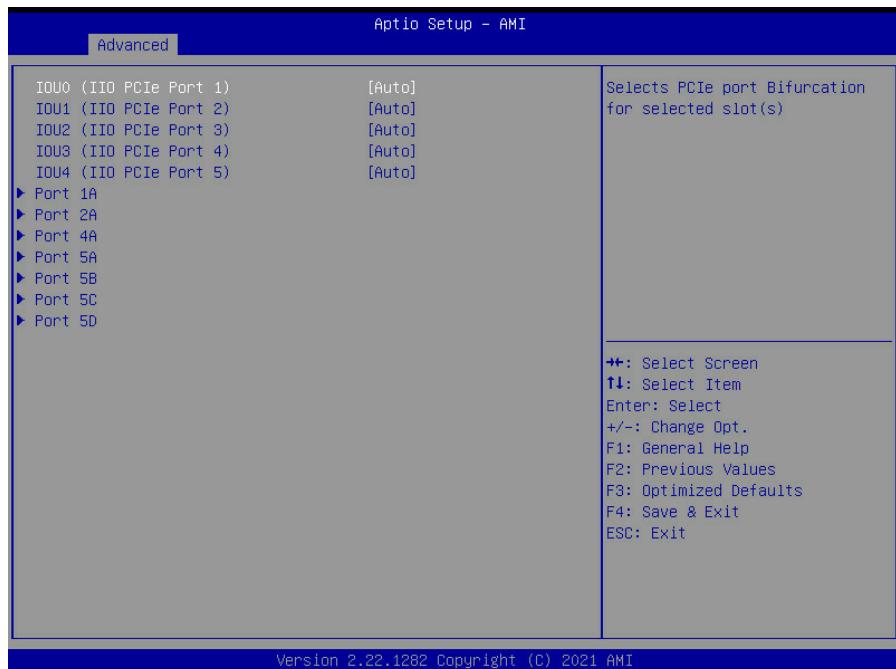
no / yes

PCIe Hot Plug

Enable/Disable PCIe Hot Plug globally.

no / yes

5.3.11.5.1 Socket 0 Configuration



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IOU0 (IIO PCIe Port 1)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU1 (IIO PCIe Port 2)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU2 (IIO PCIe Port 3)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU3 (IIO PCIe Port 4)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU4 (IIO PCIe Port 5)

Selects PCIe port Bifurcation for selected slot(s).

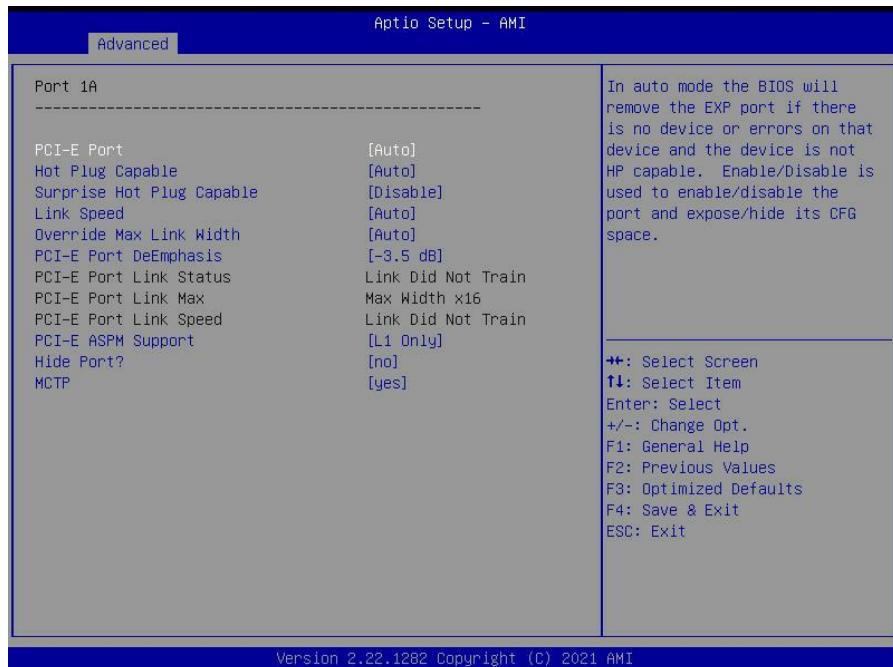
Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

Port 1A/2A/4A/5A/5B/5C/5D

Settings related to PCI Express Ports

(0/1A/1B/1C/1D/2A/2B/2C/2D/3A/3B/3C/3D/4A/4B/4C/4D/5A/5B/5C/5D).

5.3.11.5.1.1 Port 1A/2A/4A/5A/5B/5C/5D



PCI-E Port

In auto mode the BIOS will remove the EXP port if there is no device or errors on that device and the device is not HP capable. Disable is used to disable the port and hide its CFG space.

Auto / Disable / Enable

Hot Plug Capable

This option specifies if the link is considered Hot Plug capable.

Auto / Disable / Enable

Surprise Hot Plug Capable

This option specifies if the link is considered Hot Plug capable.

Disable / Enable

Link Speed

Choose Link Speed for this PCIe port.

Auto / Gen1 (2.5 GT/s) / Gen2 (5 GT/s) / Gen3 (8 GT/s) / Gen4 (16 GT/s)

Override Max Link Width

Override the max link width that was set by bifurcation.

Auto / x1 / x2 / x4 / x8 / x16

PCI-E Port DeEmphasis

De-Emphasis control (LNKCON2[6]) for this PCIe port.

-6.0 dB / **-3.5 dB**

PCI-E ASPM Support

This option enables/disables the ASPM (L1) support for the downstream devices.

Auto / **L1 Only** / Disabled

Hide Port?

User can force to hide this root port from OS.

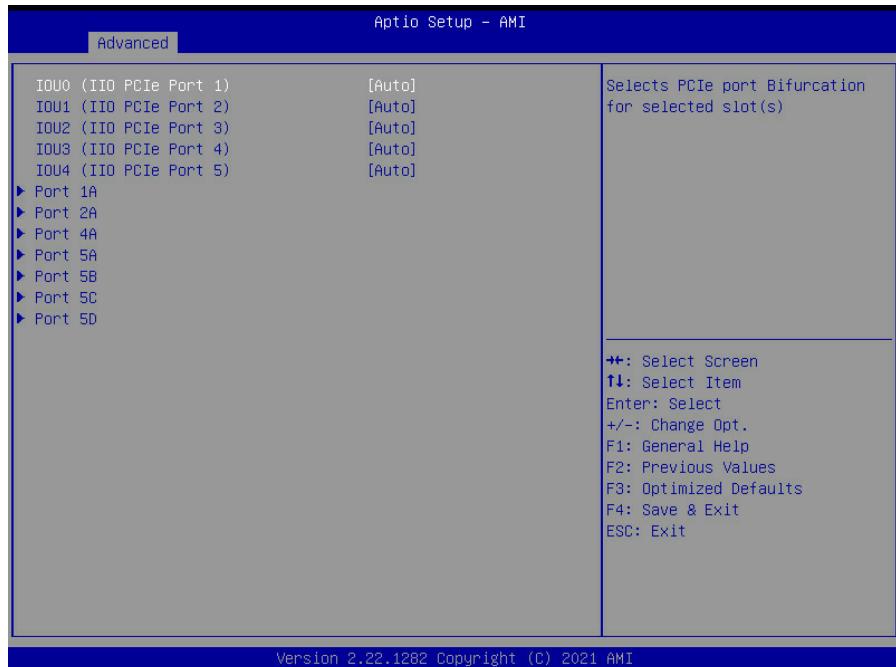
no / yes

MCTP

Enable/Disable MCTP

no / **yes**

5.3.11.5.2 Socket 1 Configuration



IOU0 (IIO PCIe Port 1)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU1 (IIO PCIe Port 2)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU2 (IIO PCIe Port 4)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU3 (IIO PCIe Port 5)

Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

IOU4 (IIO PCIe Port 5)

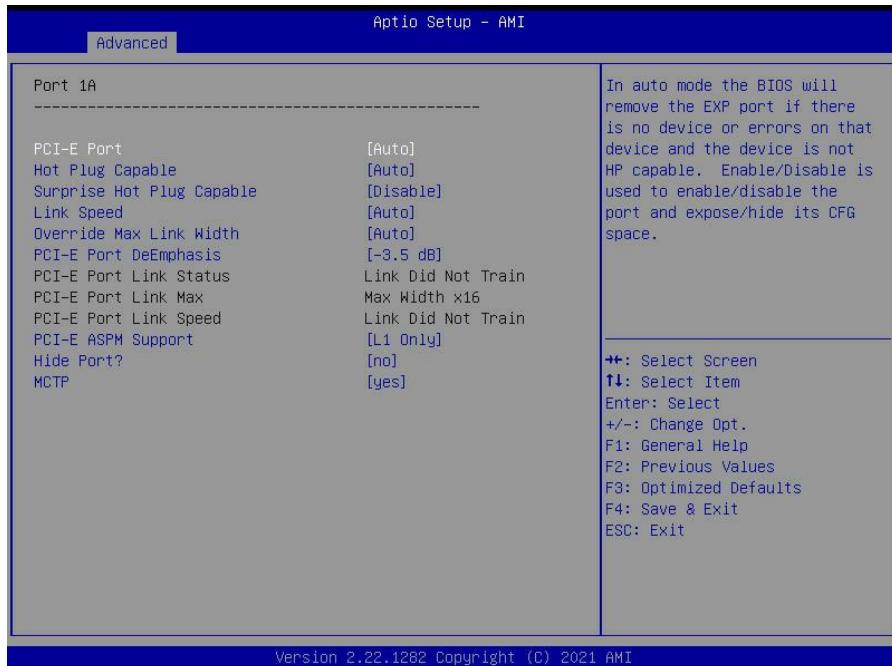
Selects PCIe port Bifurcation for selected slot(s).

Auto / x4x4x4x4 / x4x4x8 / x8x4x4 / x8x8 / x16

Port 1A/2A/4A/5A/5B/5C/5D

Settings PCIe ports Bifurcation for selected slot(s)

5.3.11.5.2.1 Port 1A/2A/4A/5A/5B/5C/5D



PCI-E Port

In auto mode the BIOS will remove the EXP port if there is no device or errors on that device and the device is not HP capable. Disable is used to disable the port and hide its CFG space.

Auto / Disable / Enable

Hot Plug Capable

This option specifies if the link is considered Hot Plug capable.

Auto / Disable / Enable

Surprise Hot Plug Capable

This option specifies if the link is considered Hot Plug capable.

Disable / Enable

Link Speed

Choose Link Speed for this PCIe port.

Auto / Gen1 (2.5 GT/s) / Gen2 (5 GT/s) / Gen3 (8 GT/s) / Gen4 (16 GT/s)

Override Max Link Width

Override the max link width that was set by bifurcation.

Auto / x1 / x2 / x4 / x8 / x16

PCI-E Port DeEmphasis

De-Emphasis control (LNKCON2[6]) for this PCIe port.

-6.0 dB / **-3.5 dB**

PCI-E ASPM Support

This option enables/disables the ASPM (L1) support for the downstream devices.

Auto / **L1 Only** / Disabled

Hide Port?

User can force to hide this root port from OS.

no / yes

MCTP

Enable/Disable MCTP

no / **yes**

5.3.11.5.3 Intel® VT for Directed I/O (VT-d)



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Intel® VT for Directed I/O (VT-d)

Enable/Disable Intel® Virtualization Technology for Directed I/O (VT-d) by reporting the I/O device assignment to VMM through DMAR ACPI Tables.

Disable / **Enable**

DMA Control Opt-In Flag

Enable/Disable DMA_CTRL_FLATFORM_OPT_IN_FLAG in DMAR table in ACPI. Not compatible with Direct Device Assignment (DDA).

Enable / **Disable**

Interrupt Remapping

Enable/Disable VT_D Interrupt Remapping Support
Auto / Enable / Disable

X2APIC Opt Out

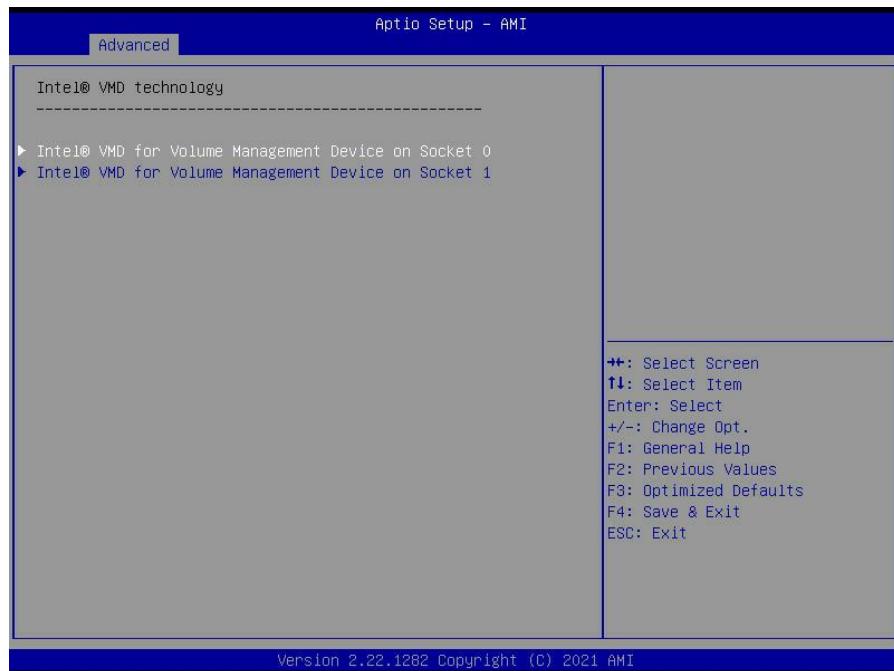
Enable/Disable x2APIC_OPT_OUT bit
Enable / **Disable**

Pre-boot DMA Protection

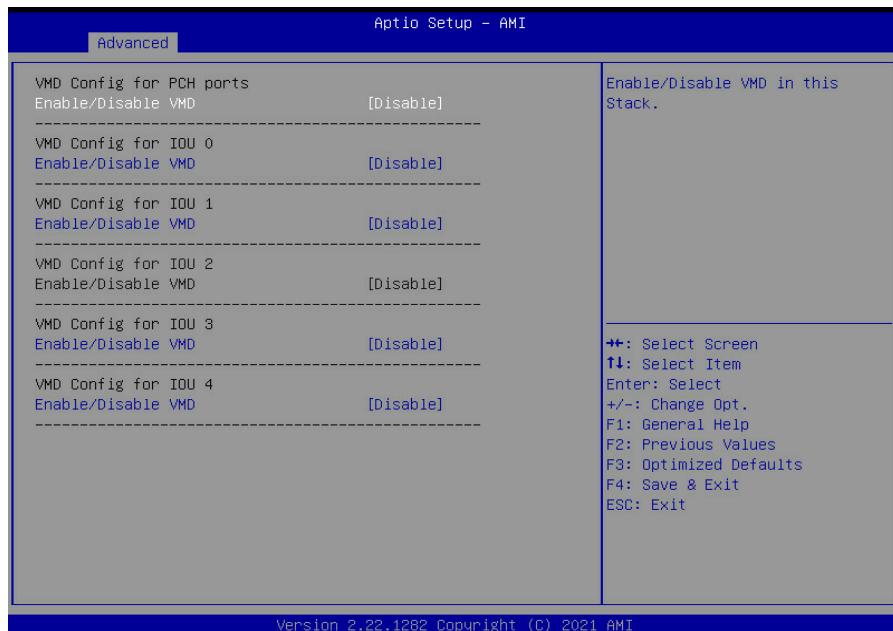
Enable DMA Protection in Pre-boot environment (If DMAR table is installed in DXE and If VTD_INFO_PPT is installed in PEI.)

Enable / **Disable**

5.3.11.5.4 Intel® VMD Technology



5.3.11.5.4.1 Intel VMD for Volume Management for Socket 0



VMD Config for PCH ports

Enable/Disable VMD
Disable / Enable

VMD Config for IOU0

Enable/Disable VMD
Disable / Enable

VMD Config for IOU1

Enable/Disable VMD
Disable / Enable

VMD Config for IOU2

Enable/Disable VMD
Disable / Enable

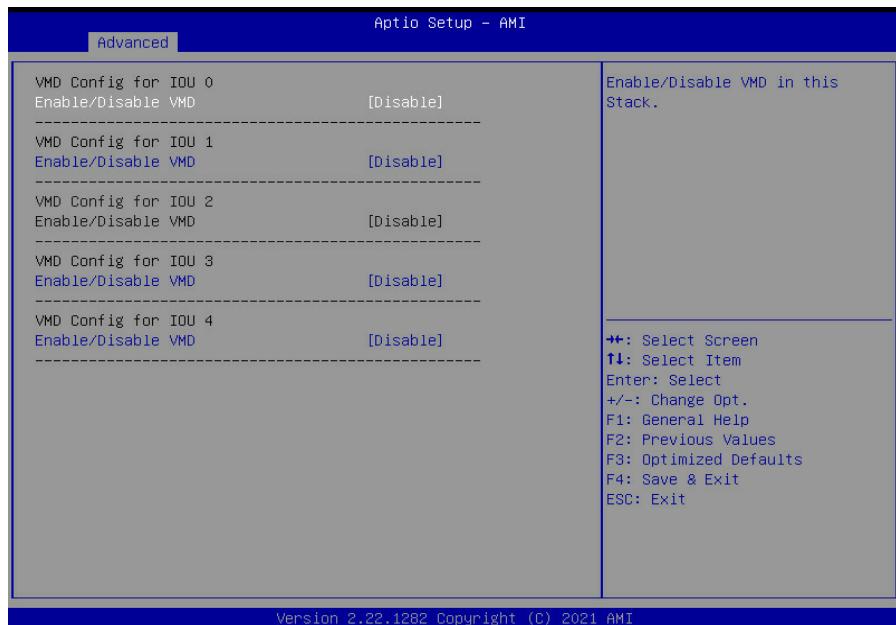
VMD Config for IOU3

Enable/Disable VMD
Disable / Enable

VMD Config for IOU4

Enable/Disable VMD
Disable / Enable

5.3.11.5.4.2 Intel VMD for Volume Management for Socket 1



VMD Config for IOU0

Enable/Disable VMD

Enable/Disable VMD in this Stack.

Disable / Enable

VMD Config for IOU1

Enable/Disable VMD

Enable/Disable VMD in this Stack.

Disable / Enable

VMD Config for IOU2

Enable/Disable VMD

Read only.

VMD Config for IOU3

Enable/Disable VMD

Enable/Disable VMD in this Stack.

Disable / Enable

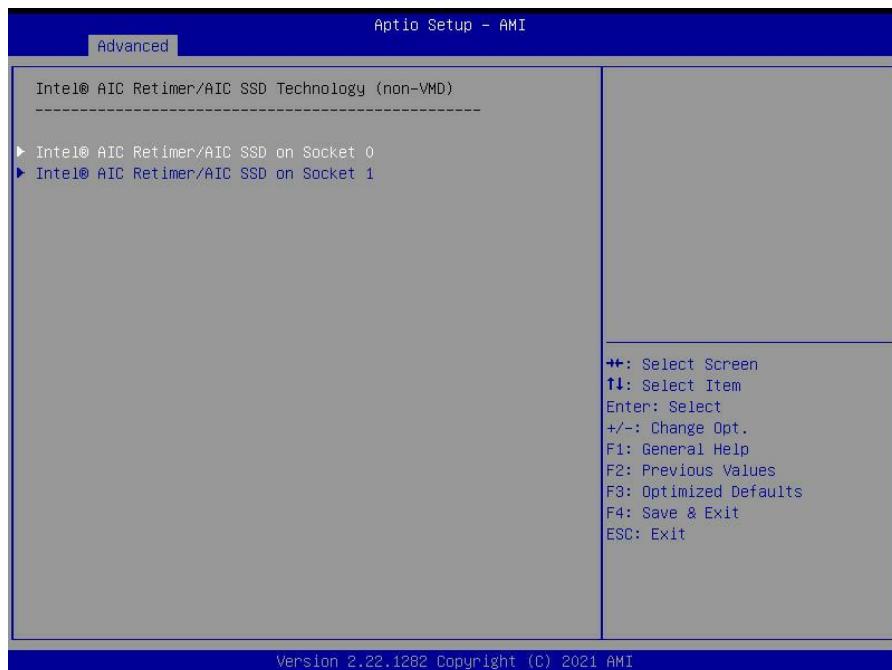
VMD Config for IOU4

Enable/Disable VMD

Enable/Disable VMD in this Stack.

Disable / Enable

5.3.11.5.5 Intel® AIC Retimer/AIC Technology (non-VMD)



5.3.11.5.5.1 Intel® AIC Retimer/AIC SSD on Socket0



Intel® AIC Retimer/AIC SSD HW at Stack1

Announce Intel® AIC Retimer/AIC SSD HW at Stack1(Port1A-1D). Override IOUx bifurcation if required

Disable / Enable

Intel® AIC Retimer/AIC SSD HW at Stack2

Announce Intel® AIC Retimer/AIC SSD HW at Stack2(Port2A-2D). Override IOUx bifurcation if required

Disable / Enable

Intel® AIC Retimer/AIC SSD HW at Stack3

Announce Intel® AIC Retimer/AIC SSD HW at Stack3(Port3A-3D). Override IOUx bifurcation if required

Disable / Enable

Intel® AIC Retimer/AIC SSD HW at Stack4

Announce Intel® AIC Retimer/AIC SSD HW at Stack4(Port4A-4D). Override IOUx bifurcation if required

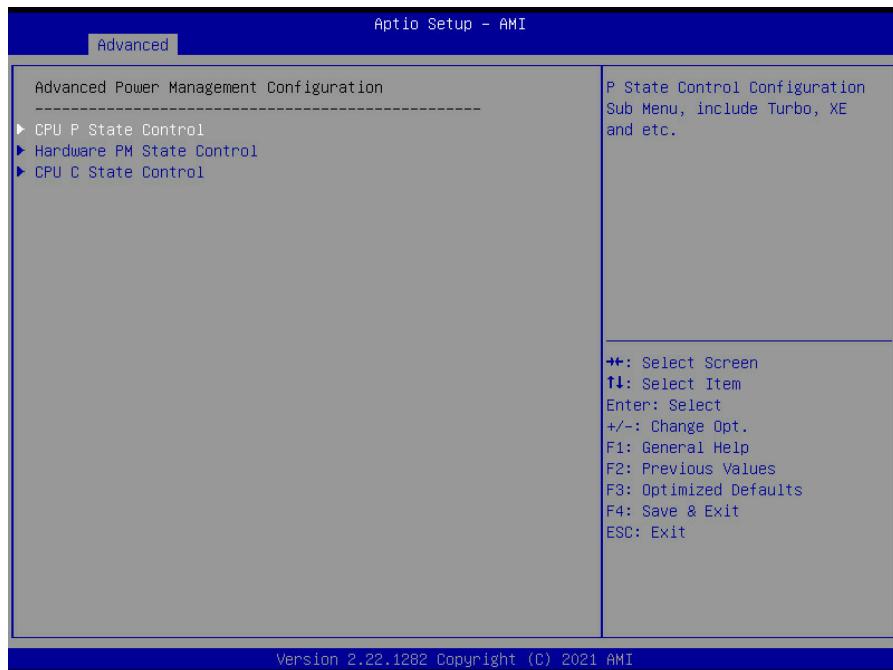
Disable / Enable

Intel® AIC Retimer/AIC SSD HW at Stack5

Announce Intel® AIC Retimer/AIC SSD HW at Stack5(Port5A-5D). Override IOUx bifurcation if required

Disable / Enable

5.3.11.6 Advanced Power Management Configuration



CPU P State Control

P State Control Configuration Sub Menu, include Turbo, XE and etc.

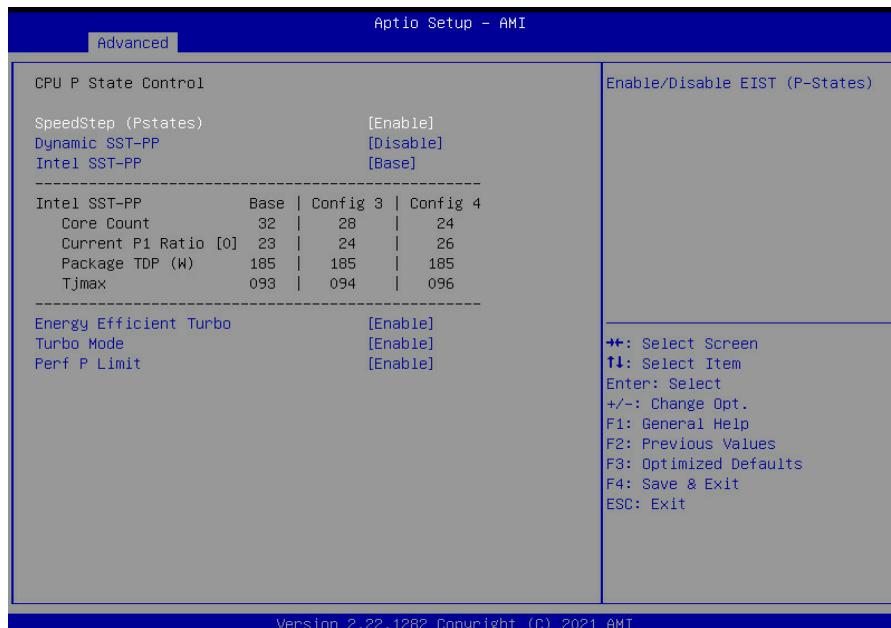
Hardware PM State Control

Hardware P-State setting.

CPU C State Control

CPU C State setting.

5.3.11.6.1 CPU P State Control



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SpeedStep (Pstates)

Enable/Disable EIST (P-States).

Disable / **Enable**

Dynamic SST-PP

Support Dynamic SST-PP Select

Disable / Enable

Intel SST-PP

Support Dynamic SST-PP select

Disable / Enable

Energy Efficient Turbo

Energy Efficient Turbo Disable, MSR 0x1FC [19].

Enable / Disable

Turbo Mode

Enable/Disable processor Turbo Mode (requires EMTTM enabled too).

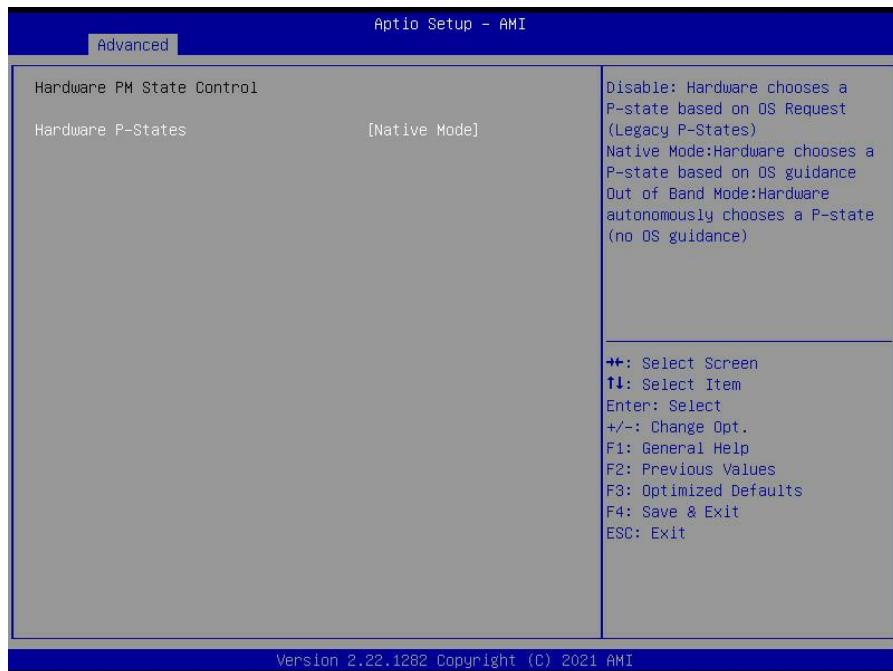
Disable / **Enable**

Perf P Limit

Enable/Disable Performance P-Limit.

Disable / **Enable**

5.3.11.6.2 Hardware PM State Control



Hardware P-States

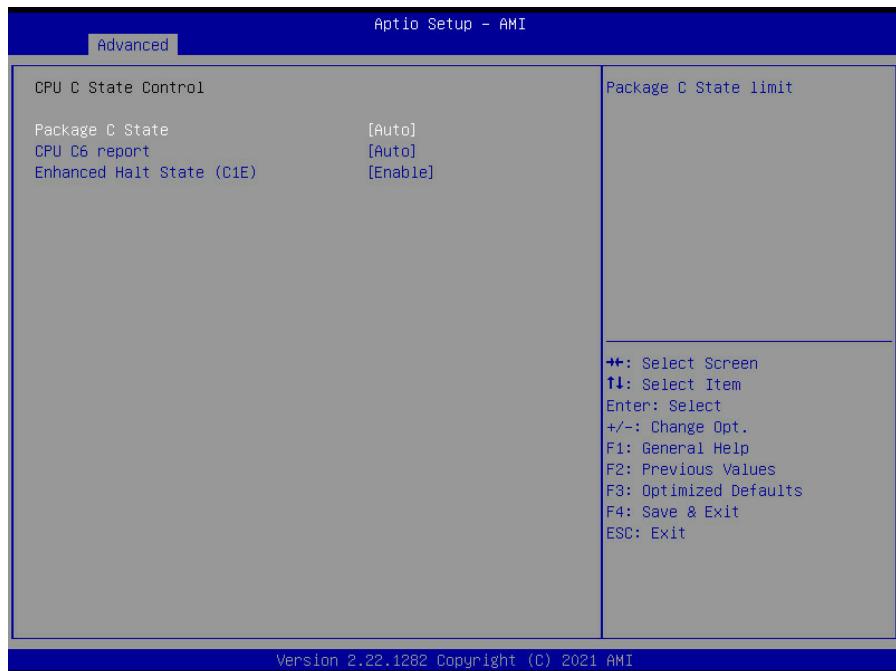
Disable: Hardware chooses a P-state based on OS Request (Legacy P-States).

Native Mode: Hardware chooses a P-state based on OS guidance.

Out of Band Mode: Hardware autonomously chooses a P-state (no OS guidance).

Disable / **Native Mode** / Out of Band Mode / Native Mode with No Legacy Support

5.3.11.6.3 CPU C State Control



Package C State

Package C State limit.

C0/C1 state / C2 state / C6 (non Retention) state / C6(Retention) state / **Auto**

CPU C6 report

Enable/Disable CPU C6 (ACPI C3) report to OS.

Disable or 0-80 (Ref 100)
Disabled / Enabled / **Auto**

Enhanced Halt State (C1E)

Enhanced Wait State (C1E)

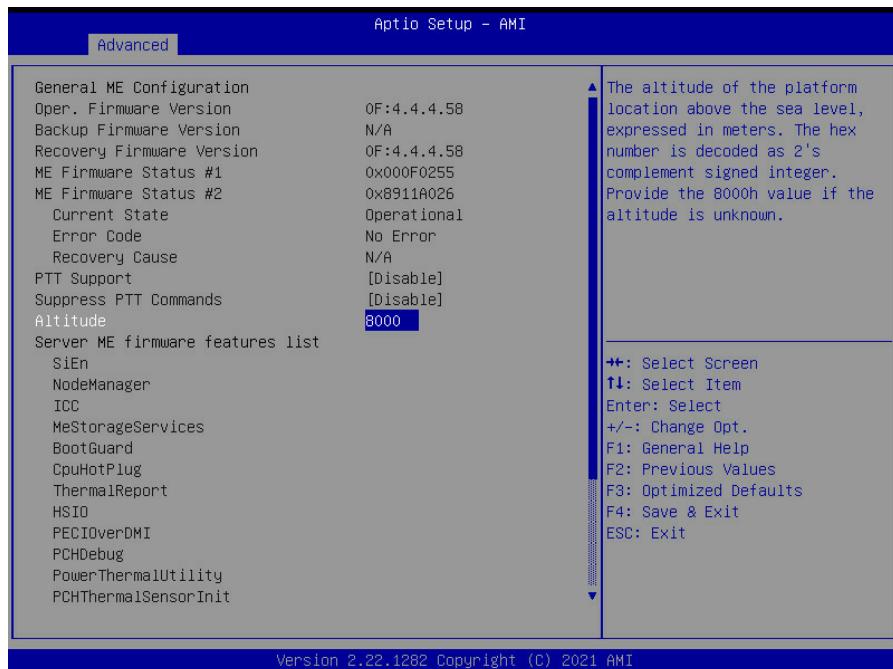
Enable auto promotion
Disable / Enable

5.3.12 Memory Topology



Read only.

5.3.13 Server ME Configuration



Altitude

The altitude of the platform location above the sea level, expressed in meters. The hex number is decoded as 2's complement signed integer. Provide the 8000h value if the altitude is unknown.

8000

5.3.14 SATA Configuration



SATA Configuration

SATA devices and settings.

sSATA Configuration

sSATA devices and settings.

5.3.14.1 SATA Configuration



SATA Controller

Enable or Disable SATA Controller.

Disable / **Enable**

Configure SATA as

Identify the SATA port is connected to Solid State Drive or Hard Disk Drive.

AHCI / RAID

Support Aggressive Link Power Management

Enables/Disables SALP.

Disable / **Enable**

Port 0/1/2/3/4/5/6/7

Enable or Disable SATA Port.

Disable / **Enable**

Hot Plug

Designates this port as Hot Pluggable.

Disable / **Enable**

Configure as eSATA

Configures port as External SATA (eSATA).

Disable / Enable

Spin Up Device

If enabled for any of ports Staggered Spin Up will be performed and only the drives which have this option enabled will spin up at boot. Otherwise all drives spin up at boot.

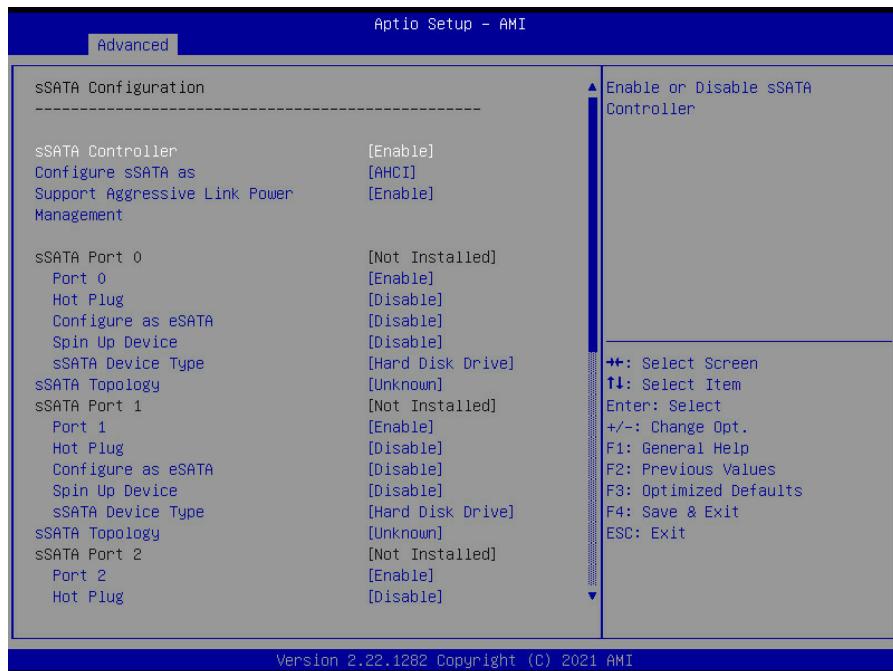
Disable / Enable

SATA Device Type

Identify the SATA port is connected to Solid State Drive or Hard disk Drive.

Hard Disk Drive / Solid State Drive

5.3.14.2 sSATA Configuration



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sSATA Controller

Enable or Disable sSATA Controller.

Disable / **Enable**

Configure sSATA as

Identify the sSATA port is connected to Solid State Drive or Hard Disk Drive.

AHCI / RAID

Support Aggressive Link Power Management

Enables/Disables SALP.

Disable / **Enable**

Port 0/1/2/3/4/5

Enable or Disable sSATA Port.

Disable / **Enable**

Hot Plug

Designates this port as Hot Pluggable.

Disable / Enable

Configure as eSATA

Configures port as External SATA (eSATA).

Disable / Enable

Spin Up Device

If enabled for any of ports Staggered Spin Up will be performed and only the drives which have this option enabled will spin up at boot. Otherwise all drives spin up at boot.

Disable / Enable

sSATA Device Type

Identify the SATA port is connected to Solid State Drive or Hard disk Drive.

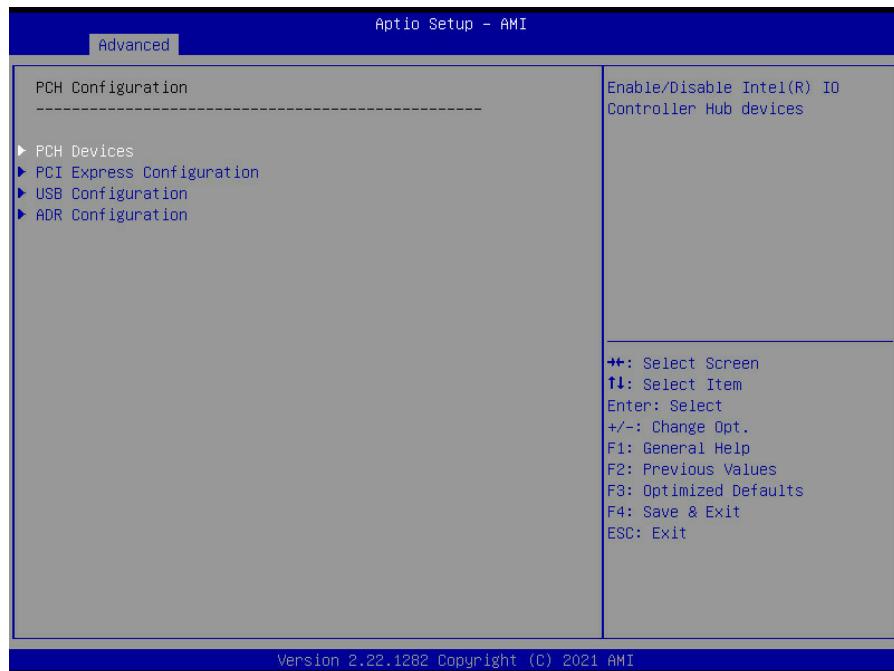
Hard Disk Drive / Solid State Drive

sSATA Topology

Identify the Secondary SATA Topology if it is Default or ISATA or Flex or DirectConnect or M2.

Unknown / ISATA / Direct Connect / Flex / M2

5.3.15 PCH Configuration



PCH Devices

Enable/Disable Intel® IO Controller Hub devices.

PCI Express Configuration

PCI Express Configuration settings.

USB Configuration

USB Configuration Settings.

ADR Configuration

Automatic DIMM Refresh (ADR) Configuration.

5.3.15.1 PCH Devices

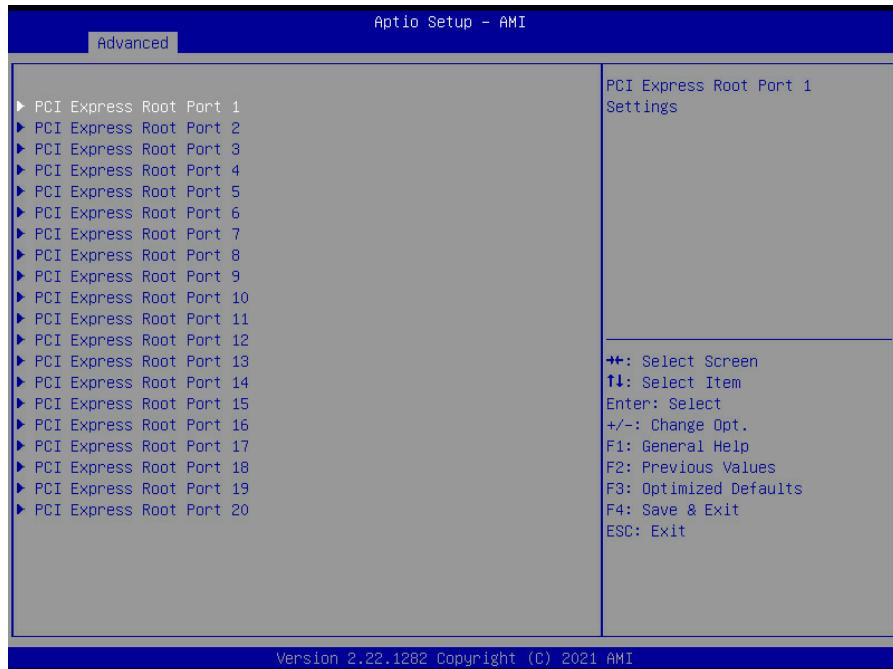


Restore AC Power Loss

Select S0/S5 for ACPI state after a G3.

Power On / Power Off / **Last State**

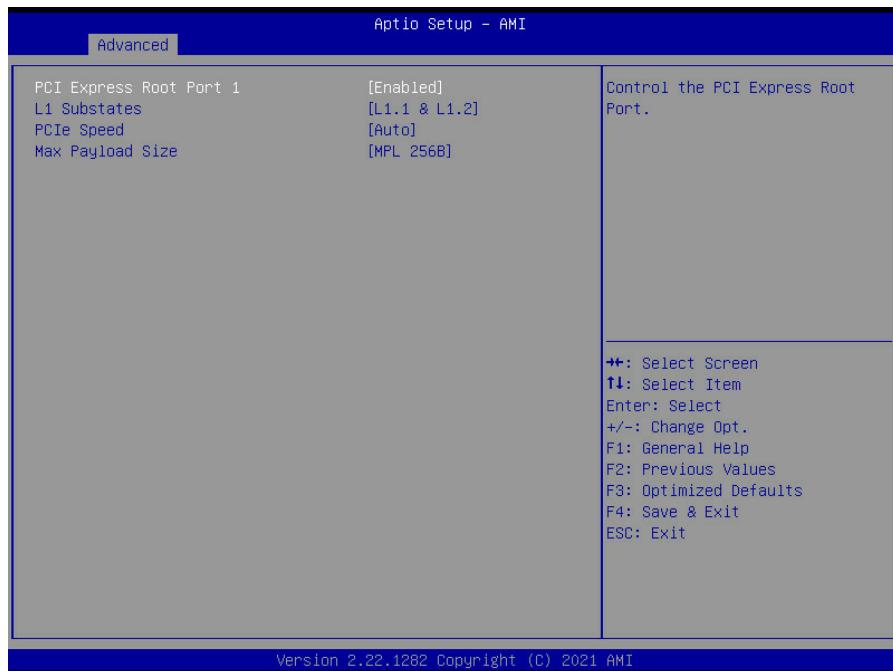
5.3.15.2 PCI Express Configuration



PCI Express Root Port 1~20

PCI Express Root Port 1~20 Settings.

5.3.15.2.1 PCI Express Root Port 1 ~ 20



PCI Express Root Port 1~20

Control the PCI Express Root Port.

Disabled / **Enabled**

NOTE: When PCI Express Root Port 1 has set to [Enabled], the following items Will be available to set up.

L1 Substates

PCI Express L1 Substates settings.

Disable / L1.1 / L1.2 / **L1.1 & L1.2**

PCIe Speed

Configure PCIe Speed.

Auto / Gen1 / Gen2 / Gen3

Max Payload Size

PCIE Max Payload Size Selection.

MPL128B / **MPL256B**

5.3.15.3 USB Configuration



XHCI Idle L1

Enable XHCI Idle L1. Disable to workaround USB3 hot plug will fail after 1 hot plug removal. Please put the system to G3 for the new settings to take effect.

Disable / **Enable**

5.3.15.4 ADR Configuration



Enable/Disable ADR

Enable or disable Automatic DIMM Refresh (ADR). This is not available if eADR is enabled since eADR requires ADR to be enabled.

Platform-POR / Enable / Disable

ADR GPIO

Select between GPIO_B or GPIO_C.

GPIO_B / **GPIO_C**

Host Partition Reset ADR Enable

Enables/Disables ADR on Host Partition Reset.

Platform-POR / Enable / Disable

Enable/Disable ADR Timer

Held-off for DEBUG PURPOSES ONLY!.

Platform-POR / Enable / Held-off

ADR timer expire time

Select proper ADR timer value: 25uS, 50uS, 100uS or 0.

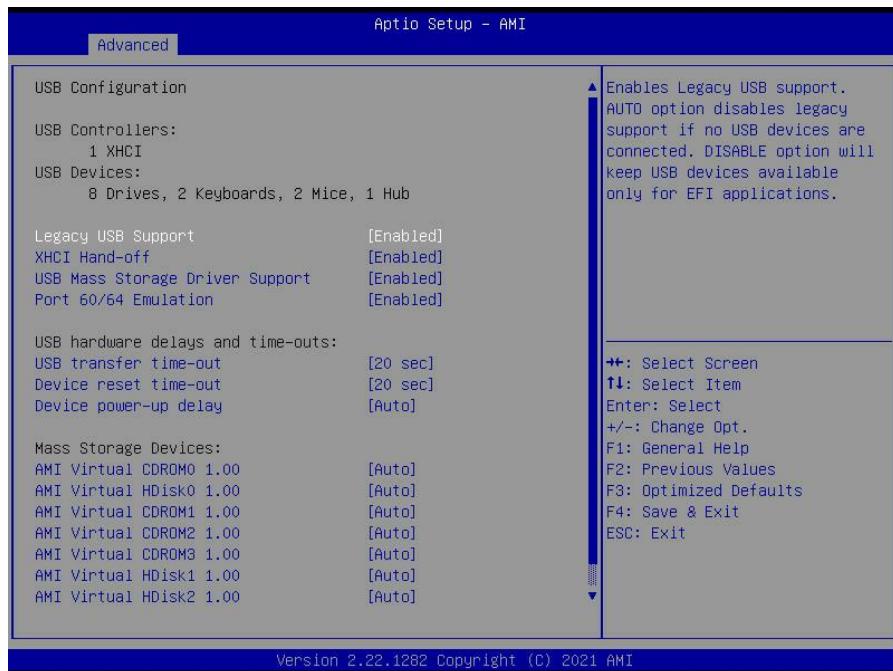
Platform-POR / 25 uS / 50 uS / 100 uS / 0 us

ADR timer multiplier

Select proper ADR timer multiplier: x1, 8, 24, 40, 56, 64, 72, 80, 88, 96.

Platform-POR / x1 / x8 / x24 / x40 / x56 / x64 / x72 / x80 / x88 / x96

5.3.16 USB Configuration



Legacy USB Support

Enables USB legacy support. AUTO option disables legacy support if no USB devices are connected. DISABLE option will keep USB devices available only for EFI applications.

Disabled / **Enabled** / Auto

XHCI Hand-off

This is a workaround for OSes without XHCI hand-off support. The XHCI ownership change should be claimed by XHCI driver.

Disabled / **Enabled**

USB Mass Storage Driver Support

Enable/Disable USB Mass Storage Driver Support.

Disabled / **Enabled**

Port 60/64 Emulation

Enables I/O Port 60h/64h emulation support. This should be enabled for the complete USB keyboard legacy support for non-USB aware OSes.

Disabled / **Enabled**

USB transfer time-out

The time-out value for Control, Bulk and Interrupt transfers.

1 sec / 5 sec / 10 sec / **20 sec**

Device reset time-out

USB mass storage device Start Unit command time-out.

10 sec / **20 sec** / 30 sec / 40 sec

Device power-up delay

Maximum time the device will take before it properly reports itself to the Host Controller. 'AUTO' uses default value: for a Root port it is 100 ms, for a Hub port the delay is taken from Hub descriptor.

Auto / Manual

NOTE: **Device power up delay in seconds** is available when **Device power-up delay** is set to [Manual].

AMI Virtual CDROM0/1/2/3 1.00

Mass storage device emulation type. 'AUTO' enumerates devices according to their media format. Optical drives are emulated as 'CDROM', drives with no media will be emulated according to a drive type.

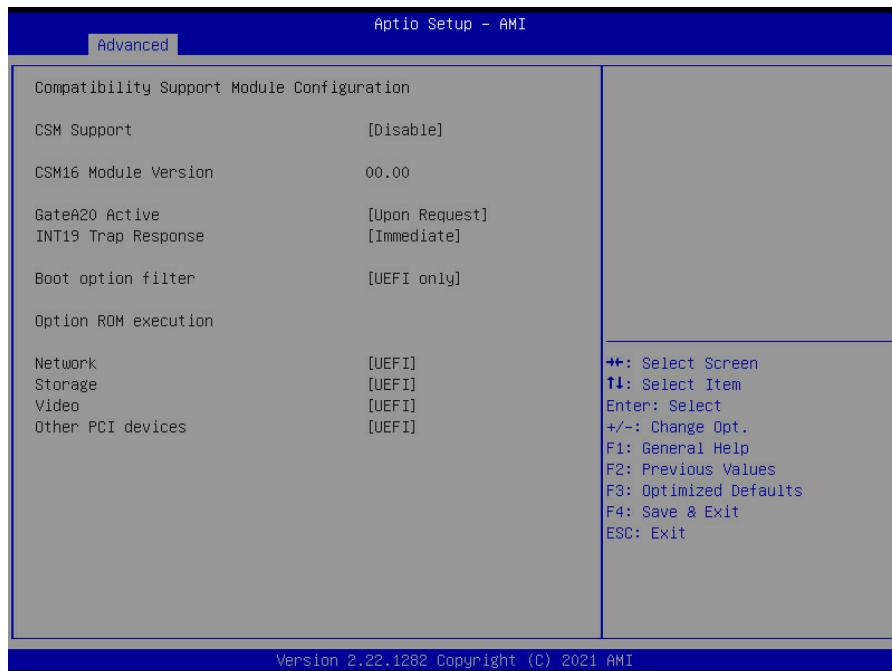
Auto / Floppy / Forced FDD / Hard Disk / CD-ROM

AMI Virtual HDisk0/1/2/3 1.00

Mass storage device emulation type. 'Auto' enumerates devices according to their media format. Optical drives are emulated as 'CDROM', drives with no media will be emulated according to a drive type.

Auto / Floppy / Forced FDD / Hard Disk / CD-ROM

5.3.17 CSM Configuration



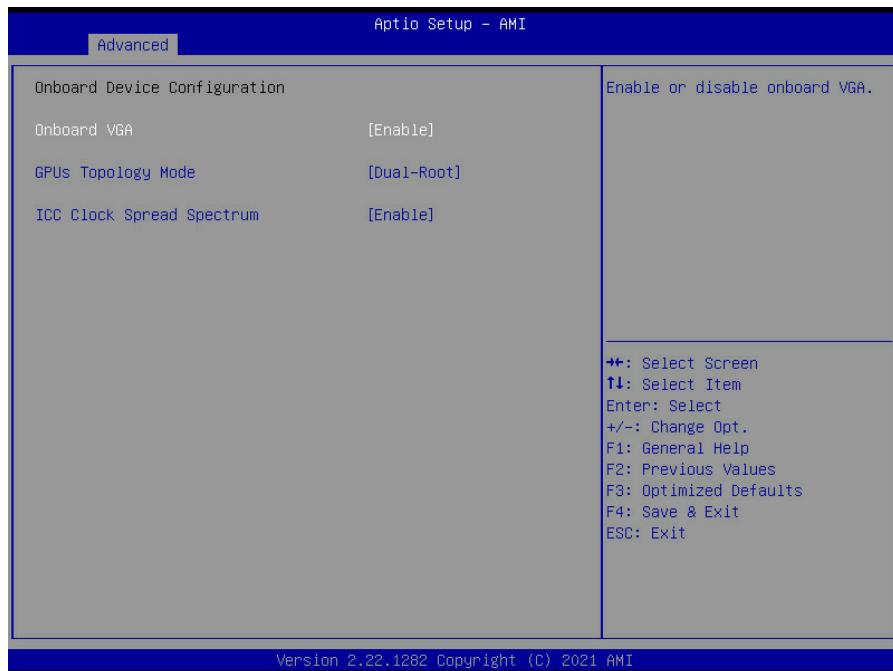
Only Read

5.3.18 NVMe Configuration



This page shows the Device Name you installed. Press Enter to read the device information. If no NVME device is installed, it shows no NVME device is found. Read only.

5.3.19 Onboard Device Configuration



Onboard VGA

Enable or disable onboard VGA.

Enable / Disable

GPUs Topology Mode

Single root means that all GPUs are connected to the same CPU, which is the CPU0. Dual-root means half of the GPUs are on CPU0 and the other half are attached to the CPU1.

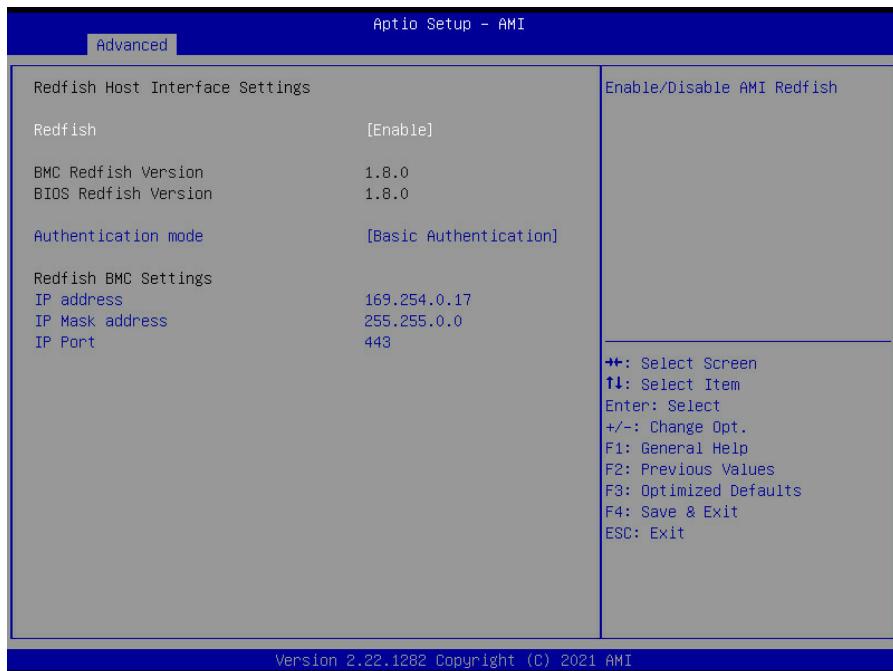
Single-Root / **Dual-Root**

ICC Clock Spread Spectrum

Turn on/off Spread Spectrum Setting for lsCLK.

Enable / Disable

5.3.20 Redfish Host Interface Configuration



Redfish Host Interface Settings

Enable/Disable AMI Redfish

Disable / **Enable**

NOTE: When Redfish Host Interface Settings set to [Enabled], the following items will appear.

Authentication mode

Select authentication mode

Basic Authentication / Session Authentication

IP Address

Enter IP address.

IP Mask Address

Enter IP Mask address.

IP Port

Enter IP Port.

5.3.21 Network Stack Configuration



NOTE: The BIOS will automatically read the onboard LAN controller.

Network Stack

Enable/Disable UEFI Network Stack.

Disable / **Enable**

NOTE: The following items are available when Network Stack is set to [Enable].

Ipv4 PXE Support

Enable Ipv4 PXE Boot Support. If disabled IPV4 PXE boot option will not be created.

Disable / Enable

Ipv4 HTTPS Support

Enable Ipv4 HTTP Boot Support. If disabled IPV4 HTTP boot option will not be created.

Disable / Enable

Ipv6 PXE Support

Enable Ipv6 PXE Boot Support. If disabled IPV6 PXE boot option will not be created.

Disable / Enable

Ipv6 HTTPS Support

Enable Ipv6 HTTP Boot Support. If disabled IPV6 HTTP boot option will not be created.

Disable / Enable

PXE boot wait time

Wait time in seconds to press ESC key to abort the PXE boot. Use either+/- or numeric keys to set the value.

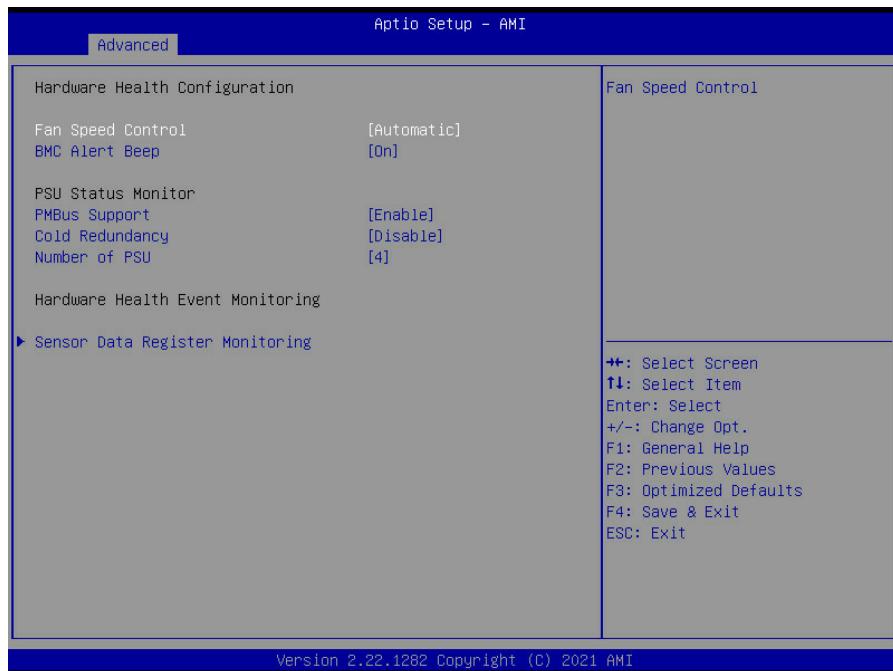
0

Media detect count

Number of times presence of media will be checked. Use either+/- or numeric keys to set the value.

5

5.3.22 Hardware Health Configuration



Fan Speed Control

Fan Speed Control.

Automatic / Manual / Full Speed

NOTE: Change the **Fan Speed Control** BIOS setting from [Manual] to [Full Speed] when installing the Nvidia GeForce / Quardro GPU and any VGA card.

PWM Minimal Duty Cycle

PWM Minimal Duty Cycle (%).

30

NOTE: This item is available when **Fan Speed Control** is set to [Manual].

BMC Alert Beep

Enable/Disable BMC Alert Beep.

On / Off

PMBus support

PMBus Support.

Enable / Disable

Cold Redundancy

Enabled or Disabled Advanced System Power Saving
Enable / **Disable**

Number of PSU

1 / 2 / 3 / **4**

5.3.22.1 Sensor Data Register Monitoring

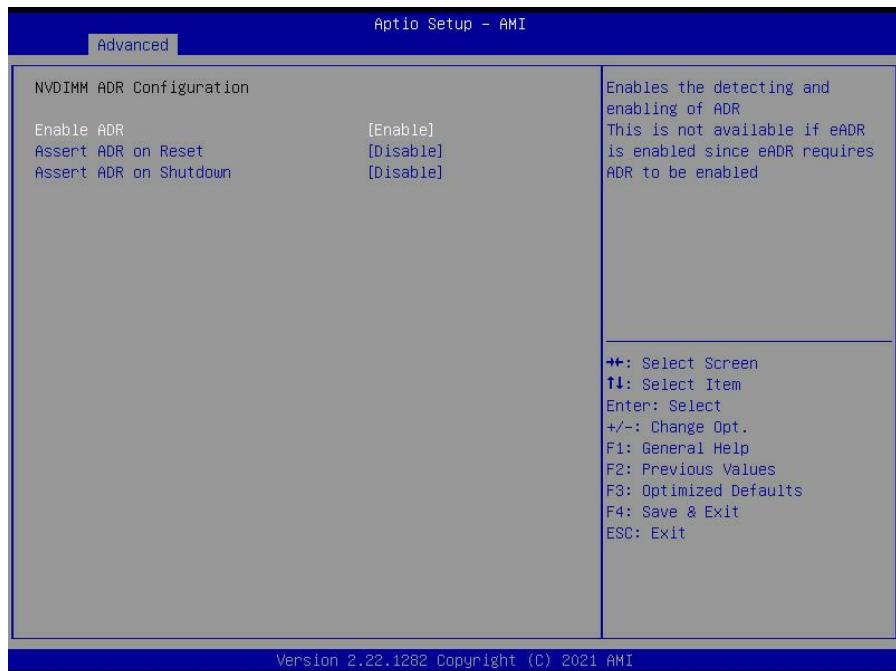
Aptio Setup - AMI				
Advanced				
PC Health Status				
ID#	NAME	READING	UNIT	STATUS
01	P0_Temp	: 54	°C	OK
02	P0_DTS_Margin	: -39		OK
03	P1_Temp	: 52	°C	OK
04	P1_DTS_Margin	: -41		OK
09	PCH_Temp	: 36	°C	OK
10	P0_MCO_DIM_CH_A	: N/A	°C	
11	P0_MCO_DIM_CH_B	: N/A	°C	
12	P0_MCO_DIM_CH_C	: N/A	°C	
13	P0_MCO_DIM_CH_D	: N/A	°C	
14	P0_MC1_DIM_CH_E	: N/A	°C	
15	P0_MC1_DIM_CH_F	: N/A	°C	
16	P0_MC1_DIM_CH_G	: 39	°C	OK
17	P0_MC1_DIM_CH_H	: N/A	°C	
18	P1_MCO_DIM_CH_A	: N/A	°C	
19	P1_MCO_DIM_CH_B	: N/A	°C	
1A	P1_MCO_DIM_CH_C	: N/A	°C	
1B	P1_MCO_DIM_CH_D	: N/A	°C	
1C	P1_MC1_DIM_CH_E	: N/A	°C	
1D	P1_MC1_DIM_CH_F	: N/A	°C	
1E	P1_MC1_DIM_CH_G	: N/A	°C	
1F	P1_MC1_DIM_CH_H	: N/A	°C	
20	P0_MOSFET	: 55	°C	OK

++: Select Screen
!!: Select Item
Enter: Select
+/-: Change Opt.
F1: General Help
F2: Previous Values
F3: Optimized Defaults
F4: Save & Exit
ESC: Exit

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NOTE: SDR cannot be modified. Read only.

5.3.23 NVDIMM ADR Configuration



Enable ADR

Enables the detecting and enabling of ADR. This is not available if eADR is enabled since eADR requires ADR to be enabled.

Enable / Disable

Assert ADR on Reset

Assert ADR on Reset.

Enable / Disable

Assert ADR on Shutdown

Assert ADR on Shutdown.

Enable / Disable

5.3.24 CPU Registration



Sign-Up the current CPU

This item support INTEL CPU, sign the CPU will record current CPU. Once BIOS checked different with registered CPU, show WARNING message on POST screen.

Deregistration / Sign-up / **Keep Current Status**

5.3.25 Memory Registration



Sign-up the current Memory

Sign the Memory will record current Memory. Once BIOS checked different with registered Memory, show WARNING message on POST screen.

Deregistration / Sign-up / **Keep Current Status**

5.3.26 T1s Auth Configuration



Server CA Configuration

Press <Enter> to configure Server CA.

Client Cert Configuration

Press <Enter> to configure Client Cert.

5.3.26.1 Server CA Configuration



Enroll Cert

Press <Enter> to enroll cert.

Delete Cert

Press <Enter> to delete cert.

5.3.25.1.1 Enroll Cert



Enroll Cert Using File

Enroll Cert Using File.

Cert GUID

Input digit character in 11111111-2222-3333-4444-1234567890ab format.

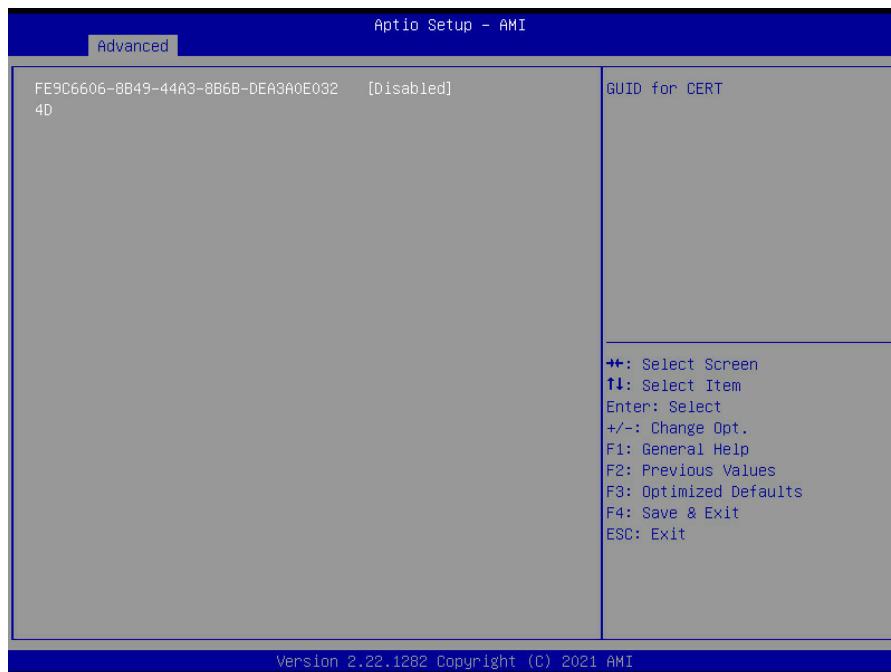
Commit Changes and Exit

Commit Changes and Exit.

Discard Changes and Exit

Discard Changes and Exit.

5.3.25.1.2 Delete Cert



FE9C6606-8B49-44A3-8B6B-DEA3A0E032

GUID for CERT.

Disabled / Enabled

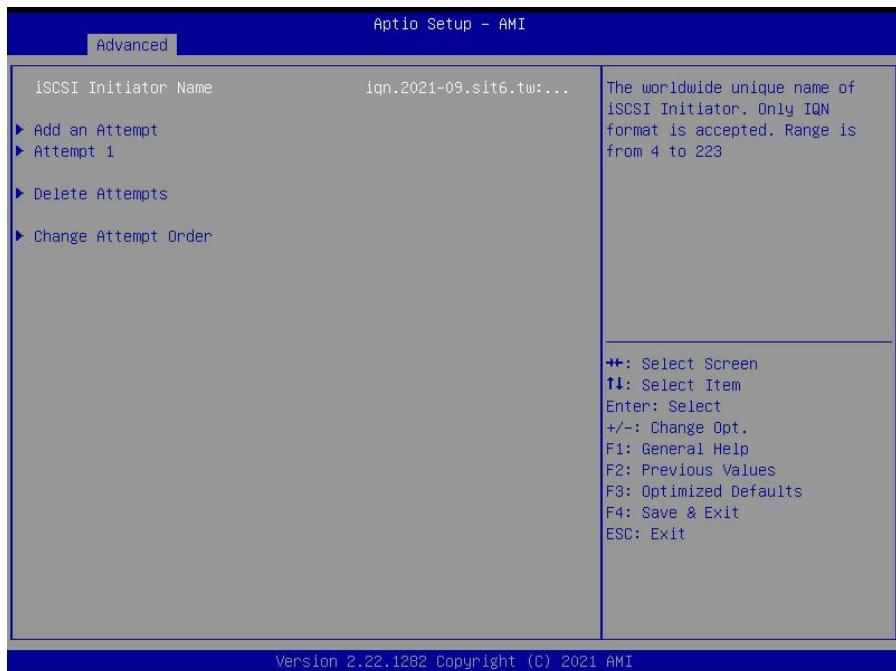
5.3.26 iSCSI Configuration



Host iSCSI Configuration

Host iSCSI Configuration

5.3.26.1 Host iSCSI Configuration



iSCSI Initiator Name

The worldwide unique name of iSCSI Initiator. Only IQN format is accepted. Enter [iqn.xxx]. xxx ranges from 4 to 223.

Add an Attempt

Add an Attempt.

Delete Attempts

Delete one or more attempts.

Change Attempt Order

Change the order of Attempts using +/- keys. Use arrow keys to select the attempt then press +/- to move the attempt up/down in the attempt order list.

5.3.26.1.1 Add an Attempt

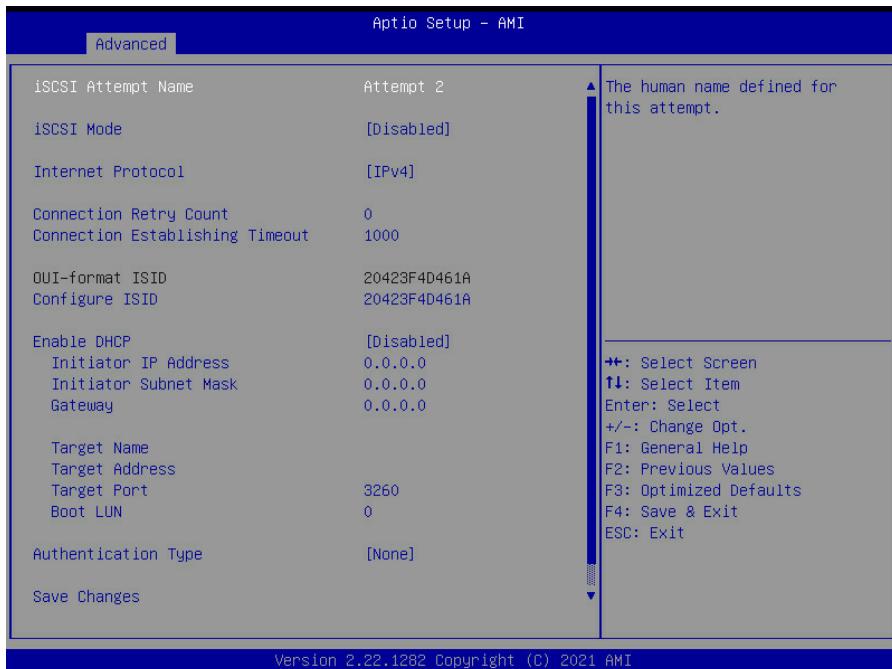


NOTE: Only LAN1 supports iSCSI function.

MAC xx:xx:xx:xx:xx:xx (Intel® I210 Gigabit Network Connection)

PFA: Bus 2 / Dev 0 / Func 0.

5.3.26.1.1.1 MAC xx:xx:xx:xx:xx:xx (Intel® I210 Gigabit Network Connection)



iSCSI Attempt Name

The human name defined for this attempt. Maximum length is up to 12 characters.

Attempt 2

iSCSI Mode

Disabled, Enabled, Enabled for MPIO.

Disabled / Enabled / Enabled for MPIO

Internet Protocol

Initiator IP address is system assigned in IP6 mode. In Autoconfigure mode, iSCSI driver will attempt to connect iSCSI target via IPv4 stack, if failed then attempt IPv6 stack.

IPv4 / IPv6 / Autoconfigure

Connection Retry Count

The minimum value is 0 and the maximum is 16. 0 means no retry.

Connection Establishing Timeout

The timeout value in milliseconds. The minimum value is 100 milliseconds and the maximum is 20 seconds.

Configure ISID

OUI-format ISID in 6 bytes, default value is derived from MAC address. Only last 3 bytes are configurable. Example: update 0ABBCCDDEEFF to OABBCCF07901 by input F07901.

Enable DHCP

Enable DHCP.

Disabled / Enabled

Initiator IP Address

Enter IP address in dotted-decimal notation.

Initiator Subnet Mask

Enter IP address in dotted-decimal notation.

Gateway

Enter IP address in dotted-decimal notation.

Target Name

The worldwide unique name of the target. Only iqn. format is accepted.

iqu. xxx

Target IP Address

Enter IP address in dotted-decimal notation.

Target Port

Target Port.

Boot LUN

Hexadecimal representation of the LU number. Examples are:
4752-3A4F-6b7e-3F99, 6734-9-156f-127, 4186-9.

Authentication Type

Authentication method: CHAP, Kerberos, or None.

CHAP / **None**

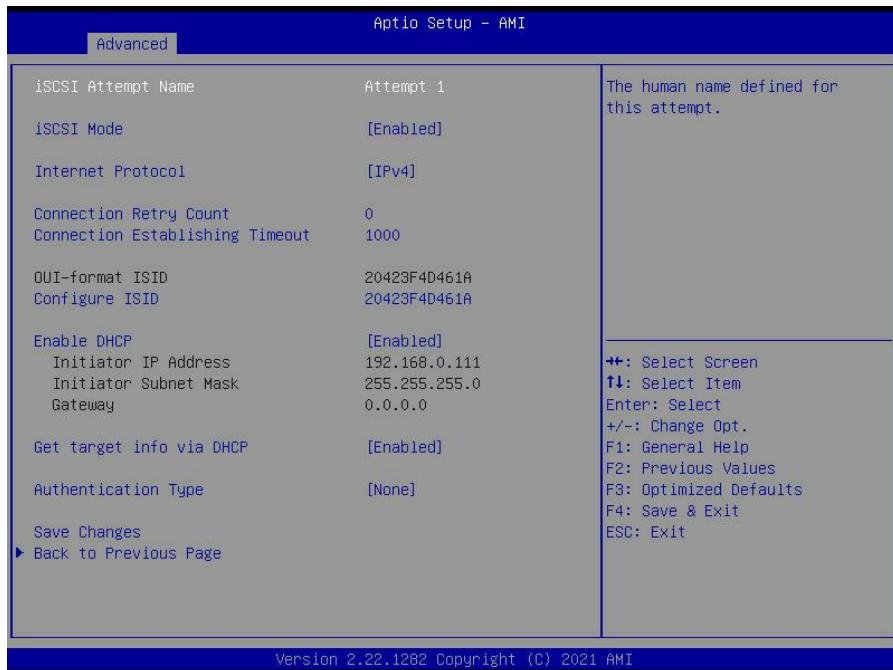
Save Changes

Must reboot system manually for changes to take place.

Back to Previous Page

Back to Previous Page.

5.3.26.1.2 Attempt 1



iSCSI Attempt Name

The human name defined for this attempt.

Attempt 1

iSCSI Mode

Disabled, Enabled, Enabled for MPIO.

Disabled / Enabled / Enabled for MPIO

Internet Protocol

Initiator IP address is system assigned in IP6 mode. In Autoconfigure mode, iSCSI driver will attempt to connect iSCSI target via IPv4 stack, if failed then attempt IPv6 stack.

IPv4 / IPv6 / Autoconfigure

Connection Retry Count

The minimum value is 0 and the maximum is 16. 0 means no retry.

Connection Establishing Timeout

The timeout value in milliseconds. The minimum value is 100 milliseconds and the maximum is 20 seconds.

Configure ISID

OUI-format ISID in 6 bytes, default value is derived from MAC address. Only last 3 bytes are configurable. Example: update 0ABBCCDDEEFF to OABBCCF07901 by input F07901.

Enable DHCP

Enable DHCP.

Disabled / Enabled

Initiator IP Address

Enter IP address in dotted-decimal notation.

Initiator Subnet Mask

Enter IP address in dotted-decimal notation.

Gateway

Enter IP address in dotted-decimal notation.

Get target info via DHCP

Get target info via DHCP

Authentication Type

Authentication method: CHAP, Kerberos, or None.

CHAP / **None**

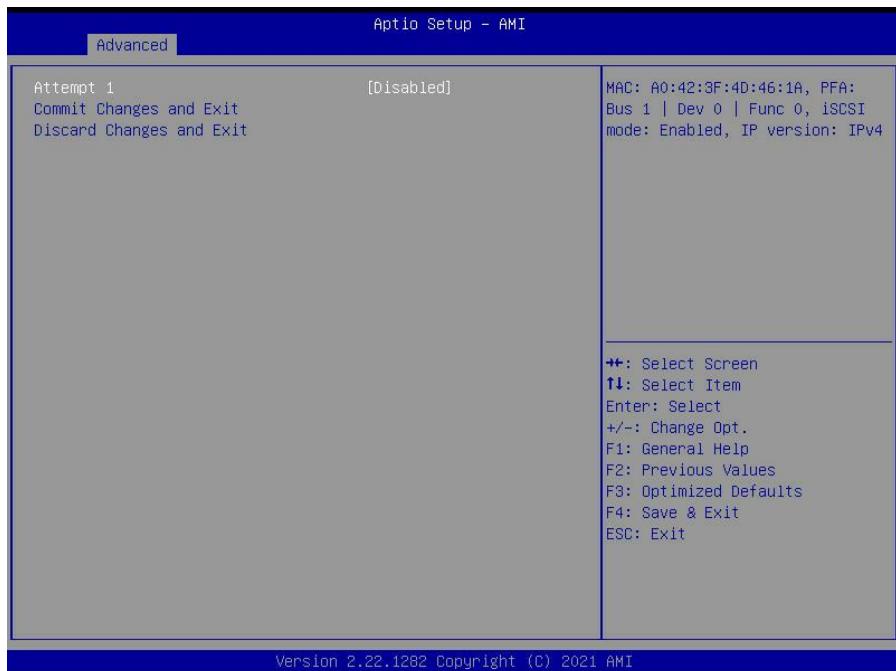
Save Changes

Must reboot system manually for changes to take place.

Back to Previous Page

Back to Previous Page.

5.3.26.1.3 Delete Attempts



Attempt 1

MAC xx:xx:xx:xx:xx:xx, PFA: Bus 2 / Dev 0 / Func 0, iSCSI mode: Disabled, IP version: IPv4.

Disabled / Enabled

Attempt 2

MAC xx:xx:xx:xx:xx:xx, PFA: Bus 2 / Dev 0 / Func 0, iSCSI mode: Disabled, IP version: IPv4.

Disabled / Enabled

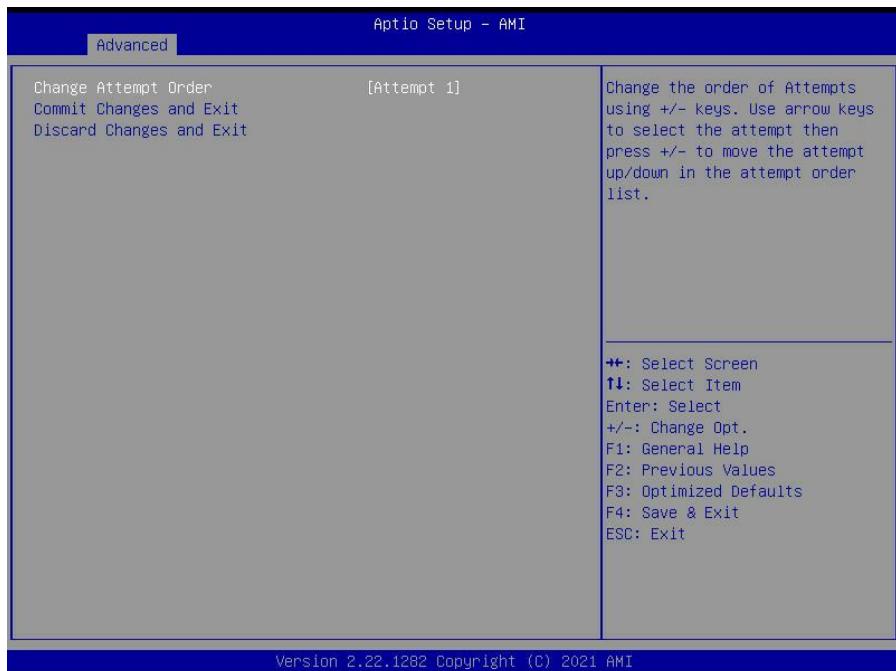
Commit Changes and Exit

Commit Changes and Exit.

Discard Changes and Exit

Discard Changes and Exit.

5.3.26.1.4 Change Attempt Order



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Change Attempt Order

Change the order of Attempts using +/- keys. Use arrow keys to select the attempt then press +/- to move the attempt up/down in the attempt order list.

Attempt 1

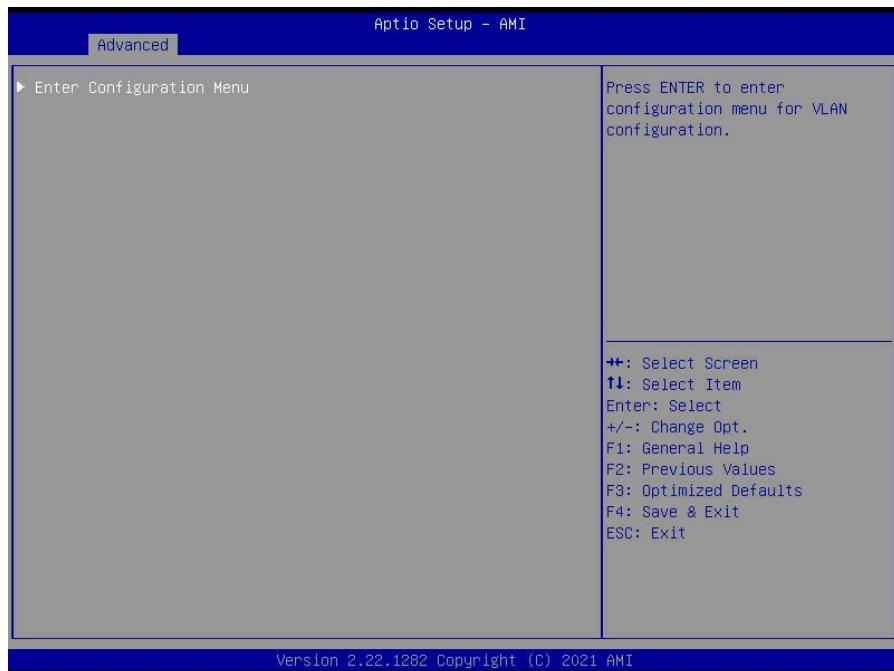
Commit Changes and Exit

Commit Changes and Exit.

Discard Changes and Exit

Discard Changes and Exit.

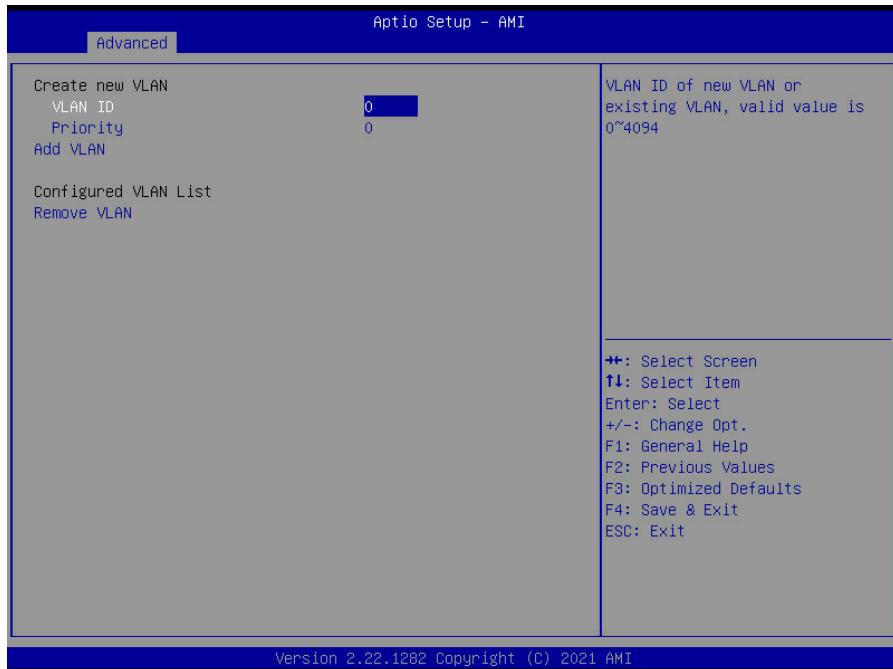
5.3.27 VLAN Configuration (MAC:xxxxxxxxxxxx)



Enter Configuration Menu

Press ENTER to enter configuration menu for VLAN configuration.

5.3.27.1 Enter Configuration Menu



VLAN ID

VLAN ID of new VLAN or existing VLAN, valid value is 0~4094.

Priority

802.1Q Priority, valid value is 0~7.

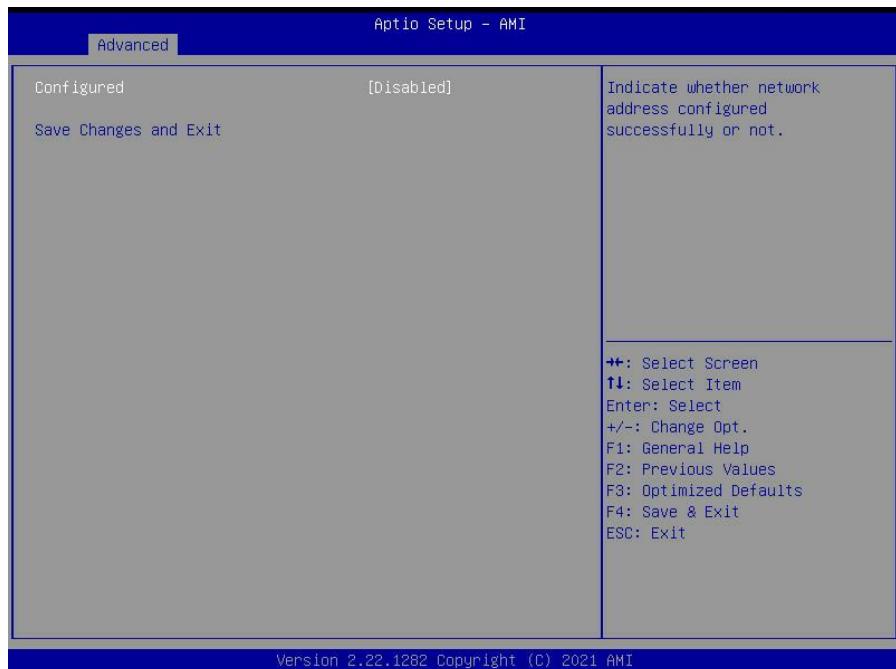
Add VLAN

Create a new VLAN or update existing VLAN.

Remove VLAN

Remove selected VLANs.

5.3.28 MAC:xxxxxxxxxx - IPv4 Network Configuration



Configured

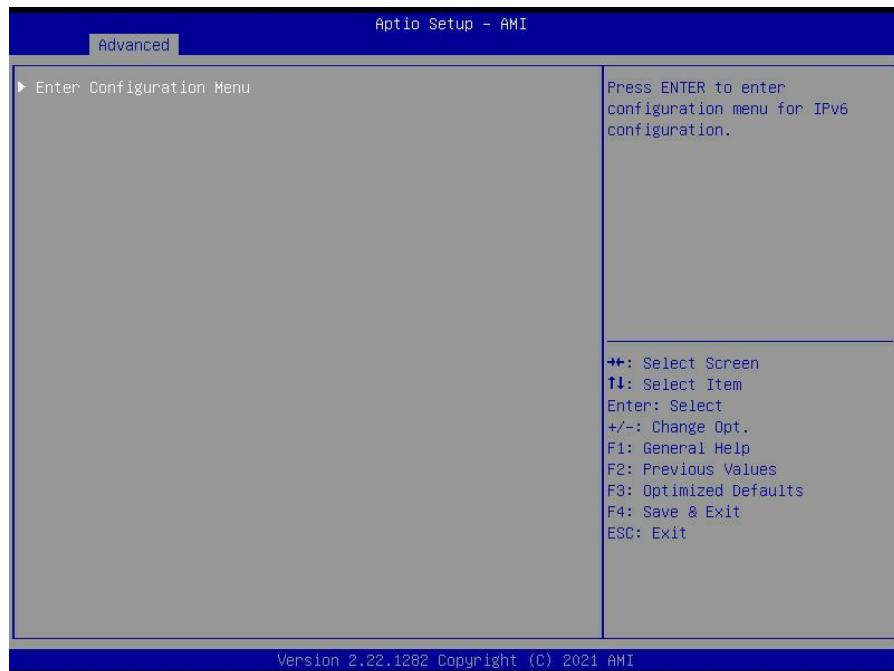
Indicate whether network address configured successfully or not.

Disabled / Enabled

Save Changes and Exit

Save Changes and Exit.

5.3.29 MAC:xxxxxxxxxxxx - IPv6 Network Configuration



Enter Configuration Menu

Press ENTER to enter configuration menu for IPv6 configuration.

5.3.29.1 Enter Configuration Menu



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Interface ID

The 64 bit alternative interface ID for the device. The string is colon separated, e.g. ff:dd:88:66:cc:1:2:3

xx:xx:x:xx:xx:xx:xx:xx

DAD Transmit Count

The number of consecutive Neighbor Solicitation messages sent while performing Duplicate Address Detection on a tentative address. A value of zero indicates that Duplicate Address Detection is not performed.

1

Policy

Automatic or manual.

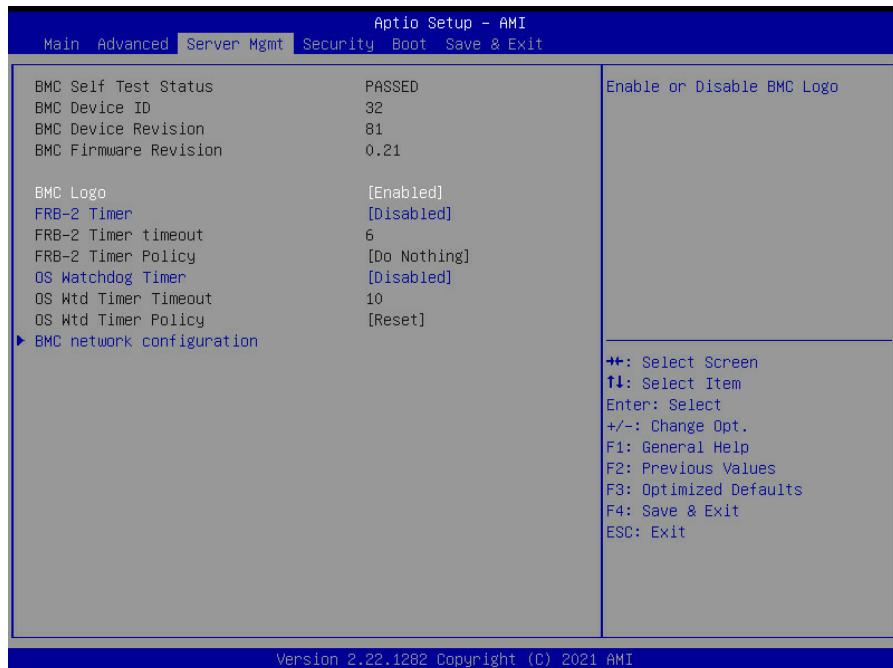
Automatic / Manual

NOTE: The **Advanced Configuration** submenu is available when **Policy** is set to [Manual].

Save Changes and Exit

Save Changes and Exit.

5.4 Server Management



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BMC Logo

Enable or Disable BMC Logo.

Enabled / Disabled

FRB-2 Timer

Enable or Disable FRB-2 timer (POST timer).

Enabled / **Disabled**

NOTE: **FRB-2 Timer timeout** and **FRB-2 Timer Policy** are available when **FRB-2 Timer** is set to [Enabled].

FRB-2 Timer timeout

Enter value Between 3 to 6 min for FRB-2 Timer Expiration value. Not available if FRB-2 Timer is disabled.

6

FRB-2 Timer Policy

Configure how the system should respond if the FRB-2 Timer expires. Not available if FRB-2 Timer is disabled.

Do Nothing / Reset / Power Down / Power Cycle

OS Watchdog Timer

If enabled, starts a BIOS timer which can only be shut off by Management Software after the OS loads. Helps determine that the OS successfully loaded or follows the OS Boot Watchdog Timer policy.

Enabled / **Disabled**

NOTE: OS Wtd Timer timeout and OS Wtd Timer Policy are available when **OS Watchdog Timer** is set to [Enabled].

OS Wtd Timer timeout

Configure the length of the OS Boot Watchdog Timer. Not available if OS Boot Watchdog timer is disabled.

10

OS Wtd Timer Policy

Configure how the system should respond if the OS Boot Watchdog Timer expires. Not available if OS Boot Watchdog timer is disabled.

Do Nothing / **Reset** / Power Down / Power Cycle

BMC network configuration

Configure BMC network parameters.

5.4.1 BMC Network Configuration

Aptio Setup - AMI		
Server Mgmt		
BMC network configuration		Select to configure LAN channel parameters statically or dynamically(by BIOS or BMC). Unspecified option will not modify any BMC network parameters during BIOS phase

Configure IPv4 support		
Management Port 1		
Configuration Address source	[Unspecified]	
Current Configuration Address source	DynamicAddressBmcDhcp	
Station IP address	10.99.240.156	
Subnet mask	255.255.254.0	
Station MAC address	A0-42-3F-4D-12-EC	
Router IP address	10.99.241.254	
Router MAC address	00-00-0C-07-AC-F0	
Management Port 2	[Disabled]	++: Select Screen †: Select Item Enter: Select +/-: Change Opt. F1: General Help F2: Previous Values F3: Optimized Defaults F4: Save & Exit ESC: Exit
Configure IPv6 support		
Management Port 1		
IPv6 Support	[Disabled]	
Management Port 2		
IPv6 Support	[Disabled]	

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Configure IPV4 support

Management Port 1

Configuration Address Source

Select the configure LAN channel parameters statically or dynamically (by BIOS or BMC). Unspecified option will not modify any BMC network parameters during BIOS phase.

Unspecified / Static / DynamicBmcDhcp / DynamicBmcNonDhcp

Management Port 2

Enable/Disable BMC Share NIC.

Enabled / **Disabled**

Configure IPV6 support

Management Port 1

IPV6 Support

Enable or Disable LAN1 IPV6 Support.

Enabled / **Disabled**

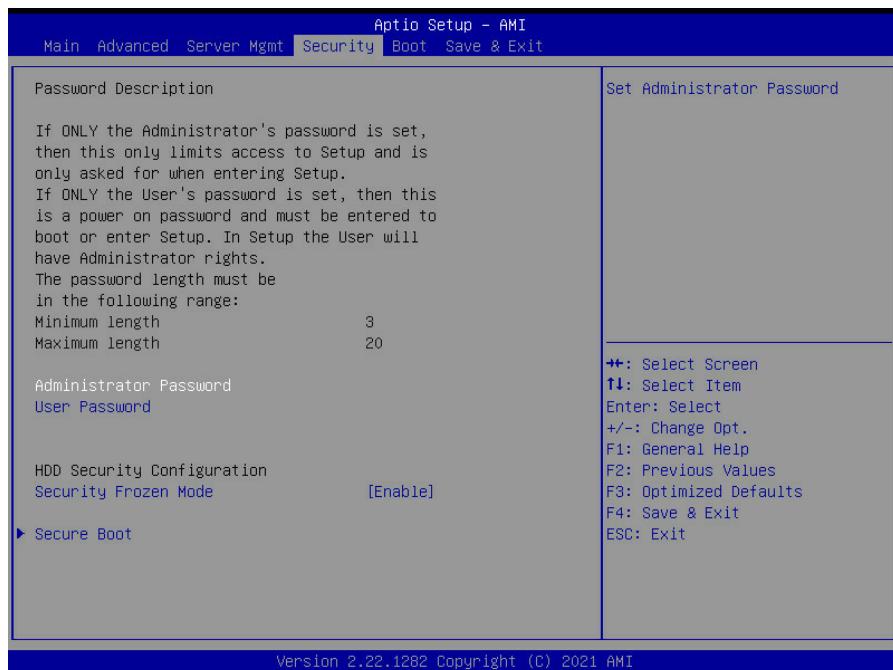
Management Port 2

IPV6 Support

Enable or Disable LAN2 IPV6 Support.

Enabled / **Disabled**

5.5 Security



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Administrator Password

Set administrator password in the **Create New Password** window. After you key in the password, the **Confirm New Password** window will pop out to ask for confirmation.

User Password

Set user password in the **Create New Password** window. After you key in the password, the **Confirm New Password** window will pop out to ask for confirmation.

Secure Frozen Mode

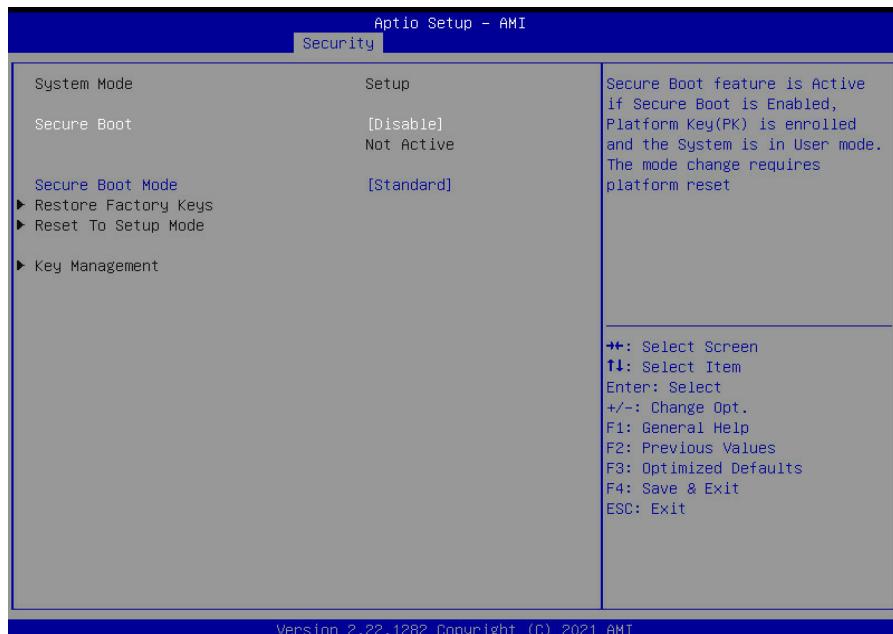
Disable means Hard Drive on Non-frozen mode. Enable means Hard Drive on Frozen mode.

Enable / Disable

Secure Boot

Secure Boot Configuration.

5.5.1 Secure Boot



Secure Boot

Secure Boot feature is Active if Secure Boot is Enabled. Platform Key (PK) is enrolled and the System is in User mode. The mode change requires platform reset.

Enable / **Disable**

Secure Boot Mode

Secure Boot mode selector: Standard/Custom. In Custom mode Secure Boot Variables can be configured without authentication.

Standard / Custom

NOTE: When Secure Boot Mode set to **[Custom]**, **Restore Factory Keys** and **Key management** will be available to set up.

Restore Factory Keys

Force System to User Mode. Install factory default Secure Boot key databases. Press 'Yes' to proceed 'No' to cancel.

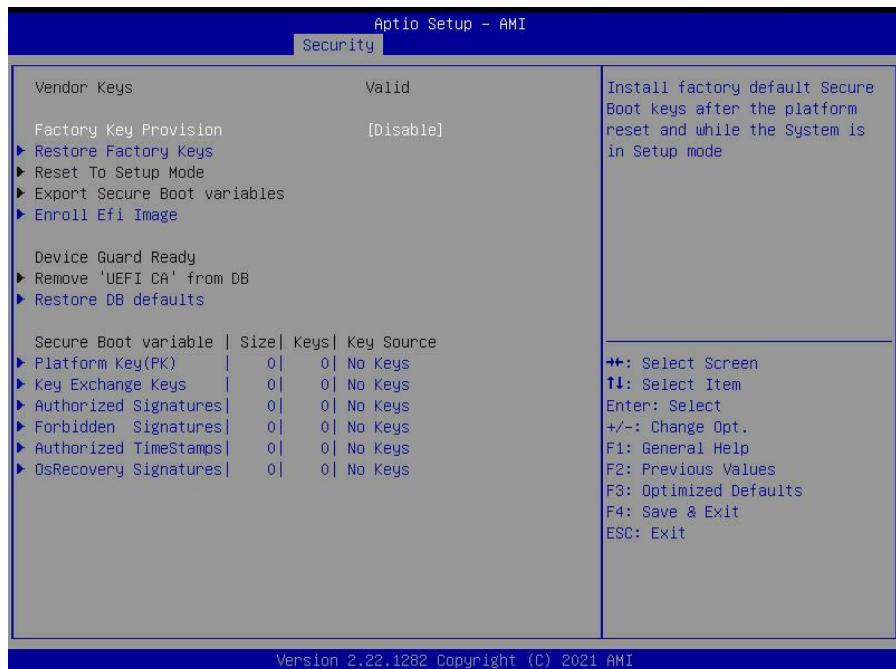
Reset to Setup Mode

Delete all Secure Boot key database from NVRAM. Deleting all variables will reset the System to Setup Mode. Press 'Yes' to proceed 'No' to cancel.

Key Management

Enables expert users to modify Secure Boot Policy variables without full authentication.

5.5.1.1 Key Management



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Factory Key Provision

Install factory default Secure Boot keys after the platform reset and while the System is in Setup mode.

Enable / **Disable**

NOTE: Factory Key Provision should be set to [Enable], the following items will be available to set up.

Restore Factory Keys

Force System to User Mode. Install factory default Secure Boot key databases. Press 'Yes' to proceed 'No' to cancel.

Reset to Setup Mode

Delete all Secure Boot key database from NVRAM. Deleting all variables will reset the System to Setup Mode.

Press 'Yes' to proceed 'No' to cancel.

Export Secure Boot variables

Copy NVRAM content of Secure Boot variables to files in a root folder on a file system device.

Enroll Efi Image

Allow the image to run in Secure Boot mode. Enroll SHA256 Hash certificate of a PE image into Authorized Signature Database (db).

Remove 'UEFI CA' from DB

Device Guard ready system must not list 'Microsoft UEFI CA' Certificate in Authorized Signature database (db). Press 'Yes' to proceed 'No' to cancel.

Restore DB defaults

Restore DB variable to factory defaults. Press 'Yes' to proceed 'No' to cancel.

Platform Key (PK)

Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:

- a) EFI_SIGNATURE_LIST
- b) EFI_CERT_X509 (DER)
- c) EFI_CERT_RSA2048 (bin)
- d) EFI_CERT_SHAXXX

2. Authenticated UEFI Variable

3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Details / Export / Update / Delete

Key Exchange Keys

Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:

- a) EFI_SIGNATURE_LIST
- b) EFI_CERT_X509 (DER)
- c) EFI_CERT_RSA2048 (bin)
- d) EFI_CERT_SHAXXX

2. Authenticated UEFI Variable

3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Details / Export / Update / Append / Delete

Authorized Signatures

Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:

- a) EFI_SIGNATURE_LIST
- b) EFI_CERT_X509 (DER)
- c) EFI_CERT_RSA2048 (bin)
- d) EFI_CERT_SHAXXX

2. Authenticated UEFI Variable

3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Details / Export / Update / Append / Delete

Forbidden Signatures

Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:
 - a) EFI_SIGNATURE_LIST
 - b) EFI_CERT_X509 (DER)
 - c) EFI_CERT_RSA2048 (bin)
 - d) EFI_CERT_SHAXXX
2. Authenticated UEFI Variable
3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Details / Export / Update / Append / Delete

Authorized TimeStamps

Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:
 - a) EFI_SIGNATURE_LIST
 - b) EFI_CERT_X509 (DER)
 - c) EFI_CERT_RSA2048 (bin)
 - d) EFI_CERT_SHAXXX
2. Authenticated UEFI Variable
3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Update / Append

OsRecovery Signatures

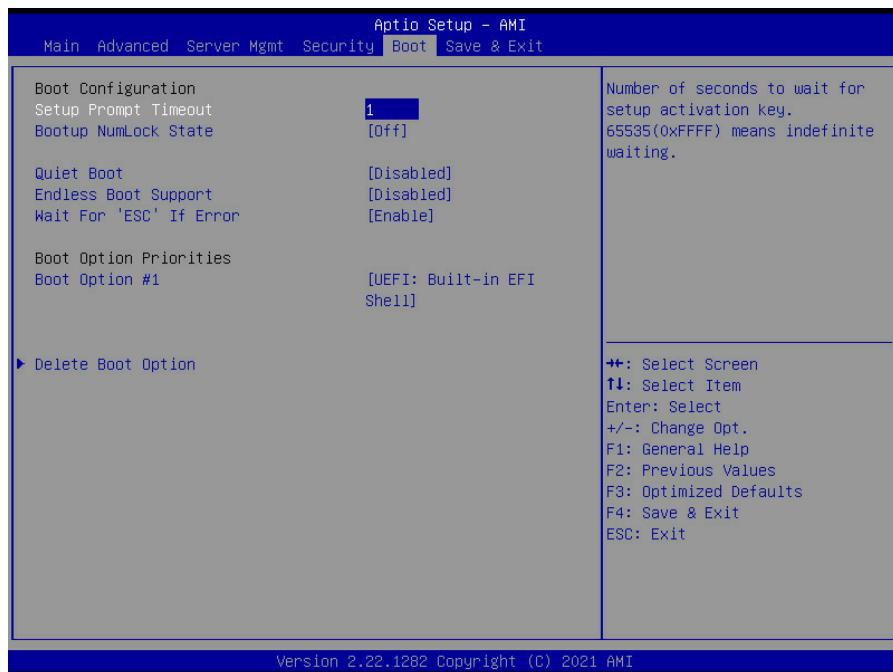
Enroll Factory Defaults or load certificates from a file:

1. Public Key Certificate in:
 - a) EFI_SIGNATURE_LIST
 - b) EFI_CERT_X509 (DER)
 - c) EFI_CERT_RSA2048 (bin)
 - d) EFI_CERT_SHAXXX
2. Authenticated UEFI Variable
3. EFI PE/C0FF Image (SHA256)

Key source: Factory, External, Mixed

Update / Append

5.6 Boot



Setup Prompt Timeout

Number of seconds to wait for setup activation key. 65535 (0xFFFF) means indefinite waiting.

1

Bootup NumLock State

Select the keyboard NumLock state.

Off / On

Quiet Boot

Enable or disable Quiet Boot option.

Enabled / Disabled

Endless Boot

Enable or disable Endless Boot.

Enabled / Disabled

Wait for 'ESC' If Error

Wait for 'ESC' key to be pressed if error occurs.

Enabled / **Disabled**

Boot Option Priorities

Boot Option #1

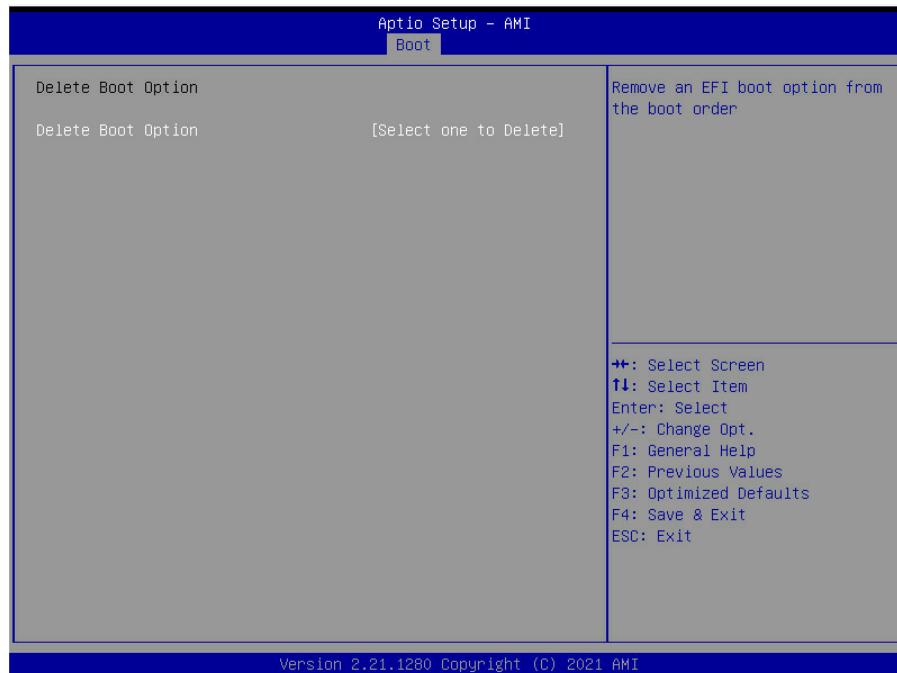
Select the system boot order.

Device Name / Disabled

Delete Boot Option

Remove an EFI boot option from the boot order.

5.6.1 Delete Boot Option



Delete Boot Option

Remove an EFI boot option from the boot order.

Select one to delete / Device Name

5.7 Save & Exit



Save Changes and Exit

Exit system setup after saving the changes.

Discard Changes and Exit

Exit system setup without saving any changes.

Save Changes and Reset

Reset the system after saving the changes.

Discard Changes and Reset

Reset system setup without saving any changes.

Save Changes

Save changes done so far to any of the setup options.

Discard Changes

Discard changes done so far to any of the setup options.

Restore Defaults

Restore/Load Default values for all the setup options.

Save as User Defaults

Save the changes done so far as User Defaults.

Restore User Defaults

Restore the User Defaults to all the setup options.

Boot Override

Read only.

Chapter 6: Diagnostics

NOTE: if you experience problems with setting up your system, always check the following things in the following order:

Memory, Video, CPU

By checking these items, you will most likely find out what the problem might have been when setting up your system. For more information on troubleshooting, check the TYAN website at <http://www.tyan.com>.

6.1 Flash Utility

Every BIOS file is unique for the motherboard it was designed for. For Flash Utilities, BIOS downloads, and information on how to properly use the Flash Utility with your motherboard, please check the TYAN web site at <http://www.tyan.com>

NOTE: Please be aware that by flashing your BIOS, you agree that in the event of a BIOS flash failure, you must contact your dealer for a replacement BIOS. There are no exceptions. TYAN does not have a policy for replacing BIOS chips directly with end users. In no event will TYAN be held responsible for damages done by the end user.

6.2 AMIBIOS Post Code

The POST code checkpoints are the largest set of checkpoints during the BIOS pre-boot process. The following table describes the type of checkpoints that may occur during the POST portion of the BIOS:

Checkpoint Ranges

Status Code Range	Description
0x01 – 0x0B	SEC execution
0x0C – 0x0F	Sec errors
0x10 – 0x2F	PEI execution up to and including memory detection
0x30 – 0x4F	PEI execution after memory detection
0x50 – 0x5F	PEI errors
0x60 – 0x8F	DXE execution up to BDS
0x90 – 0xCF	BDS execution
0xD0 – 0xDF	DXE errors
0xE0 – 0xE8	S3 Resume (PEI)
0xE9 – 0xEF	S3 Resume errors (PEI)
0xF0 – 0xF8	Recovery (PEI)
0xF9 – 0xFF	Recovery errors (PEI)

Standard Checkpoints

SEC Phase

Status Code	Description
0x00	Note used
Progress Codes	
0x01	Power on. Reset type detection (soft/hard).
0x02	AP initialization before microcode loading
0x03	North Bridge initialization before microcode loading
0x04	South Bridge initialization before microcode loading
0x05	OEM initialization before microcode loading
0x06	Microcode loading
0x07	AP initialization after microcode loading
0x08	North Bridge initialization after microcode loading
0x09	South Bridge initialization after microcode loading
0x0A	OEM initialization after microcode loading
0x0B	Cache initialization

SEC Error Codes	
0x0C – 0x0D	Reserved for future AMI SEC error codes
0x0E	Microcode not found
0x0F	Microcode not found

PEI Phase

Status Code	Description
Progress Codes	
0x10	PCI Core is started
0x11	Pre-memory CPU initialization is started
0x12	Pre-memory CPU initialization (CPU module specific)
0x13	Pre-memory CPU initialization (CPU module specific)
0x14	Pre-memory CPU initialization (CPU module specific)
0x15	Pre-memory North Bridge initialization is started
0x16	Pre-Memory North Bridge initialization (North Bridge module specific)
0x17	Pre-memory North Bridge initialization (North Bridge module specific)
0x18	Pre-Memory North Bridge initialization (North Bridge module specific)
0x19	Pre-memory South Bridge initialization is started
0x1A	Pre-Memory South Bridge initialization (South Bridge module specific)
0x1B	Pre-memory South Bridge initialization (South Bridge module specific)
0x1C	Pre-Memory South Bridge initialization (South Bridge module specific)
0x1D – 0x2A	OEM pre-memory initialization codes
0x2B	Memory initialization. Serial Presence Detect (SPD) data reading
0x2C	Memory initialization. Memory presence detection
0x2D	Memory initialization. Programming memory timing information
0x2E	Memory initialization. Configuring memory
0x2F	Memory initialization (other)
0x30	Reserved for ASL (see ASL Status Codes section below)
0x31	Memory Installed
0x32	CPU post-memory initialization is started.
0x33	CPU post-memory initialization. Cache initialization
0x34	CPU post-memory initialization. Application Processor(s) (AP) initialization

Status Code	Description
0x35	CPU post-memory initialization. Boot Strap Processor (BSP) selection
0x36	CPU post-memory initialization. System Management Mode (SMM) initialization
0x37	Post-Memory North Bridge initialization is started.
0x38	Post-Memory North Bridge initialization (North Bridge module specific)
0x39	Post-Memory North Bridge initialization (North Bridge module specific)
0x3A	Post-Memory North Bridge initialization (North Bridge module specific)
0x3B	Post-Memory South Bridge initialization is started
0x3C	Post-Memory South Bridge initialization (South Bridge module specific)
0x3D	Post-Memory South Bridge initialization (South Bridge module specific)
0x3E	Post-Memory South Bridge initialization (South Bridge module specific)
0x3F – 0x4E	OEM post memory initialization codes
0x4F	DXE PIL is started
PEI Error Codes	
0x50	Memory initialization error. Invalid memory type or incompatible memory speed
0x51	Memory initialization error. SPD reading has failed.
0x52	Memory initialization error. Invalid memory size or memory modules do not match.
0x53	Memory initialization error. No usable memory detected
0x54	Unspecified memory initialization error
0x55	Memory not installed
0x56	Invalid CPU type or speed
0x57	CPU mismatch
0x58	CPU self test failed or possible CPU cache error
0x59	CPU microcode is not found or microcode update is failed.
0x5A	Internal CPU error
0x5B	Reset PPI is not available.
0x5C – 0x5F	Reserved for future AMI error codes
S3 Resume Progress Codes	
0xE0	S3 Resume is started (S3 Resume PPI is called by the DXE IPL).
0xE1	S3 Boot Script execution

Status Code	Description
0xE2	Video repost
0xE3	OS S3 wake vector call
0xE4 – 0xE7	Reserved for future AMI progress codes
S3 Resume Error Codes	
0xE8	S3 Resume failed
0xE9	S3 Resume PPI not found
0xEA	S3 Resume Boot Script error
0xEB	S3 OS wake error
0xEC – 0xEF	Reserved for future AMI error codes
Recovery Progress Codes	
0xF0	Recovery condition triggered by firmware (Auto recovery)
0xF1	Recovery condition triggered by user (forced recovery)
0xF2	Recovery process started
0xF3	Recovery firmware image is found.
0xF4	Recovery firmware image is loaded.
0xF5 – 0xF7	Reserved for future AMI progress codes
Recovery Error Codes	
0xF8	Recovery PPI is not available.
0xF9	Recovery capsule is not found.
0xFA	Invalid recovery capsule
0xFB – 0xFF	Reserved for future AMI error codes

DXE Phase

Status Code	Description
0x60	DXE Core is started.
0x61	NVRAM initialization
0x62	Installation of the South Bridge Runtime Services
0x63	CPU DXE initialization is started.
0x64	CPU DXE initialization (CPU module specific)
0x65	CPU DXE initialization (CPU module specific)
0x66	CPU DXE initialization (CPU module specific)
0x67	CPU DXE initialization (CPU module specific)
0x68	PCI host bridge initialization
0x69	North Bridge DXE initialization is started.

Status Code	Description
0x6A	North Bridge DXE SMM initialization is started.
0x6B	North Bridge DXE initialization (North Bridge module specific)
0x6C	North Bridge DXE initialization (North Bridge module specific)
0x6D	North Bridge DXE initialization (North Bridge module specific)
0x6E	North Bridge DXE initialization (North Bridge module specific)
0x6F	North Bridge DXE initialization (North Bridge module specific)
0x70	South Bridge DXE initialization is started.
0x71	South Bridge DXE SMM initialization is started.
0x72	South Bridge devices initialization
0x73	South Bridge DXE initialization (South Bridge module specific)
0x74	South Bridge DXE initialization (South Bridge module specific)
0x75	South Bridge DXE initialization (South Bridge module specific)
0x76	South Bridge DXE initialization (South Bridge module specific)
0x77	South Bridge DXE initialization (South Bridge module specific)
0x78	ACPI module initialization
0x79	CSM initialization
0x7A – 0x7F	Reserved for future AMI DXE codes
0x80 – 0x8F	OEM DXE initialization codes
0x90	Boot Device Selection (BDS) phase is started
0x91	Driver connecting is started
0x92	PCI Bus initialization is started
0x93	PCI Bus Hot Plug Controller initialization
0x94	PCI Bus Enumeration
0x95	PCI BUS Request Resources
0x96	PCI Bus Assign Resources
0x97	Console output devices connect
0x98	Console Input devices connect
0x99	Super IO initialization
0x9A	USB initialization is started.
0x9B	USB Reset
0x9C	USB Detect
0x9D	USB Enable
0x9E -0x9F	Reserved for future AMI codes
0xA0	IDE initialization is started

Status Code	Description
0xA1	IDE Reset
0xA2	IDE Detect
0xA3	IDE Enable
0xA4	SCSI initialization is started.
0xA5	SCSI Reset
0xA6	SCSI Detect
0xA7	SCSI Enable
0xA8	Setup Verifying Password
0xA9	Start of Setup
0xAA	System has transitioned into ACPI mode. Interrupt controller is in APIC mode.
0xAB	Setup Input Wait
0xAC	System has transitioned into ACPI mode. Interrupt controller is in PIC mode.
0xAD	Ready To Boot event
0xAE	Legacy Boot event
0xAF	Exit Boot Services event
0xB0	Runtime Set Virtual Address MAP Begin
0xB1	Runtime Set Virtual Address MAP End
0xB2	Legacy Option ROM initialization
0xB3	System Reset
0xB4	USB hot plug
0xB5	PCI bus hot plug
0xB6	Clean-up of NVRAM
0xB7	Configuration Reset (reset of NVRAM settings)
0xB8 – 0xBF	Reserved for future AMI codes
0xC0 – 0xCF	OEM BDS initialization codes
DXE Error Codes	
0xD0	CPU initialization error
0xD1	North Bridge initialization error
0xD2	South Bridge initialization error
0xD3	Some of the Architectural Protocols are not available
0xD4	PCI resource allocation error. Out of Resources
0xD5	No Space for Legacy Option ROM
0xD6	No Console Output Devices are found.

Status Code	Description
0xD7	No Console Input Devices are found.
0xD8	Invalid password
0xD9	Error loading Boot Option (LoadImage returned error)
0xDA	Boot Option is failed (StartImage returned error).
0xDB	Flash update is failed.
0xDC	Reset protocol is not available.

Beep Codes

# of Beeps	Description
1 (repeatedly)	Memory not detected.
1	Invalid password.
5	No Console Output Devices are found.
8	PCI out of resources.

6.3 Intel MRC Post Code

Status Code	Description
0xDD00	MRC initialization start
0xDD02	Safe Mode Override
0xDD03	MRC Early Overrides
0xDD09	DDRIO Config - Pre DCC
0xDD89	DDRIO Config - Pre DCC Error
0xDD10	2D command plot
0xDD90	2D command plot Error
0xDD11	MC Frequency Lock
0xDD91	MC Frequency Lock Error
0xDD12	DDRIO Config - Post DCC
0xDD92	DDRIO Config - Post DCC Error
0xDD13	DDR SCOMP Config
0xDD93	DDR SCOMP Config Error
0xDD15	Memory SubSystem Config
0xDD95	Memory SubSystem Config Error
0xDD1A	DCC Initialization
0xDD9A	DCC Initialization Error

0xDD1B	Fast boot permitted
0xDD9B	Fast boot permitted Error
0xDD1C	Restore non-training values
0xDD9C	Restore non-training values Error
0xDD1D	Print input parameters
0xDD9D	Print input parameters Error
0xDD1E	Pre-SPD Timing overrides
0xDD9E	Pre-SPD Timing overrides Error
0xDD20	SPD processing
0xDDA0	SPD processing Error
0xDD21	MRC Auto Updates and Overrides
0xDDA1	MRC Auto Updates and Overrides Error
0xDD22	MC Capabilities
0xDDA2	MC Capabilities Error
0xDD23	MC Config
0xDDA3	MC Config Error
0xDD24	MC Memory map
0xDDA4	MC Memory map Error
0xDD26	JEDEC reset
0xDDA6	JEDEC reset Error
0xDD27	Pre-Training
0xDDA7	Pre-Training Error
0xDD28	Early Command Training
0xDDA8	Early Command Training Error
0xDD29	SenseAmp Offset Training
0xDDA9	SenseAmp Offset Training Error
0xDD2A	Read MPR training
0xDDAA	Read MPR training Error
0xDD2B	Read Leveling training
0xDDAB	Read Leveling training Error
0xDD2C	Jedec Write Leveling training
0xDDAC	Jedec Write Leveling training Error
0xDD2D	LPDDR3 Latency Set B
0xDDAD	LPDDR3 Latency Set B Error
0xDD2E	Write Timing Centering

0xDDAE	Write Timing Centering Error
0xDD2F	Read Timing Centering
0xDDAF	Read Timing Centering Error
0xDD30	DIMM ODT Training
0xDDB0	DIMM ODT Training Error
0xDD31	Early Write Timing Centering 2D
0xDDB1	Early Write Timing Centering 2D Error
0xDD32	Write Drive Strength Up/Dn 2D
0xDDB2	Write Drive Strength Up/Dn 2D Error
0xDD33	Write Equalization Training
0xDDB3	Read Equalization Training Error
0xDD34	Early Read Timing Centering 2D
0xDDB4	Early Read Timing Centering 2D Error
0xDD35	Read ODT Training
0xDDB5	Read ODT Training Error
0xDD36	Read Equalization Training
0xDDB6	Read Equalization Training Error
0xDD37	Read Amplifier Power
0xDDB7	Read Amplifier Power Error
0xDD38	Write Timing Centering 2D
0xDDB8	Write Timing Centering 2D Error
0xDD39	Read Timing Centering 2D
0xDDB9	Read Timing Centering 2D Error
0xDD3A	Command Voltage Centering
0xDDBA	Command Voltage Centering Error
0xDD3B	Write Voltage Centering 2D
0xDDBB	Write Voltage Centering 2D Error
0xDD3C	Read Voltage Centering 2D
0xDDBC	Read Voltage Centering 2D Error
0xDD3D	Post training
0xDDBD	Post training Error
0xDD3E	Late command training
0xDDBE	Late command training Error
0xDD3F	Round Trip Latency Training
0xDDBF	Round Trip Latency Training Error

0xDD40	Turn Around Trip Training
0xDDC0	Turn Around Trip Training Error
0xDD41	Comp Optimization Training
0xDDC1	Comp Optimization Training Error
0xDD42	Save MC Values
0xDDC2	Save MC Values Error
0xDD43	Restore Training Values
0xDDC3	Restore Training Values Error
0xDD44	Rank Margin Tool
0xDDC4	Rank Margin Tool Error
0xDD45	Write Slew Rate
0xDDC5	Write Slew Rate Error
0xDD46	DIMM Ron Training
0xDDC6	DIMM Ron Training Error
0xDD47	Receive Enable Timing Centering
0xDDC7	Receive Enable Timing Centering Error
0xDD48	Save MRs to Scratch Registers
0xDDC8	Save MRs to Scratch Registers Error
0xDD49	PowerSavingMeter update
0xDDC9	PowerSavingMeter update Error
0xDD4A	DDR4 PDA Mapping
0xDDCA	DDR4 PDA Mapping Error
0xDD4B	Write Voltage Centering
0xDDCB	Write Voltage Centering Error
0xDD4C	Early ReadMPR Timing Centering 2D
0xDDCC	Early ReadMPR Timing Centering 2D Error
0xDD4E	Write Leveling FlyBy training
0xDDCE	Write Leveling FlyBy training Error
0xDD4F	MRC Comp override
0xDDCF	MRC Comp override Error
0xDD50	MRC activate
0xDDD0	MRC activate Error
0xDD51	Row Hammer Prevention
0xDDD1	Row Hammer Prevention Error
0xDD52	Get MRC Data

0xDDD2	Get MRC Data Error
0xDD53	Write DQ/DQS Retraining
0xDDD3	Write DQ/DQS Retraining Error
0xDD55	Memory Init Done
0xDDD5	Memory Init Done Error
0xDD56	Write TCO Comp Training
0xDDD6	Write TCO Comp Training Error
0xDD57	Read Voltage Centering
0xDDD7	Read Voltage Centering Error
0xDD58	Check Margin for Retrain
0xDDD8	Check Margin for Retrain Error
0xDD59	Rank Margin Tool Bit
0xDDD9	Rank Margin Tool Bit Error
0xDD5A	MRC SA GV Switch
0xDDDA	MRC SA GV Switch Error
0xDD5B	MRC Memory alias check
0xDDDB	MRC Memory alias check Error
0xDD5C	MRC Memory Scrubbing
0xDDDC	MRC Memory Scrubbing Error
0xDD5D	MRC done
0xDDDD	MRC done Error
0xDD5E	Update MC Values in Fast flow
0xDDDE	Update MC Values in Fast flow Error
0xDD5F	MRC HW Memory test
0xDDDF	MRC HW Memory test Error
0xDD60	TXT Memory alias check
0xDDE0	TXT Memory alias check Error
0xDD61	MRC Energy Performance Gain
0xDDE1	MRC Energy Performance Gain Error
0xDD62	ClkTCO Comp Training
0xDDE2	ClkTCO Comp Training Error
0xDD63	Read Per Bit Deskew Calibration
0xDDE3	Read Per Bit Deskew Calibration Error
0xDD64	Sense amplifier offset correction
0xDDE4	Sense amplifier offset correction Error

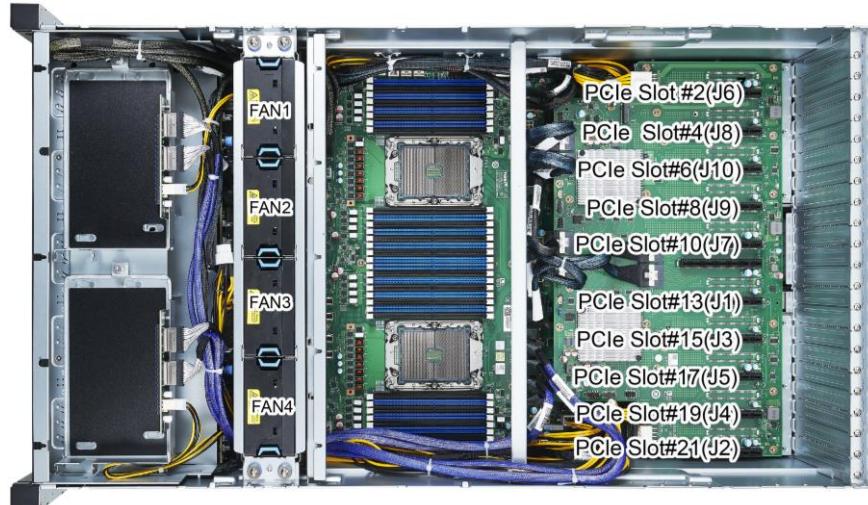
0xDD65	DCC Replica
0xDDE5	DCC Replica Error
0xDD66	DCC Finalization
0xDDE6	DCC Finalization Error
0xDD68	Memory Test
0xDDE8	Memory Test Error
0xDD69	Fill BDAT Structure
0xDDE9	Fill BDAT Structure Error
0xDD6A	Command Slew Rate Training
0xDDEA	Command Slew Rate Training Error
0xDD6B	Command Slew Rate Training Off
0xDDEB	Command Slew Rate Training Off Error
0xDD6C	Command Drive Strength and Equalization 2D
0xDDEC	Command Drive Strength and Equalization 2D Error
0xDD6D	DIMM CA ODT Training
0xDDED	DIMM CA ODT Training Error
0xDD6E	Write TCO DqsP/N/Bypass Training
0xDDEE	Write TCO DqsP/N/Bypass Training Error
0xDD6F	DQ DFE Training
0xDDEF	DQ DFE Training Error
0xDD70	Perform Self Refresh Exit
0xDDF0	Perform Self Refresh Exit Error
0xDD71	Normal Operation
0xDDF1	Normal Operation Error
0xDD72	Configure Thermal values
0xDDF2	Configure Thermal values Error
0xDD73	Margin limit Check on Fast Flow
0xDDF3	Margin limit Check on Fast Flow Error
0xDD74	Early Command Voltage Centering
0xDDF4	Early Command Voltage Centering Error
0xDD76	Read Timing optimization Shift Rx Vref
0xDDF6	Read Timing optimization Shift Rx Vref Error
0xDDFE	No Memory detected

Appendix II: PCIE Slot Location and Corresponding List

PCIE address and PCIE number Mapping

PCI-e address	Slot number
0000000:3D:00.0	13(J1)
0000000:3E:00.0	21(J2)
0000000:3F:00.0	15(J3)
0000000:40:00.0	19(J4)
0000000:41:00.0	17(J5)
0000000:60:00.0	2(J6)
0000000:61:00.0	10(J7)
0000000:62:00.0	4(J8)
0000000:63:00.0	8(J9)
0000000:64:00.0	6(J10)

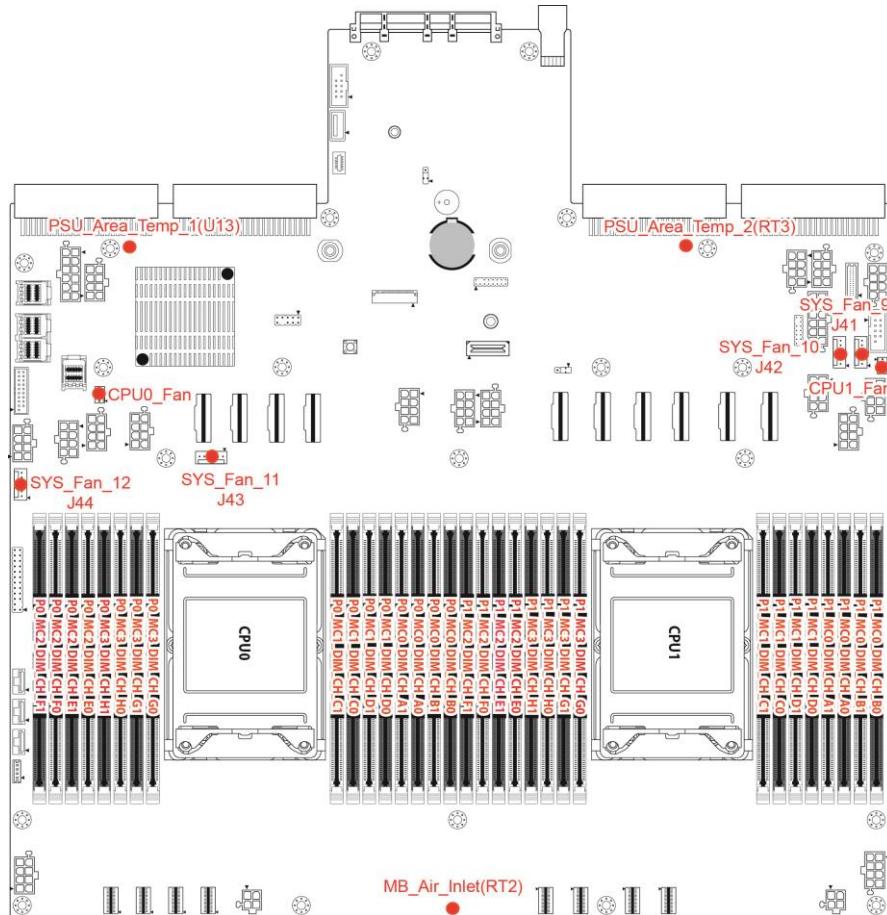
PCIE Slot Location



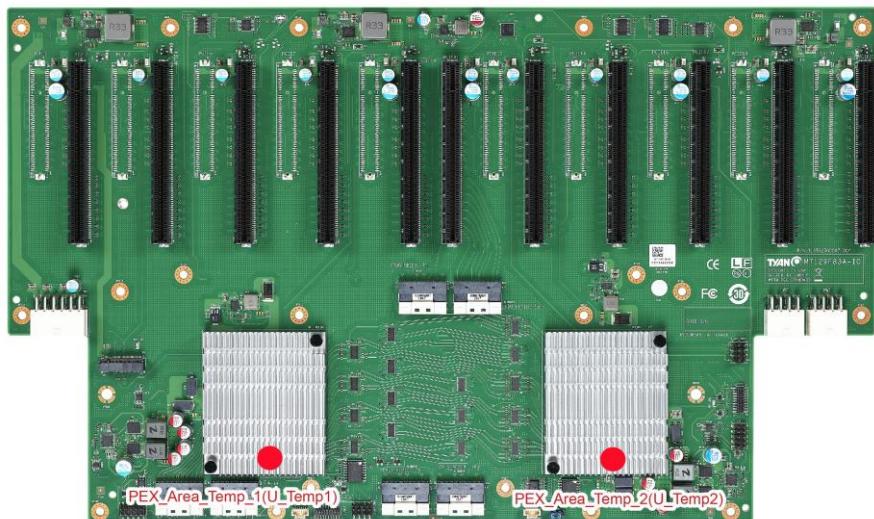
Appendix III: Fan and Temp Sensors

This section aims to help readers identify the locations of some specific FAN and Temp Sensors on the motherboard. A table of BIOS Temp sensor name explanation is also included for readers' reference.

Figure 1: Sensor Location



NOTE: The red spot indicates the sensor.



Fan and Temp Sensor Location:

1. Fan Sensor: It is located in the **third** pin of the fan connector, which detects the fan speed (rpm)
2. Temp Sensor: refer to Figure 1: Sensor Location. They detect the system temperature around.

BIOS Temp Sensor Name Explanation:

PC Health Status				
ID#	NAME	READING	UNIT	STATUS
01	P0_Temp	: 54	°C	OK
02	P0_DTS_Margin	: -39		OK
03	P1_Temp	: 52	°C	OK
04	P1_DTS_Margin	: -41		OK
09	PCH_Temp	: 36	°C	OK
10	P0_MCO_DIM_CH_A	: N/A	°C	
11	P0_MCO_DIM_CH_B	: N/A	°C	
12	P0_MCO_DIM_CH_C	: N/A	°C	
13	P0_MCO_DIM_CH_D	: N/A	°C	
14	P0_MC1_DIM_CH_E	: N/A	°C	
15	P0_MC1_DIM_CH_F	: N/A	°C	
16	P0_MC1_DIM_CH_G	: 39	°C	OK
17	P0_MC1_DIM_CH_H	: N/A	°C	
18	P1_MCO_DIM_CH_A	: N/A	°C	
19	P1_MCO_DIM_CH_B	: N/A	°C	
1A	P1_MCO_DIM_CH_C	: N/A	°C	
1B	P1_MCO_DIM_CH_D	: N/A	°C	
1C	P1_MC1_DIM_CH_E	: N/A	°C	
1D	P1_MC1_DIM_CH_F	: N/A	°C	
1E	P1_MC1_DIM_CH_G	: N/A	°C	
1F	P1_MC1_DIM_CH_H	: N/A	°C	
20	P0_MOSFET	: 55	°C	OK

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++: Select Screen
!!: Select Item
Enter: Select
+/-: Change Opt.
F1: General Help
F2: Previous Values
F3: Optimized Defaults
F4: Save & Exit
ESC: Exit

Aptio Setup - AMI			
Advanced			
20 P0_MOSFET	:	57	°C OK
21 P0_DIMM_MOSFET_1	:	42	°C OK
22 P0_DIMM_MOSFET_2	:	43	°C OK
24 P1_MOSFET	:	53	°C OK
25 P1_DIMM_MOSFET_1	:	37	°C OK
26 P1_DIMM_MOSFET_2	:	39	°C OK
30 SYS_Air_Inlet	:	N/A	°C
32 MB_Air_Inlet	:	38	°C OK
33 PSU_Area_Temp_1	:	30	°C OK
34 PSU_Area_Temp_2	:	34	°C OK
35 PEX_Area_Temp_1	:	37	°C OK
36 PEX_Area_Temp_2	:	34	°C OK
40 GPU0_Temp	:		Disabled
41 GPU1_Temp	:		Disabled
42 GPU2_Temp	:		Disabled
43 GPU3_Temp	:		Disabled
44 GPU4_Temp	:		Disabled
45 GPU5_Temp	:		Disabled
46 GPU6_Temp	:		Disabled
47 GPU7_Temp	:		Disabled
48 GPU8_Temp	:		Disabled
49 GPU9_Temp	:		Disabled
50 OCP_Card_Temp	:	N/A	°C
E4 NVMe SSD_0	:	N/A	°C
E5 NVMe SSD_1	:	N/A	°C

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Aptio Setup - AMI			
Advanced			
E6 NVMe SSD_2	:	N/A	°C
E7 NVMe SSD_3	:	N/A	°C
E8 NVMe SSD_4	:	N/A	°C
E9 NVMe SSD_5	:	N/A	°C
EA NVMe SSD_6	:	N/A	°C
EB NVMe SSD_7	:	N/A	°C
62 SYS_FAN_1	:	N/A	RPM
63 SYS_FAN_2	:	N/A	RPM
64 SYS_FAN_3	:	N/A	RPM
65 SYS_FAN_4	:	N/A	RPM
66 SYS_FAN_5	:	N/A	RPM
67 SYS_FAN_6	:	N/A	RPM
68 SYS_FAN_7	:	N/A	RPM
69 SYS_FAN_8	:	N/A	RPM
6A SYS_FAN_9	:	N/A	RPM
6B SYS_FAN_10	:	N/A	RPM
6C SYS_FAN_11	:	N/A	RPM
6D SYS_FAN_12	:	N/A	RPM
70 PSU0_Temp	:	30	°C OK
71 PSU0_Fan	:	4600	RPM OK
72 PSU0_Pout	:	147	W OK
73 PSU0_Pin	:	175	W OK
78 PSU1_Temp	:	N/A	°C
79 PSU1_Fan	:	N/A	RPM
7A PSU1_Pout	:	N/A	W

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↑: Select Screen
 ↑: Select Item
 Enter: Select
 +/-: Change Opt.
 F1: General Help
 F2: Previous Values
 F3: Optimized Defaults
 F4: Save & Exit
 ESC: Exit

BIOS Temp Sensor	Name Explanation
P0_Temp	CPU0 Tempterature
P1_Temp	CPU1 Tempterature
PCH_Temp	Temperature of the PCH
SYS_Air_Inlet	Temperature of the SYS Air Inlet Area
MB_Air_Inlet	Temperature of the M/B Air Inlet Area
P0_MOSFET	Max Temperature of CPU0_MOSFET
P1_MOSFET	Max Temperature of CPU1_MOSFET
P0_DIMM_MOSFET_1	Max Temperature of CPU0 DIMM Area1 MOSFET
P0_DIMM_MOSFET_2	Max Temperature of CPU0 DIMM Area2 MOSFET
P1_DIMM_MOSFET_1	Max Temperature of CPU1 DIMM Area1 MOSFET
P1_DIMM_MOSFET_2	Max Temperature of CPU1 DIMM Area2 MOSFET
P0_MC0_DIM_CH_A	Temperature of CPU0 DIMM Channel A
P0_MC0_DIM_CH_B	Temperature of CPU0 DIMM Channel B
P0_MC0_DIM_CH_C	Temperature of CPU0 DIMM Channel C
P0_MC0_DIM_CH_D	Temperature of CPU0 DIMM Channel D
P0_MC1_DIM_CH_E	Temperature of CPU0 DIMM Channel E
P0_MC1_DIM_CH_F	Temperature of CPU0 DIMM Channel F
P0_MC1_DIM_CH_G	Temperature of CPU0 DIMM Channel G
P0_MC1_DIM_CH_H	Temperature of CPU0 DIMM Channel H
P1_MC0_DIM_CH_A	Temperature of CPU1 DIMM Channel A
P1_MC0_DIM_CH_B	Temperature of CPU1 DIMM Channel B
P1_MC0_DIM_CH_C	Temperature of CPU1 DIMM Channel C
P1_MC0_DIM_CH_D	Temperature of CPU1 DIMM Channel D
P1_MC1_DIM_CH_E	Temperature of CPU1 DIMM Channel E
P1_MC1_DIM_CH_F	Temperature of CPU1 DIMM Channel F
P1_MC1_DIM_CH_G	Temperature of CPU1 DIMM Channel G
P1_MC1_DIM_CH_H	Temperature of CPU1 DIMM Channel H
NVME0_Temp	Temperature of NVME0
NVME1_Temp	Temperature of NVME1
NVME2_Temp	Temperature of NVME2
NVME3_Temp	Temperature of NVME3
CPU0_FAN	Fan Speed of CPU0_FAN
CPU1_FAN	Fan Speed of CPU1_FAN
SYS_FAN_1	Fan Speed of SYS_FAN_1
SYS_FAN_2	Fan Speed of SYS_FAN_2
SYS_FAN_3	Fan Speed of SYS_FAN_3
SYS_FAN_4	Fan Speed of SYS_FAN_4
SYS_FAN_5	Fan Speed of SYS_FAN_5
SYS_FAN_6	Fan Speed of SYS_FAN_6
SYS_FAN_7	Fan Speed of SYS_FAN_7
SYS_FAN_8	Fan Speed of SYS_FAN_8
SYS_FAN_9	Fan Speed of SYS_FAN_9
SYS_FAN_10	Fan Speed of SYS_FAN_10
SYS_FAN_11	Fan Speed of SYS_FAN_11
SYS_FAN_12	Fan Speed of SYS_FAN_12

PSU0_STATUS	Current status of PSU0
PSU0_Temp	Temperature of PSU0
PSU0_FAN	Fan Speed of PSU0
PSU1_STATUS	Current status of PSU1
PSU1_Temp	Temperature of PSU1
PSU1_FAN	Fan Speed of PSU1

Appendix IV: Cable Connection Tables

1. Fan PWR & FAN ctrl Cable

M7129F83-FB to S7129 MB		
Fan board	Connect to	S7129 M/B
FAN PWR Cable J9	→	J46 P/N: 422T62700004
FAN Ctrl Cable J10	→	FAN_HD1 P/N: 422T53400003

2. FP Ctrl Cable (P/N: 422T62700009)

M1718T65-FPB to S7129 MB		
M1718T65-FPB	Connect to	S7129 M/B
J4	→	EPIO1

3. USB Cable (P/N: 422T62800001)

M1717T65-USB to S7129 MB		
M1717T65-USB	Connect to	S7129 M/B
J3 & J4	→	J5

4. VGA & COM port Cable

Front BKT to S7129 MB		
Front BKT	Connect to	S7129 M/B
VGA Cable	→	FPIO_VGA P/N: 422T61000008
COM port Cable	→	HD_COM1 P/N: 422T61000009

5. Rear USB Cable

M7129F83A-RIO to S7129 MB		
M7129F83A-RIO	Connect to	S7129 M/B
USB Cable J2	→	J23 P/N: 422T62700008

6. HDD BP PWR & Mini-SAS HD & Signal Cable

(B7129F83AV14E8HR-2T-N)

M1297T65-BP12E-12 to S7129 MB		
M1297T65-BP12E-12	Connect to	S7129 M/B
Mini-SAS HD Cable-1 (SATA0_3)	→	J20 P/N: 422T53400018
Mini-SAS HD Cable-2 (SATA4_7)	→	SATA0_7 P/N: 422T53400005
Mini-SAS HD Cable-3 (SATA8_11)	→	SATA0_7 P/N: 422T53400006
HDD BP PWR Cable (2.5" J9 & 3.5" PW1)	→	J55 P/N: 422T62700005
Signal Cable (HDR_1)	→	J19 P/N: 422T60900011

7. Mini-SAS HD & Slim-SAS & Signal Cable (B7129F83AV14E8HR-2T-N)

M1315F83A-BP12E-10 to S7129 MB		
M1315F83A-BP12E-10	Connect to	S7129 M/B
Slim-SAS Cable-1 (J5)	→	CN1 & CN2 P/N: 422T62700014
Slim-SAS Cable-2 (J14)	→	CN3 & CN4 P/N: 422T62700014
Slim-SAS Cable-3 (J13)	→	CN5 & CN6 P/N: 422T62700014
Slim-SAS Cable-4 (J11)	→	CN7 & CN8 P/N: 422T62700014
Mini-SAS HD Cable (J19)	→	J23 P/N: 422T53400011
Signal Cable (HDR_1)	→	J18 P/N: 422T60900011

8. HDD BP PWR & Mini-SAS HD & Signal Cable

(B7129F83AV8E4HR-2T-N)

M1297T65-BP12E-12 to S7129 MB		
M1297T65-BP12E-12	Connect to	S7129 M/B
Mini-SAS HD Cable-1 (SATA0_3)	→	J20 P/N: 422T53400018
Mini-SAS HD Cable-2 (SATA4_7)	→	SATA0_7 P/N: 422T53400005
Mini-SAS HD Cable-3 (SATA8_11)	→	SATA0_7 P/N: 422T53400006
Slim-SAS Cable-1 (SLIMSAS1)	→	CN1 & CN2 P/N: 422T62700014
Slim-SAS Cable-2 (SLIMSAS2)	→	CN3 & CN4 P/N: 422T62700014
HDD BP PWR Cable (2.5" J9 & 3.5" PW1)	→	J55 P/N: 422T62700005
Signal Cable (HDR_1)	→	J19 P/N: 422T60900011

9. Riser PWR & Slim-SAS Cable

M7129F83A-L16 to S7129 MB		
M7129F83A-L16	Connect to	S7129 M/B
Slim-SAS Cable-1 (Riser-1 J5)	→	SLIMSAS6 P/N: 422T60900003
Slim-SAS Cable-2 (Riser-1 J6)	→	SLIMSAS7 P/N: 422T60900003
Slim-SAS Cable-3 (Riser-2 J5)	→	SLIMSAS8 P/N: 422T61600004
Slim-SAS Cable-4 (Riser-2 J6)	→	SLIMSAS9 P/N: 422T61600004
Riser PWR cable-1 (Riser-1 PWR2)	→	J36 P/N: 422T62700006
Riser PWR cable-2 (Riser-2 PWR2)	→	J52 P/N: 422T62700006

10. 2x4P MB PWR Cable

S7129 MB to S7129 MB		
S7129 M/B	Connect to	S7129 M/B
2x4P PWR Cable-1 J45	→	J54 P/N: 422T57200004
2x4P PWR Cable-2 J50	→	J49 P/N: 422T57200004

11. Slim-SAS & IO PWR Cable

M7129F83A-IO to S7129 MB		
M7129F83A-IO	Connect to	S7129 M/B
Slim-SAS Cable-1 SLIMSAS6	→	SLIMSAS0 P/N: 422T62700013
Slim-SAS Cable-2 SLIMSAS5	→	SLIMSAS1 P/N: 422T62700013
Slim-SAS Cable-3 SLIMSAS1	→	SLIMSAS2 P/N: 422T60900001
Slim-SAS Cable-4 SLIMSAS2	→	SLIMSAS3 P/N: 422T62700011 (反向)
Slim-SAS Cable-5 SLIMSAS4	→	SLIMSAS4 P/N: 422T62700012
Slim-SAS Cable-6 SLIMSAS3	→	SLIMSAS5 P/N: 422T62700013
2x4P PWR Cable PW1	→	J15 P/N: 422T62700015
2x6P PWR Cable PW3	→	J47 P/N: 422T62700007

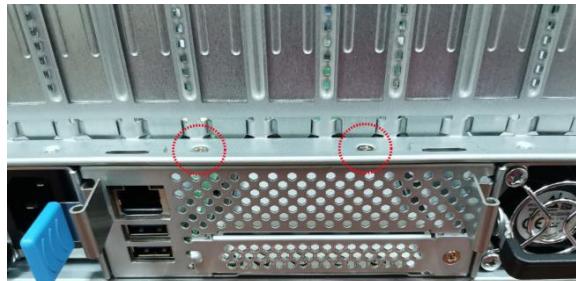
12. Rear FAN extend Cable

Rear FAN to S7129 MB		
Rear FAN	Connect to	S7129 M/B
FAN1	→	J41 P/N: 422T62700010
FAN2	→	J42 P/N: 422T62700010
FAN3	→	J43 P/N: 422T62700010
FAN4	→	J44 P/N: 422T62700010

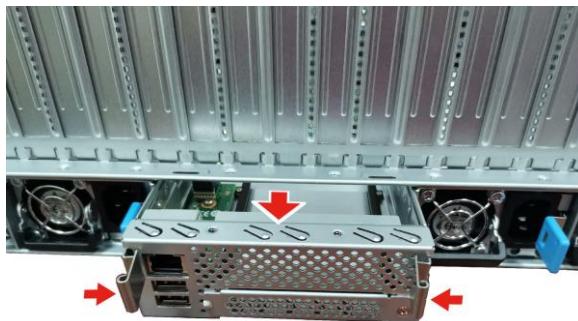
Appendix V: Installing OCP Card

Follow these instructions to install the OCP 3.0 Card.

1. Unscrew the Rear IO Bracket.



2. Push both latches to pull the Rear IO Bracket out.



3. Unscrew the IO bracket.



4. Pull out the IO bracket.



5. Insert the 3.0 OCP card to the bracket.



6. Reinstall the IO bracket into the chassis.



Appendix VI: FRU Parts Table

FT83A-B7129 FRU Parts				
Item	Model Number	Part Number	Picture	Description
Air Duct		452T62700003		TF-AIR DUCT;SBU,AL,FOR CPUHSK,_NCT,FT77D-B7109
Cable		422T53400003		TF-CABLE ASSY;CONTROL INTERNAL,SBU,28 AWG,600 mm,FAN CTRL CABLE, 2*15P, P1.0/2*15P, P1.0,TN71-BP012
		422T53400005		TF-CABLE ASSY;SAS INTERNAL,SBU,30 AWG,700 mm,MINI-SAS HD CABLE, SHORT MINI-SAS HD 36P/SHORT MINI-SAS HD 36P,TN71-BP012
		422T53400006		TF-CABLE ASSY;SAS INTERNAL,SBU,30 AWG,800 mm,MINI-SAS HD CABLE, SHORT MINI-SAS HD 36P/SHORT MINI-SAS HD 36P,TN71-BP012
		422T53400018		TF-CABLE ASSY;SAS INTERNAL,SBU,30 AWG,600 mm,MINI-SAS HD CABLE, SHORT MINI-SAS HD 36P/SHORT MINI-SAS HD 36P,TN71-BP012
		422T57200004		TF-AC/DC POWER CABLE:SBU,18 AWG,450mm,2*4P(M), P4.2/2*4P(M), P4.2, UL1015,13A,GT62F-B5630
		422T60900001		TF-CABLE ASSY;SAS INTERNAL,SBU,32 AWG,250 mm,SlimSAS 8i to SlimSAS 8i CABLE,SlimSAS 8i 74P/SlimSAS 8i 74P,Normal Signal,TS65-B8036
		422T60900003		TF-CABLE ASSY;SAS INTERNAL,SBU,32 AWG,700 mm,SlimSAS 8i to SlimSAS 8i CABLE,SlimSAS 8i 74P/SlimSAS 8i 74P,Normal Signal,TS65-B8036
		422T60900011		TF-CABLE ASSY;CONTROL INTERNAL,SBU,28 AWG,700 mm, SIGNAL CABLE, 1*7P, P1.25/1*7P,P1.25,TS65-B8036
		422T61000008		TF-CABLE ASSY;VGA INTERNAL, SBU,30 AWG,1200 mm,VGA CABLE, 2*7P, P2.0,K11P/VGA PORT 15P(F), W/2PCS HEX SCREW, FT83-B7119
		422T61000009		TF-CABLE ASSY;COM PORT INTERNAL,SBU,28 AWG,750 mm, COM PORT CABLE, 2*5P, P2.54,K10P/COM PORT DB9P(M), W/2PCS HEX SCREW,FT83-B7119
		422T61600004		TF-CABLE ASSY;SAS INTERNAL, SBU,32 AWG,800 mm,SlimSAS 8i to SlimSAS 8i Cable, Short SlimSAS 8i 74P/Short SlimSAS 8i 74P,Normal

			Signal, GC68-B8036
	422T62700004		TF-AC/DC POWER CABLE;SBU,18 AWG,550 mm,2*4P(M),P4.2/ 2*4P(M), P4.2,UL1015, 13A, FT83A-B7129
	422T62700005		TF-AC/DC POWER CABLE;SBU,18 AWG,700 mm,2*6P(M),P4.2/ 2*4P(M), P4.2(2), UL1015,13A, FT83A-B7129
	422T62700006		TF-AC/DC POWER CABLE;SBU,18 AWG,450 mm,2*2P(M),P4.2/ 2*2P(M),P4.2,FT83A-B7129
	422T62700007		TF-AC/DC POWER CABLE;SBU,18 AWG,150 mm,2*6P(M),P4.2/ 2*6P(M), P4.2, UL1015, 13A,FT83A-B7129
	422T62700009		TF-CABLE ASSY;CONTROL INTERNAL,SBU,28 AWG,1100 mm,FP CTRL CABLE, 2*15P, P1.0/2*12P, P2.54, K4P, FT83A-B7129
	422T62700011		TF-CABLE ASSY;SAS INTERNAL, SBU,32 AWG,200 mm,SlimSAS 8i to SlimSAS 8i Cable,Short SlimSAS 8i 74P/Short SlimSAS 8i 74P, Reversed Signal, FT83A-B7129
	422T62700012		TF-CABLE ASSY;SAS INTERNAL,SBU,32 AWG,150 mm,SlimSAS 8i to SlimSAS 8i CABLE,SlimSAS 8i 74P/SlimSAS 8i 74P,FT83A-B7129
	422T62700013		TF-CABLE ASSY;SAS INTERNAL, SBU,32 AWG,100 mm,SlimSAS 8i to SlimSAS 8i CABLE,SlimSAS 8i 74P/SlimSAS 8i 74P,FT83A-B7129
	422T62700014		TF-CABLE ASSY;SAS INTERNAL, SBU,30 AWG,650 mm,SlimSAS 8i to 2*SlimSAS 4i CABLE,SlimSAS 8i 74P/2*SlimSAS 4i 38P,NEW, FT83A-B7129
	422T62700015		TF-AC/DC POWER CABLE;SBU,18 AWG,80 mm, 2*4P(M), P4.2/2*4P(M), P4.2, UL1015, 13A,FT83A-B7129
	422T62800001		TF-CABLE ASSY;USB INTERNAL, SBU,28 AWG,750 mm,USB 3.0 CABLE,USB 3.0, 2*10P, P2.0, K20P/2*5P2,P2.0,K3P,TE45-B5645
	422T56800011		TF-AC/DC POWER CABLE;SBU,20 AWG,250mm,GPU PWR CABLE, 2*4P(M), P4.2/2*3P+ 2*1P(M)*2pcs, P4.2,FT77D-B7109
	422T60400014		TF-AC/DC POWER CABLE;SBU,18 AWG,200 mm,2*4P(M),P4.2/ 2*4P(M), P4.2,UL1015,13A,GT90-B7113
	332810000515		TF-POWER CORD;SBU,EU,250 V,16 AWG(1.0mm ²),1800mm,AC PWR CORD

		332810000514		TF-POWER CORD;SBU,US,125 V,16 AWG(1.31mm ²),1800mm,AC PWR CORD
Compatible Accessories	FRU-NC-9060	5412T5770006		M7062-I599-2T W/Bracket
	FRU-NC-9100	5412T5770010		M7086-X710-2F W/ Bracket
	FRU-NC-9200	5412T6100003		M7108-X550-2T W/Bracket
	FRU-NC-9210	5412T6100004		M7108-I350 W/Bracket
	M2217-L16-IO	411T57700034		OCP Riser Card
CPU Heatsink	FRU-TH-0220	343T62300001		HF-HEATSINK;SBU,AL,SOLDERLING +PIPE, 4189-2U- PASSIVE- HEATSINK, MICROLOOPS, TNM-ML0873-HN5, 113.5X 78.0X64.0MM, SCREW, TS65-B7120
FAN	FRU-TS-9200	422T62700001		TF-FAN ASSY;SBU,FAN, 12V, V80E12BS1NB5-07T095, 2BALL, 4.54A, 54.5W, 15000 RPM, 131.7 CFM, 4.54 inch-H2O, 68.0 dBA, 240g, 80*80*38mm, 6 PIN (HEADER 1*6), WIRE L=170MM, FT83A-B7129
HDD Backplane		411T62700043		M1315F83A-BP12E-10,FT83A-B7129
	FRU-BP-9270	411T60900096		M1297T65-BP12E-12,FT83A-B7129
Riser card		411T62700036		M7129F83A-L16,FT83A-B7129
ME Parts	FRU-SM-9150	340T62700008		FRU OPTION KIT; GPU Card BKT; GPU HDR ASM; for NVIDIA GPU; for FT83A-B7129; RoHS
		340T62700003		REAR TOP COVER,4.5U
Power Supply		471100000518		TF-POWER SUPPLY;SBU,1600 W,CHICONY,R18-1K6P1WA,R1K6AS 02P,(01),1U CRPS MODULE,REV:01
Rack Mounting Kit		452T61000003		TF-SLIDE RAIL KIT;SBU,SGCC+STEEL+SCREW,FT8 3-B7119

Appendix VII: Glossary

ACPI (Advanced Configuration and Power Interface): a power management specification that allows the operating system to control the amount of power distributed to the computer's devices. Devices not in use can be turned off, reducing unnecessary power expenditure.

AGP (Accelerated Graphics Port): a PCI-based interface which was designed specifically for demands of 3D graphics applications. The 32-bit AGP channel directly links the graphics controller to the main memory. While the channel runs only at 66 MHz, it supports data transmission during both the rising and falling ends of the clock cycle, yielding an effective speed of 133 MHz.

ATAPI (AT Attachment Packet Interface): also known as IDE or ATA; a drive implementation that includes the disk controller on the device itself. It allows CD-ROMs and tape drives to be configured as master or slave devices, just like HDDs.

ATX: the form factor designed to replace the AT form factor. It improves on the AT design by rotating the board 90 degrees, so that the IDE connectors are closer to the drive bays, and the CPU is closer to the power supply and cooling fan. The keyboard, mouse, USB, serial, and parallel ports are built-in.

Bandwidth: refers to carrying capacity. The greater the bandwidth, the more data the bus, phone line, or other electrical path can carry. Greater bandwidth results in greater speed.

BBS (BIOS Boot Specification): a feature within the BIOS that creates, prioritizes, and maintains a list of all Initial Program Load (IPL) devices, and then stores that list in NVRAM. IPL devices have the ability to load and execute an OS, as well as provide the ability to return to the BIOS if the OS load process fails. At that point, the next IPL device is called upon to attempt loading of the OS.

BIOS (Basic Input/Output System): the program that resides in the ROM chip, which provides the basic instructions for controlling your computer's hardware. Both the operating system and application software use BIOS routines to ensure compatibility.

Buffer: a portion of RAM which is used to temporarily store data; usually from an application though it is also used when printing and in most keyboard drivers. The CPU can manipulate data in a buffer before copying it to a disk drive. While this

improves system performance (reading to or writing from a disk drive a single time is much faster than doing so repeatedly) there is the possibility of losing your data should the system crash. Information in a buffer is temporarily stored, not permanently saved.

Bus: a data pathway. The term is used especially to refer to the connection between the processor and system memory, and between the processor and PCI or ISA local buses.

Bus mastering: allows peripheral devices and IDEs to access the system memory without going through the CPU (similar to DMA channels).

Cache: a temporary storage area for data that will be needed often by an application. Using a cache lowers data access times since the information is stored in SRAM instead of slower DRAM. Note that the cache is also much smaller than your regular memory: a typical cache size is 512KB, while you may have as much as 4GB of regular memory.

Closed and open jumpers: jumpers and jumper pins are active when they are “on” or “closed”, and inactive when they are “off” or “open”.

CMOS (Complementary Metal-Oxide Semiconductors): chips that hold the basic startup information for the BIOS.

COM port: another name for the serial port, which is called as such because it transmits the eight bits of a byte of data along one wire, and receives data on another single wire (that is, the data is transmitted in serial form, one bit after another). Parallel ports transmit the bits of a byte on eight different wires at the same time (that is, in parallel form, eight bits at the same time).

DDR (Double Data Rate): a technology designed to double the clock speed of the memory. It activates output on both the rising and falling edge of the system clock rather than on just the rising edge, potentially doubling output.

DIMM (Dual In-line Memory Module): faster and more capacious form of RAM than SIMMs, and do not need to be installed in pairs.

DIMM bank: sometimes called DIMM socket because the physical slot and the logical unit are the same. That is, one DIMM module fits into one DIMM socket, which is capable of acting as a memory bank.

DMA (Direct Memory Access): channels that are similar to IRQs. DMA channels allow hardware devices (like soundcards or keyboards) to access the main memory without involving the CPU. This frees up CPU resources for other tasks. As with

IRQs, it is vital that you do not double up devices on a single line. Plug-n-Play devices will take care of this for you.

DRAM (Dynamic RAM): widely available, very affordable form of RAM which loses data if it is not recharged regularly (every few milliseconds). This refresh requirement makes DRAM three to ten times slower than non-recharged RAM such as SRAM.

ECC (Error Correction Code or Error Checking and Correcting): allows data to be checked for errors during run-time. Errors can subsequently be corrected at the same time that they're found.

EEPROM (Electrically Erasable Programmable ROM): also called Flash BIOS, it is a ROM chip which can, unlike normal ROM, be updated. This allows you to keep up with changes in the BIOS programs without having to buy a new chip. TYAN®'s BIOS updates can be found at <http://www.tyan.com>

ESCD (Extended System Configuration Data): a format for storing information about Plug-n-Play devices in the system BIOS. This information helps properly configure the system each time it boots.

Firmware: low-level software that controls the system hardware.

Form factor: an industry term for the size, shape, power supply type, and external connector type of the Personal Computer Board (PCB) or motherboard. The standard form factors are the AT and ATX.

Global timer: onboard hardware timer, such as the Real-Time Clock (RTC).

HDD: stands for Hard Disk Drive, a type of fixed drive.

H-SYNC: controls the horizontal synchronization/properties of the monitor.

HyperTransport™: a high speed, low latency, scalable point-to-point link for interconnecting ICs on boards. It can be significantly faster than a PCI bus for an equivalent number of pins. It provides the bandwidth and flexibility critical for today's networking and computing platforms while retaining the fundamental programming model of PCI.

IC (Integrated Circuit): the formal name for the computer chip.

IDE (Integrated Device/Drive Electronics): a simple, self-contained HDD interface. It can handle drives up to 8.4 GB in size. Almost all IDEs sold now are in fact Enhanced IDEs (EIDEs), with maximum capacity determined by the hardware controller.

IDE INT (IDE Interrupt): Hardware interrupt signal that goes to the IDE.

I/O (Input/Output): the connection between your computer and another piece of hardware (mouse, keyboard, etc.)

IRQ (Interrupt Request): an electronic request that runs from a hardware device to the CPU. The interrupt controller assigns priorities to incoming requests and delivers them to the CPU. It is important that there is only one device hooked up to each IRQ line; doubling up devices on IRQ lines can lock up your system. Plug-n-Play operating systems can take care of these details for you.

Latency: the amount of time that one part of a system spends waiting for another part to catch up. This occurs most commonly when the system sends data out to a peripheral device and has to wait for the peripheral to spread (peripherals tend to be slower than onboard system components).

NVRAM: ROM and EEPROM are both examples of Non-Volatile RAM, memory that holds its data without power. DRAM, in contrast, is volatile.

Parallel port: transmits the bits of a byte on eight different wires at the same time.

PCI (Peripheral Component Interconnect): a 32 or 64-bit local bus (data pathway) which is faster than the ISA bus. Local buses are those which operate within a single system (as opposed to a network bus, which connects multiple systems).

PCI PIO (PCI Programmable Input/Output) modes: the data transfer modes used by IDE drives. These modes use the CPU for data transfer (in contrast, DMA channels do not). PCI refers to the type of bus used by these modes to communicate with the CPU.

PCI-to-PCI Bridge: allows you to connect multiple PCI devices onto one PCI slot.

Pipeline burst SRAM: a fast secondary cache. It is used as a secondary cache because SRAM is slower than SDRAM, but usually larger. Data is cached first to the faster primary cache, and then, when the primary cache is full, to the slower secondary cache.

PnP (Plug-n-Play): a design standard that has become ascendant in the industry. Plug-n-Play devices require little set-up to use. Devices and operating systems that are not Plug-n-Play require you to reconfigure your system each time you add or change any part of your hardware.

PXE (Preboot Execution Environment): one of four components that together make up the Wired for Management 2.0 baseline specification. PXE was

designed to define a standard set of preboot protocol services within a client with the goal of allowing networked-based booting to boot using industry standard protocols.

RAID (Redundant Array of Independent Disks): a way for the same data to be stored in different places on many hard drives. By using this method, the data is stored redundantly and multiple hard drives will appear as a single drive to the operating system. RAID level 0 is known as striping, where data is striped (or overlapped) across multiple hard drives, but offers no fault-tolerance. RAID level 1 is known as mirroring, which stores the data within at least two hard drives, but does not stripe. RAID level 1 also allows for faster access time and fault-tolerance, since either hard drive can be read at the same time. RAID level 0+1 is striping and mirroring, providing fault-tolerance, striping, and faster access all at the same time.

RAIDOS: RAID I/O Steering (Intel)

RAM (Random Access Memory): technically refers to a type of memory where any byte can be accessed without touching the adjacent data and is often referred to as the system's main memory. This memory is available to any program running on the computer.

ROM (Read-Only Memory): a storage chip which contains the BIOS; the basic instructions required to boot the computer and start up the operating system.

SDRAM (Synchronous Dynamic RAM): called as such because it can keep two sets of memory addresses open simultaneously. By transferring data alternately from one set of addresses and then the other, SDRAM cuts down on the delays associated with non-synchronous RAM, which must close one address bank before opening the next.

Serial port: called as such because it transmits the eight bits of a byte of data along one wire, and receives data on another single wire (that is, the data is transmitted in serial form, one bit after another).

SCSI Interrupt Steering Logic (SISL): Architecture that allows a RAID controller, such as AcceleRAID 150, 200 or 250, to implement RAID on a system board-embedded SCSI bus or a set of SCSI busses. SISL: SCSI Interrupt Steering Logic (LSI) (only on LSI SCSI boards)

Sleep/Suspend mode: in this mode, all devices except the CPU shut down.

SDRAM (Static RAM): unlike DRAM, this type of RAM does not need to be refreshed in order to prevent data loss. Thus, it is faster and more expensive.

SLI (Scalable Link Interface): NVIDIA SLI technology links two graphics cards together to provide scalability and increased performance. NVIDIA SLI takes advantage of the increased bandwidth of the PCI Express bus architecture, and features hardware and software innovations within NVIDIA GPUs (graphics processing units) and NVIDIA MCPs (media and communications processors). Depending on the application, NVIDIA SLI can deliver as much as two times the performance of a single GPU configuration.

Standby mode: in this mode, the video and hard drives shut down; all other devices continue to operate normally.

UltraDMA-33/66/100: a fast version of the old DMA channel. UltraDMA is also called UltraATA. Without a proper UltraDMA controller, your system cannot take advantage of higher data transfer rates of the new UltraDMA/UltraATA hard drives.

USB (Universal Serial Bus): a versatile port. This one port type can function as a serial, parallel, mouse, keyboard or joystick port. It is fast enough to support video transfer, and is capable of supporting up to 127 daisy-chained peripheral devices.

VGA (Video Graphics Array): the PC video display standard

V-SYNC: controls the vertical scanning properties of the monitor.

ZCR (Zero Channel RAID): PCI card that allows a RAID card to use the onboard SCSI chip, thus lowering cost of RAID solution

ZIF Socket (Zero Insertion Force socket): these sockets make it possible to insert CPUs without damaging the sensitive CPU pins. The CPU is lightly placed in an open ZIF socket, and a lever is pulled down. This shifts the processor over and down, guiding it into the board and locking it into place.

Appendix VIII: Technical Support

If a problem arises with your system, you should first turn to your dealer for direct support. Your system has most likely been configured or designed by them and they should have the best idea of what hardware and software your system contains. Hence, they should be of the most assistance for you. Furthermore, if you purchased your system from a dealer near you, take the system to them directly to have it serviced instead of attempting to do so yourself (which can have expensive consequences).

If these options are not available for you then TYAN® Computer Corporation can help. Besides designing innovative and quality products for over a decade, TYAN® has continuously offered customers service beyond their expectations. TYAN's website (www.tyan.com) provides easy-to-access resources such as in-depth Linux Online Support sections with downloadable Linux drivers and comprehensive compatibility reports for chassis, memory and much more. With all these convenient resources just a few keystrokes away, users can easily find the latest software and operating system components to keep their systems running as powerful and productive as possible. TYAN® also ranks high for its commitment to fast and friendly customer support through email. By offering plenty of options for users, TYAN® serves multiple market segments with the industry's most competitive services to support them.

"TYAN's tech support is some of the most impressive we've seen, with great response time and exceptional organization in general" - Anandtech.com

You can contact TYAN® Technical Support by using our Online Support System:

<http://12.230.196.231/helpstar/hsPages/login.aspx?ReturnUrl=%2fhelpstar%2fhsPages%2fDefault.aspx>

Help Resources:

1. See the beep codes section of this manual.
2. See the TYAN® website for FAQ's, bulletins, driver updates, and other information: <http://www.tyan.com>
3. Contact your dealer for help BEFORE calling TYAN®.
4. Check the TYAN® user group: alt.comp.periphs.mainboard.TYAN@

Returning Merchandise for Service

During the warranty period, contact your distributor or system vendor FIRST for any product problems. This warranty only covers normal customer use and does not

cover damages incurred during shipping or failure due to the alteration, misuse, abuse, or improper maintenance of products.

NOTE: A receipt or copy of your invoice marked with the date of purchase is required before any warranty service can be rendered. You may obtain service by calling the manufacturer for a Return Merchandise Authorization (RMA) number. The RMA number should be prominently displayed on the outside of the shipping carton and the package should be mailed prepaid. TYAN® will pay to have the board shipped back to you

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